

HP ProLiant ML350 G6 Server Maintenance and Service Guide

Abstract

This guide is for an experienced service technician. HP assumes you are qualified in the servicing of computer equipment and trained in recognizing hazards in products with hazardous energy levels and are familiar with weight and stability precautions for rack installations.



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Customer self repair

HP products are designed with many Customer Self Repair (CSR) parts to minimize repair time and allow for greater flexibility in performing defective parts replacement. If during the diagnosis period HP (or HP service providers or service partners) identifies that the repair can be accomplished by the use of a CSR part, HP will ship that part directly to you for replacement. There are two categories of CSR parts:

- **Mandatory**—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.
- **Optional**—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

NOTE: Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

Based on availability and where geography permits, CSR parts will be shipped for next business day delivery. Same day or four-hour delivery may be offered at an additional charge where geography permits. If assistance is required, you can call the HP Technical Support Center and a technician will help you over the telephone. HP specifies in the materials shipped with a replacement CSR part whether a defective part must be returned to HP. In cases where it is required to return the defective part to HP, you must ship the defective part back to HP within a defined period of time, normally five (5) business days. The defective part must be returned with the associated documentation in the provided shipping material. Failure to return the defective part may result in HP billing you for the replacement. With a customer self repair, HP will pay all shipping and part return costs and determine the courier/carrier to be used.

For more information about HP's Customer Self Repair program, contact your local service provider. For the North American program, refer to the HP website (<http://www.hp.com/go/selfrepair>).

Parts only warranty service

Your HP Limited Warranty may include a parts only warranty service. Under the terms of parts only warranty service, HP will provide replacement parts free of charge.

For parts only warranty service, CSR part replacement is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

Réparation par le client (CSR)

Les produits HP comportent de nombreuses pièces CSR (Customer Self Repair = réparation par le client) afin de minimiser les délais de réparation et faciliter le remplacement des pièces défectueuses. Si pendant la période de diagnostic, HP (ou ses partenaires ou mainteneurs agréés) détermine que la réparation peut être effectuée à l'aide d'une pièce CSR, HP vous l'envoie directement. Il existe deux catégories de pièces CSR:

Obligatoire - Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

Facultatif - Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

REMARQUE: Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

Les pièces CSR sont livrées le jour ouvré suivant, dans la limite des stocks disponibles et selon votre situation géographique. Si votre situation géographique le permet et que vous demandez une livraison le jour même ou dans les 4 heures, celle-ci vous sera facturée. Pour bénéficier d'une assistance téléphonique, appelez le Centre d'assistance technique HP. Dans les documents envoyés avec la pièce de rechange CSR, HP précise s'il est nécessaire de lui retourner la pièce défectueuse. Si c'est le cas, vous devez le faire dans le délai indiqué, généralement cinq (5) jours ouvrés. La pièce et sa documentation doivent être retournées dans l'emballage fourni. Si vous ne retournez pas la pièce défectueuse, HP se réserve le droit de vous facturer les coûts de remplacement. Dans le cas d'une pièce CSR, HP supporte l'ensemble des frais d'expédition et de retour, et détermine la société de courses ou le transporteur à utiliser.

Pour plus d'informations sur le programme CSR de HP, contactez votre Mainteneur Agréé local. Pour plus d'informations sur ce programme en Amérique du Nord, consultez le site Web HP (<http://www.hp.com/go/selfrepair>).

Service de garantie "pièces seules"

Votre garantie limitée HP peut inclure un service de garantie "pièces seules". Dans ce cas, les pièces de rechange fournies par HP ne sont pas facturées.

Dans le cadre de ce service, la réparation des pièces CSR par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

Riparazione da parte del cliente

Per abbreviare i tempi di riparazione e garantire una maggiore flessibilità nella sostituzione di parti difettose, i prodotti HP sono realizzati con numerosi componenti che possono essere riparati direttamente dal cliente (CSR, Customer Self Repair). Se in fase di diagnostica HP (o un centro di servizi o di assistenza HP) identifica il guasto come riparabile mediante un ricambio CSR, HP lo spedisce direttamente al cliente per la sostituzione. Vi sono due categorie di parti CSR:

Obbligatorie – Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

Opzionali – Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese aggiuntive a seconda del tipo di garanzia previsto per il prodotto.

NOTA: alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

In base alla disponibilità e alla località geografica, le parti CSR vengono spedite con consegna entro il giorno lavorativo seguente. La consegna nel giorno stesso o entro quattro ore è offerta con un supplemento di costo solo in alcune zone. In caso di necessità si può richiedere l'assistenza telefonica di un addetto del centro di supporto tecnico HP. Nel materiale fornito con una parte di ricambio CSR, HP specifica se il cliente deve restituire dei componenti. Qualora sia richiesta la resa ad HP del componente difettoso, lo si deve spedire ad HP entro un determinato periodo di tempo, generalmente cinque (5) giorni lavorativi. Il componente difettoso deve essere restituito con la documentazione associata nell'imballo di spedizione fornito. La mancata restituzione del componente può comportare la fatturazione del ricambio da parte di HP. Nel caso di riparazione da parte del cliente, HP sostiene tutte le spese di spedizione e resa e sceglie il corriere/vettore da utilizzare.

Per ulteriori informazioni sul programma CSR di HP contattare il centro di assistenza di zona. Per il programma in Nord America fare riferimento al sito Web HP (<http://www.hp.com/go/selfrepair>).

Servizio di garanzia per i soli componenti

La garanzia limitata HP può includere un servizio di garanzia per i soli componenti. Nei termini di garanzia del servizio per i soli componenti, HP fornirà gratuitamente le parti di ricambio.

Per il servizio di garanzia per i soli componenti è obbligatoria la formula CSR che prevede la riparazione da parte del cliente. Se il cliente invece richiede la sostituzione ad HP, dovrà sostenere le spese di spedizione e di manodopera per il servizio.

Customer Self Repair

HP Produkte enthalten viele CSR-Teile (Customer Self Repair), um Reparaturzeiten zu minimieren und höhere Flexibilität beim Austausch defekter Bauteile zu ermöglichen. Wenn HP (oder ein HP Servicepartner) bei der Diagnose feststellt, dass das Produkt mithilfe eines CSR-Teils repariert werden kann, sendet Ihnen HP dieses Bauteil zum Austausch direkt zu. CSR-Teile werden in zwei Kategorien unterteilt:

Zwingend – Teile, für die das Customer Self Repair-Verfahren zwingend vorgegeben ist. Wenn Sie den Austausch dieser Teile von HP vornehmen lassen, werden Ihnen die Anfahrt- und Arbeitskosten für diesen Service berechnet.

Optional – Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

HINWEIS: Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

CSR-Teile werden abhängig von der Verfügbarkeit und vom Lieferziel am folgenden Geschäftstag geliefert. Für bestimmte Standorte ist eine Lieferung am selben Tag oder innerhalb von vier Stunden gegen einen Aufpreis verfügbar. Wenn Sie Hilfe benötigen, können Sie das HP technische Support Center anrufen und sich von einem Mitarbeiter per Telefon helfen lassen. Den Materialien, die mit einem CSR-Ersatzteil geliefert werden, können Sie entnehmen, ob das defekte Teil an HP zurückgeschickt werden muss. Wenn es erforderlich ist, das defekte Teil an HP zurückzuschicken, müssen Sie dies innerhalb eines vorgegebenen Zeitraums tun, in der Regel innerhalb von fünf (5) Geschäftstagen. Das defekte Teil muss mit der zugehörigen Dokumentation in der Verpackung zurückgeschickt werden, die im Lieferumfang enthalten ist. Wenn Sie das

defekte Teil nicht zurückschicken, kann HP Ihnen das Ersatzteil in Rechnung stellen. Im Falle von Customer Self Repair kommt HP für alle Kosten für die Lieferung und Rücksendung auf und bestimmt den Kurier-/Frachtdienst.

Weitere Informationen über das HP Customer Self Repair Programm erhalten Sie von Ihrem Servicepartner vor Ort. Informationen über das CSR-Programm in Nordamerika finden Sie auf der HP Website unter (<http://www.hp.com/go/selfrepair>).

Parts-only Warranty Service (Garantieservice ausschließlich für Teile)

Ihre HP Garantie umfasst möglicherweise einen Parts-only Warranty Service (Garantieservice ausschließlich für Teile). Gemäß den Bestimmungen des Parts-only Warranty Service stellt HP Ersatzteile kostenlos zur Verfügung.

Für den Parts-only Warranty Service ist das CSR-Verfahren zwingend vorgegeben. Wenn Sie den Austausch dieser Teile von HP vornehmen lassen, werden Ihnen die Anfahrt- und Arbeitskosten für diesen Service berechnet.

Reparaciones del propio cliente

Los productos de HP incluyen muchos componentes que el propio usuario puede reemplazar (*Customer Self Repair*, CSR) para minimizar el tiempo de reparación y ofrecer una mayor flexibilidad a la hora de realizar sustituciones de componentes defectuosos. Si, durante la fase de diagnóstico, HP (o los proveedores o socios de servicio de HP) identifica que una reparación puede llevarse a cabo mediante el uso de un componente CSR, HP le enviará dicho componente directamente para que realice su sustitución. Los componentes CSR se clasifican en dos categorías:

- **Obligatorio:** componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.
- **Opcional:** componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

NOTA: Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

Según la disponibilidad y la situación geográfica, los componentes CSR se enviarán para que lleguen a su destino al siguiente día laborable. Si la situación geográfica lo permite, se puede solicitar la entrega en el mismo día o en cuatro horas con un coste adicional. Si precisa asistencia técnica, puede llamar al Centro de asistencia técnica de HP y recibirá ayuda telefónica por parte de un técnico. Con el envío de materiales para la sustitución de componentes CSR, HP especificará si los componentes defectuosos deberán devolverse a HP. En aquellos casos en los que sea necesario devolver algún componente a HP, deberá hacerlo en el periodo de tiempo especificado, normalmente cinco días laborables. Los componentes defectuosos deberán devolverse con toda la documentación relacionada y con el embalaje de envío. Si no

enviara el componente defectuoso requerido, HP podrá cobrarle por el de sustitución. En el caso de todas sustituciones que lleve a cabo el cliente, HP se hará cargo de todos los gastos de envío y devolución de componentes y escogerá la empresa de transporte que se utilice para dicho servicio.

Para obtener más información acerca del programa de Reparaciones del propio cliente de HP, póngase en contacto con su proveedor de servicios local. Si está interesado en el programa para Norteamérica, visite la página web de HP siguiente (<http://www.hp.com/go/selfrepair>).

Servicio de garantía exclusivo de componentes

La garantía limitada de HP puede que incluya un servicio de garantía exclusivo de componentes. Según las condiciones de este servicio exclusivo de componentes, HP le facilitará los componentes de repuesto sin cargo adicional alguno.

Para este servicio de garantía exclusivo de componentes, es obligatoria la sustitución de componentes por parte del usuario (CSR). Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

Customer Self Repair

Veel onderdelen in HP producten zijn door de klant zelf te repareren, waardoor de reparatieduur tot een minimum beperkt kan blijven en de flexibiliteit in het vervangen van defecte onderdelen groter is. Deze onderdelen worden CSR-onderdelen (Customer Self Repair) genoemd. Als HP (of een HP Service Partner) bij de diagnose vaststelt dat de reparatie kan worden uitgevoerd met een CSR-onderdeel, verzendt HP dat onderdeel rechtstreeks naar u, zodat u het defecte onderdeel daarmee kunt vervangen. Er zijn twee categorieën CSR-onderdelen:

Verplicht: Onderdelen waarvoor reparatie door de klant verplicht is. Als u HP verzoekt deze onderdelen voor u te vervangen, worden u voor deze service reiskosten en arbeidsloon in rekening gebracht.

Optioneel: Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garantieservice voor het product.

OPMERKING: Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievoorwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

Afhankelijk van de leverbaarheid en de locatie worden CSR-onderdelen verzonden voor levering op de eerstvolgende werkdag. Levering op dezelfde dag of binnen vier uur kan tegen meerkosten worden aangeboden, indien dit mogelijk is gezien de locatie. Indien assistentie gewenst is, belt u een HP Service Partner om via de telefoon technische ondersteuning te ontvangen. HP vermeldt in de documentatie bij het vervangende CSR-onderdeel of het defecte onderdeel aan HP moet worden geretourneerd. Als het defecte onderdeel aan HP moet worden teruggezonden, moet u het defecte onderdeel binnen een bepaalde periode, gewoonlijk vijf (5) werkdagen, retourneren aan HP. Het defecte onderdeel moet met de bijbehorende documentatie worden geretourneerd in het meegeleverde verpakkingsmateriaal. Als u het defecte onderdeel niet terugzendt, kan HP u voor het vervangende onderdeel kosten in rekening brengen. Bij reparatie door de klant betaalt HP alle verzendkosten voor het vervangende en geretourneerde onderdeel en kiest HP zelf welke koerier/transportonderneming hiervoor wordt gebruikt.

Neem contact op met een Service Partner voor meer informatie over het Customer Self Repair programma van HP. Informatie over Service Partners vindt u op de HP website (<http://www.hp.com/go/selfrepair>).

Garantieservice "Parts Only"

Het is mogelijk dat de HP garantie alleen de garantieservice "Parts Only" omvat. Volgens de bepalingen van de Parts Only garantieservice zal HP kosteloos vervangende onderdelen ter beschikking stellen.

Voor de Parts Only garantieservice is vervanging door CSR-onderdelen verplicht. Als u HP verzoekt deze onderdelen voor u te vervangen, worden u voor deze service reiskosten en arbeidsloon in rekening gebracht.

Reparo feito pelo cliente

Os produtos da HP são projetados com muitas peças para reparo feito pelo cliente (CSR) de modo a minimizar o tempo de reparo e permitir maior flexibilidade na substituição de peças com defeito. Se, durante o período de diagnóstico, a HP (ou fornecedores/parceiros de serviço da HP) concluir que o reparo pode ser efetuado pelo uso de uma peça CSR, a peça de reposição será enviada diretamente ao cliente. Existem duas categorias de peças CSR:

Obrigatória – Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

Opcional – Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

OBSERVAÇÃO: Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca "No" (Não), no catálogo de peças ilustrado.

Conforme a disponibilidade e o local geográfico, as peças CSR serão enviadas no primeiro dia útil após o pedido. Onde as condições geográficas permitirem, a entrega no mesmo dia ou em quatro horas pode ser feita mediante uma taxa adicional. Se precisar de auxílio, entre em contato com o Centro de suporte técnico da HP para que um técnico o ajude por telefone. A HP especifica nos materiais fornecidos com a peça CSR de reposição se a peça com defeito deve ser devolvida à HP. Nos casos em que isso for necessário, é preciso enviar a peça com defeito à HP dentro do período determinado, normalmente cinco (5) dias úteis. A peça com defeito deve ser enviada com a documentação correspondente no material de transporte fornecido. Caso não o faça, a HP poderá cobrar a reposição. Para as peças de reparo feito pelo cliente, a HP paga todas as despesas de transporte e de devolução da peça e determina a transportadora/serviço postal a ser utilizado.

Para obter mais informações sobre o programa de reparo feito pelo cliente da HP, entre em contato com o fornecedor de serviços local. Para o programa norte-americano, visite o site da HP (<http://www.hp.com/go/selfrepair>).

Serviço de garantia apenas para peças

A garantia limitada da HP pode incluir um serviço de garantia apenas para peças. Segundo os termos do serviço de garantia apenas para peças, a HP fornece as peças de reposição sem cobrar nenhuma taxa.

No caso desse serviço, a substituição de peças CSR é obrigatória. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

顧客自己修理保証サービス

修理時間を短縮し、故障部品の交換における高い柔軟性を確保するために、HP製品には多数の顧客自己修理（CSR）部品があります。診断の際に、CSR部品を使用すれば修理ができるとHP（HPまたはHP正規保守代理店）が判断した場合、HPはその部品を直接、お客様に発送し、お客様に交換していただきます。CSR部品には以下の2通りがあります。

- 必須 - 顧客自己修理が必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。
- 任意 - 顧客自己修理が任意である部品。この部品も顧客自己修理用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、別途費用を負担していただくことなく保証サービスを受けることができます。

注：HP製品の一部の部品は、顧客自己修理用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品が顧客自己修理除外品である旨が記載されています。

部品供給が可能な場合、地域によっては、CSR部品を翌営業日に届くように発送します。また、地域によっては、追加費用を負担いただくことにより同日または4時間以内に届くように発送することも可能な場合があります。サポートが必要なときは、HPの修理受付窓口にご電話いただければ、技術者が電話でアドバイスします。交換用のCSR部品または同梱物には、故障部品をHPに返送する必要があるかどうかが表示されています。故障部品をHPに返送する必要がある場合は、指定期限内（通常は5営業日以内）に故障部品をHPに返送してください。故障部品を返送する場合は、届いた時の梱包箱に関連書類とともに入れてください。故障部品を返送しない場合、HPから部品費用が請求されます。顧客自己修理の際には、HPは送料および部品返送費を全額負担し、使用する宅配便会社や運送会社を指定します。

部品のみ保証サービス

HP保証サービスには、部品のみ保証サービスが適用される場合があります。このサービスでは、交換部品は無償で提供されます。

部品のみ保証サービスにおいては、CSR部品をお客様により交換作業していただくことが必須となります。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費はお客様の負担となります。

客户自行维修

HP 产品提供许多客户自行维修 (CSR) 部件，以尽可能缩短维修时间和在更换缺陷部件方面提供更大的灵活性。如果在诊断期间 HP（或 HP 服务提供商或服务合作伙伴）确定可以通过使用 CSR 部件完成维修，HP 将直接把该部件发送给您进行更换。有两类 CSR 部件：

- **强制性的** — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。
- **可选的** — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据为您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

注：某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

CSR 部件将在下一个工作日发运（取决于备货情况和允许的地理范围）。在允许的地理范围内，可在当天或四小时内发运，但要收取额外费用。如果需要帮助，您可以致电 HP 技术支持中心，将会有技术人员通过电话为您提供帮助。HP 会在随更换的 CSR 部件发运的材料中指明是否必须将有缺陷的部件返还给 HP。如果要求您将有缺陷的部件返还给 HP，那么您必须在规定期限内（通常是五 (5) 个工作日）将缺陷部件发给 HP。有缺陷的部件必须随所提供的发运材料中的相关文件一起返还。如果未能送还有缺陷的部件，HP 可能会要求您支付更换费用。客户自行维修时，HP 将承担所有相关运输和部件返回费用，并指定快递商/承运商。

有关 HP 客户自行维修计划的详细信息，请与您当地的服务提供商联系。有关北美地区的计划，请访问 HP 网站 (<http://www.hp.com/go/selfrepair>)。

仅部件保修服务

您的 HP 有限保修服务可能涉及仅部件保修服务。根据仅部件保修服务条款的规定，HP 将免费提供更换的部件。

仅部件保修服务要求进行 CSR 部件更换。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

客戶自行維修

HP 產品設計了許多「客戶自行維修」(CSR) 的零件以減少維修時間，並且使得更換瑕疵零件時能有更大的彈性。如果在診斷期間 HP (或 HP 服務供應商或維修夥伴) 辨認出此項維修工作可以藉由使用 CSR 零件來完成，則 HP 將直接寄送該零件給您作更換。CSR 零件分為兩種類別：

- **強制的** — 客戶自行維修所使用的零件是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。
- **選購的** — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

備註：某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

基於材料取得及環境允許的情況下，CSR 零件將於下一個工作日以快遞寄送。在環境的允許下當天或四小時內送達，則可能需要額外的費用。若您需要協助，可致電「HP 技術支援中心」，會有一位技術人員透過電話來協助您。不論損壞的零件是否必須退回，HP 皆會在與 CSR 替換零件一起運送的材料中註明。若要將損壞的零件退回 HP，您必須在指定的一段時間內（通常為五 (5) 個工作天），將損壞的零件寄回 HP。損壞的零件必須與寄送資料中隨附的相關技術文件一併退還。如果無法退還損壞的零件，HP 可能要向您收取替換費用。針對客戶自行維修情形，HP 將負責所有運費及零件退還費用並指定使用何家快遞/貨運公司。

如需 HP 的「客戶自行維修」方案詳細資訊，請連絡您當地的服務供應商。至於北美方案，請參閱 HP 網站 (<http://www.hp.com/go/selfrepair>)。

僅限零件的保固服務

您的「HP 有限保固」可能包含僅限零件的保固服務。在僅限零件的保固服務情況下，HP 將免費提供替換零件。

針對僅限零件的保固服務，CSR 零件替換是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

고객 셀프 수리

HP 제품은 수리 시간을 최소화하고 결함이 있는 부품 교체 시 더욱 융통성을 발휘할 수 있도록 하기 위해 고객 셀프 수리(CSR) 부품을 다량 사용하여 설계되었습니다. 진단 기간 동안 HP(또는 HP 서비스 공급업체 또는 서비스 협력업체)에서 CSR 부품을 사용하여 수리가 가능하다고 판단되면 HP는 해당 부품을 바로 사용자에게 보내어 사용자가 교체할 수 있도록 합니다. CSR 부품에는 두 가지 종류가 있습니다.

- **고객 셀프 수리가 의무 사항인 필수 부품.** 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.
- **고객 셀프 수리가 선택 사항인 부품.** 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

참고: 일부 HP 부품은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 만족스러운 고객 보증을 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다. 이러한 부품들은 Illustrated Parts Catalog에 "No"라고 표시되어 있습니다.

CSR 부품은 재고 상태와 지리적 조건이 허용하는 경우 다음 영업일 납품이 가능하도록 배송이 이루어집니다. 지리적 조건이 허용하는 경우 추가 비용이 청구되는 조건으로 당일 또는 4시간 배송이 가능할 수도 있습니다. 도움이 필요하시면 HP 기술 지원 센터로 전화하십시오. 전문 기술자가 전화로 도움을 줄 것입니다. HP는 결함이 발생한 부품을 HP로 반환해야 하는지 여부를 CSR 교체 부품과 함께 배송된 자료에 지정합니다. 결함이 발생한 부품을 HP로 반환해야 하는 경우에는 지정된 기간 내(통상 영업일 기준 5일)에 HP로 반환해야 합니다. 이 때 결함이 발생한 부품은 제공된 포장 재료에 넣어 관련 설명서와 함께 반환해야 합니다. 결함이 발생한 부품을 반환하지 않는 경우 HP가 교체 부품에 대해 비용을 청구할 수 있습니다. 고객 셀프 수리의 경우, HP는 모든 운송 및 부품 반환 비용을 부담하며 이용할 운송업체 및 택배 서비스를 결정합니다.

HP 고객 셀프 수리 프로그램에 대한 자세한 내용은 가까운 서비스 제공업체에 문의하십시오. 북미 지역의 프로그램에 대해서는 HP 웹 사이트(<http://www.hp.com/go/selfrepair>)를 참조하십시오.

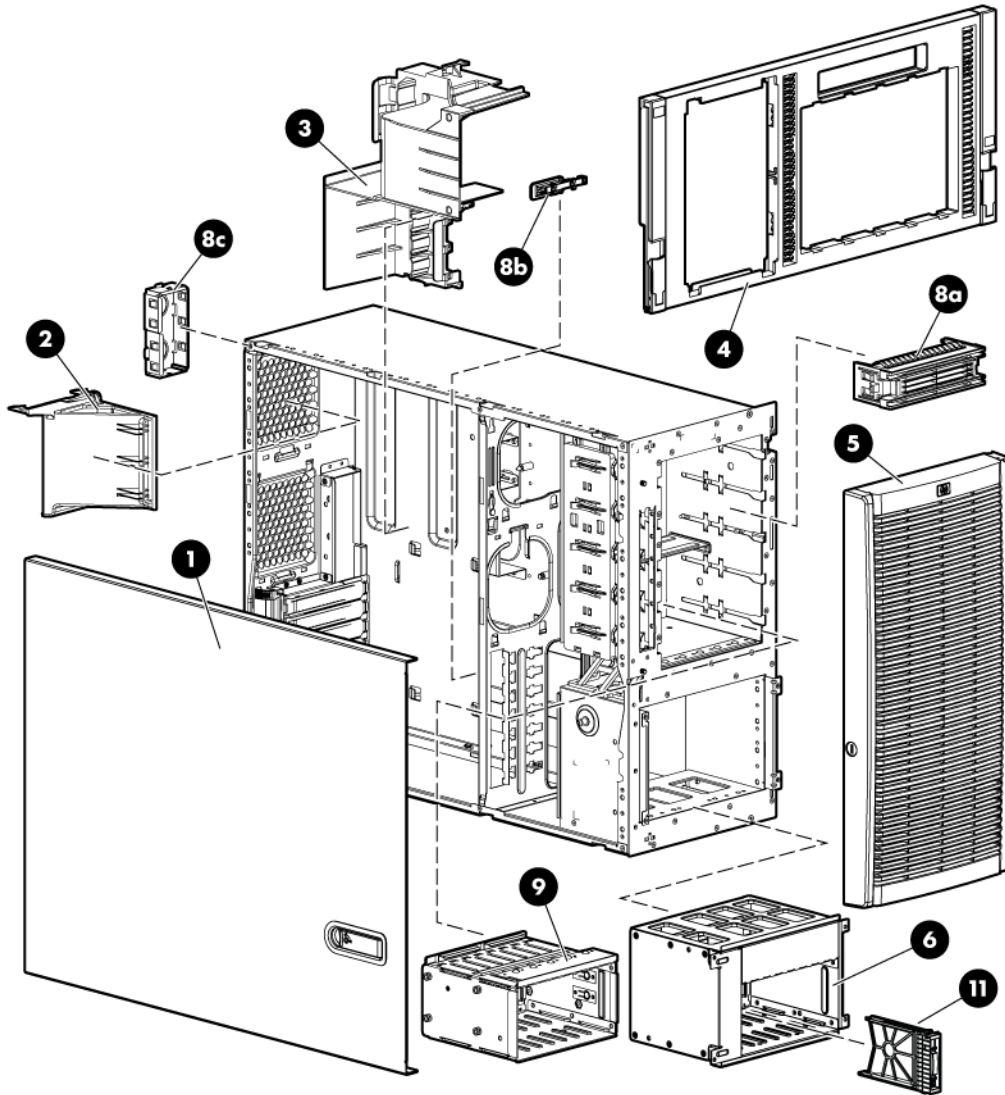
부품 제공 보증 서비스

HP 제한 보증에는 부품 제공 보증 서비스가 포함될 수 있습니다. 이러한 경우 HP는 부품 제공 보증 서비스의 조건에 따라 교체 부품만을 무료로 제공합니다.

부품 제공 보증 서비스 제공 시 CSR 부품 교체는 의무 사항입니다. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

Illustrated parts catalog

Mechanical components



Item	Description	Spare part number	Customer self repair (on page 5)
1	Access panel	511769-001	Mandatory ¹
2	DIMM baffle	511773-001	Mandatory ¹
3	Large redundant fan air baffle	511772-001	Mandatory ¹
4	Front bezel, rack model	511771-001	Mandatory ¹
5	Front bezel, tower model	511770-001	Mandatory ¹

Item	Description	Spare part number	Customer self repair (on page 5)
6	Standard SAS/SATA 8-bay hard drive cage, SFF	511782-001	Mandatory ¹
7	Standard SAS/SATA 6-bay hard drive cage, LFF*	511784-001	Mandatory ¹
8	Plastics and hardware kit	511788-001	Mandatory ¹
	a) Removable media blank	—	—
	b) Retainer card guide	—	—
	c) Power supply blank	—	—
	d) Foot, carbonite*	—	—
9	Optional SAS/SATA 8-bay hard drive expansion cage, SFF (Option kit 507803-B21)	N/A	—
10	Optional SAS/SATA 2-bay hard drive expansion cage, LFF* (Option kit 487936-B21)	N/A	—
11	Hard drive blank, SFF	392613-001	Mandatory ¹
12	Hard drive blank, LFF*	389015-001	Mandatory ¹

*Not shown

¹Mandatory—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

²Optional—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

³No—Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

¹Mandatory: Obligatoire—Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

²Optional: Facultatif—Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

³No: Non—Certains pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

¹Mandatory: Obbligatorie—Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

²Optional: Opzionali—Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese addizionali a seconda del tipo di garanzia previsto per il prodotto.

³No: Non CSR—Alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

¹Mandatory: Zwingend—Teile, die im Rahmen des Customer Self Repair Programms ersetzt werden müssen. Wenn Sie diese Teile von HP ersetzen lassen, werden Ihnen die Versand- und Arbeitskosten für diesen Service berechnet.

²Optional: Optional—Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

³No: Kein—Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

¹Mandatory: Obligatorio—componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

²Optional: Opcional— componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

³No: No—Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

¹Mandatory: Verplicht—Onderdelen waarvoor Customer Self Repair verplicht is. Als u HP verzoekt deze onderdelen te vervangen, komen de reiskosten en het arbeidsloon voor uw rekening.

²Optional: Optioneel—Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garanteservice voor het product.

³No: Nee—Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantiev voorwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

¹Mandatory: Obrigatória—Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

²Optional: Opcional—Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

³No: Nenhuma—Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca "No" (Não), no catálogo de peças ilustrado.

¹Mandatory : 必須 - 顧客自己修理が必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。

²Optional : 任意 - 顧客自己修理が任意である部品。この部品も顧客自己修理用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、費用を負担していただくことなく保証サービスを受けることができます。

³No : 除外 - HP製品の一部の部品は、顧客自己修理用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品が顧客自己修理除外品である旨が記載されています。

¹Mandatory: 强制性的 — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

²Optional: 可选的 — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

³No: 否 — 某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

¹Mandatory: 強制的 — 客戶自行維修所使用的零件是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

²Optional: 選購的 — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

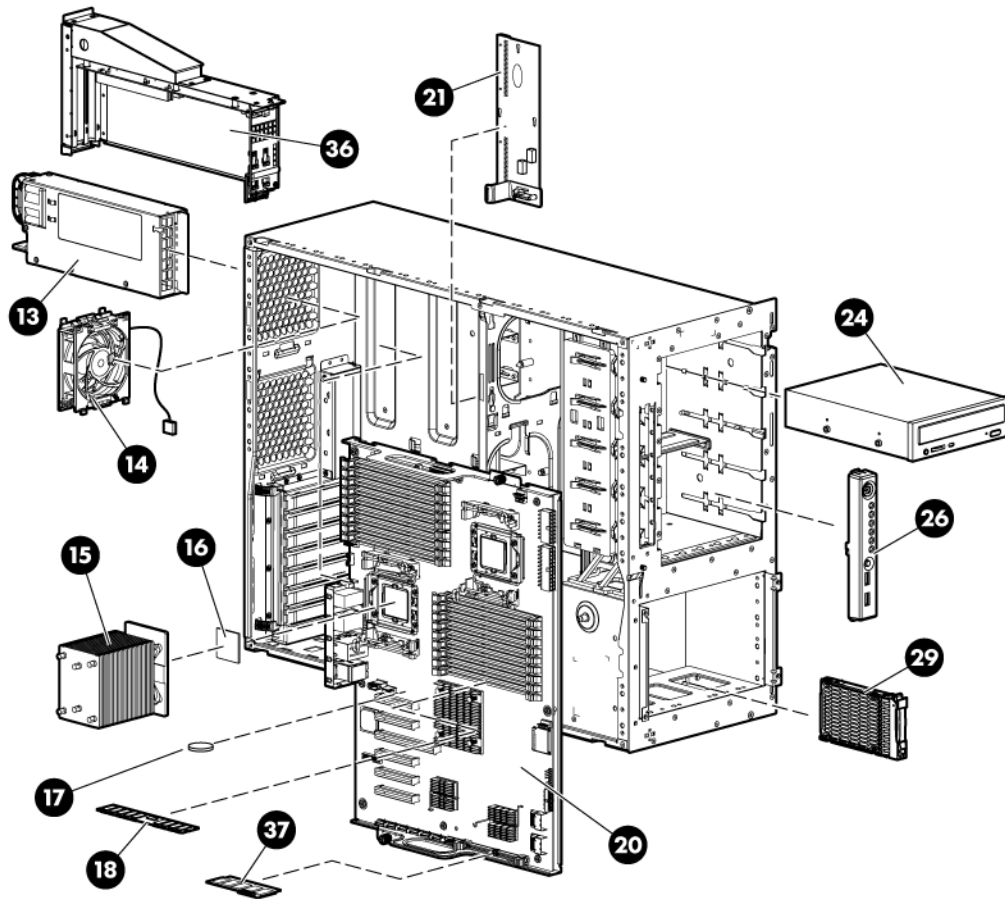
³No: 否 — 某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

¹ Mandatory: 필수 — 고객 셀프 수리가 의무 사항인 필수 부품. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

² Optional: 옵션 — 고객 셀프 수리가 선택 사항인 부품. 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

³ No: No — 고객 셀프 수리가 불가능하도록 설계된 HP 부품. 이 부품들은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 고객 보증을 만족시키기 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다.

System components



Item	Description	Spare part number	Customer self repair (on page 5)
System components			
13	Hot-plug power supply	—	—
	a) AC, 460 W	511777-001	Mandatory ¹
	b) AC, 750 W	511778-001	Mandatory ¹
	c) AC, 1200 W	498152-001	Mandatory ¹
14	Fan assembly, 92 mm	511774-001	Mandatory ¹
15	Heatsink	508876-001	Optional ²
16	Processor with thermal grease and alcohol pad	—	—
	a) 2.26-GHz Intel® Xeon® processor L5520, 60 W**	504584-001	Optional ²
	b) 2.13-GHz Intel® Xeon® processor L5506, 60 W* **	513597-001	Optional ²
	c) 1.86-GHz Intel® Xeon® processor E5502, 80 W* **	490075-001	Optional ²
	d) 2.00-GHz Intel® Xeon® processor E5504, 80 W* **	490074-001	Optional ²
	e) 2.13-GHz Intel® Xeon® processor E5506, 80 W* **	506013-001	Optional ²

Item	Description	Spare part number	Customer self repair (on page 5)
	f) 2.26-GHz Intel® Xeon® processor E5520, 80 W* **	490073-001	Optional ²
	g) 2.40-GHz Intel® Xeon® processor E5530, 80 W* **	490072-001	Optional ²
	h) 2.53-GHz Intel® Xeon® processor E5540, 80 W* **	490071-001	Optional ²
	i) 2.66-GHz Intel® Xeon® processor X5550, 95 W* **	490070-001	Optional ²
	j) 2.80-GHz Intel® Xeon® processor X5560, 95 W* **	490069-001	Optional ²
	k) 2.93-GHz Intel® Xeon® processor X5570, 95 W* **	506012-001	Optional ²
	l) 3.20-GHz Intel® Xeon® processor X5672, 95 W* **	638135-001	Optional ²
	m) 3.06-GHz Intel® Xeon® processor X5675, 95 W* **	638134-001	Optional ²
	n) 1.60-GHz Intel® Xeon® processor E5603, 80 W* **	628700-001	Optional ²
	o) 2.13-GHz Intel® Xeon® processor E5606, 80 W* **	628699-001	Optional ²
	p) 2.26-GHz Intel® Xeon® processor E5607, 80 W* **	628698-001	Optional ²
	q) 2.40-GHz Intel® Xeon® processor E5645, 80 W* **	628696-001	Optional ²
	r) 2.53-GHz Intel® Xeon® processor E5649, 80 W* **	628695-001	Optional ²
	s) 2.66-GHz Intel® Xeon® processor E5640, 80 W* **	594885-001	Optional ²
	t) 2.53-GHz Intel® Xeon® processor E5630, 80 W* **	594886-001	Optional ²
	u) 2.40-GHz Intel® Xeon® processor E5620, 80 W* **	594887-001	Optional ²
	v) 2.26-GHz Intel® Xeon® processor E5507, 80 W* **	594888-001	Optional ²
	w) 2.13-GHz Intel® Xeon® processor L5630, 40 W* **	594891-001	Optional ²
	x) 2.00-GHz Intel® Xeon® processor E5503, 80 W* **	594889-001	Optional ²
	y) 2.66-GHz Intel® Xeon® processor X5650, 95 W* **	594884-001	Optional ²
	z) 2.8-GHz Intel® Xeon® processor X5660, 95 W* **	594883-001	Optional ²
	aa) 2.93-GHz Intel® Xeon® processor X5670, 95 W* **	594882-001	Optional ²
17	3-V lithium battery	234556-001	Mandatory ¹
	Memory		
18	RDIMM	—	—
	a) 2-GB PC3-10600 (DDR3-1333) (RoHS)	501533-001	Mandatory ¹
	b) 4-GB PC3-10600 (DDR3-1333) (RoHS)*	501534-001	Mandatory ¹
	c) 4-GB PC3-8500 (DDR3-1066) (RoHS)*	595424-001	Mandatory ¹
	d) 8-GB PC3-10600 (DDR3-1066) (RoHS)*	501536-001	Mandatory ¹
	e) 16-GB PC3-8500 (DDR3-1066) (RoHS)	501538-001	Mandatory ¹
	f) PC3L-8500 (DDR3-1333) 4-GB (low voltage)* ***	595422-001	Mandatory ¹
	g) PC3L-8500 (DDR3-1333) 8-GB (low voltage)* ***	595423-001	Mandatory ¹
	h) 16-GB 2RX4 PC3L-10600R-9	632204-001	Mandatory ¹
19	UDIMM	—	—

Item	Description	Spare part number	Customer self repair (on page 5)
	a) 1-GB PC3-10600 (DDR3-1333) (RoHS)*	501539-001	Mandatory ¹
	b) 2-GB PC3-10600 (DDR3-1333) (RoHS)*	501540-001	Mandatory ¹
	c) 4-GB PC3-10600 (DDR3-1333) (RoHS)*	501541-001	Mandatory ¹
	Boards		
20	System board	—	—
	a) For systems using Intel 5500 series processors	511775-001	Optional ²
	b) For systems using Intel 5500 and 5600 series processors*	606019-001	Optional ²
21	Power supply backplane	511776-001	Optional ²
22	SAS/SATA 8-bay hard drive cage backplane board assembly, SFF*	511785-001	Optional ²
23	SAS/SATA 6-bay hard drive cage backplane board assembly, LFF*	511787-001	Optional ²
	Optical drives		
24	SATA DVD-ROM drive, 48x	397931-001	Mandatory ¹
25	SATA DVD-RW drive, 48x*	399404-001	Mandatory ¹
	Miscellaneous		
26	Power switch board with cable	511781-001	Optional ²
27	DVD-ROM drive signal cable*	413987-001	Mandatory ¹
28	AC power cord, 1.83 m (6 ft)*	142258-001	Mandatory ¹
	Options		
29	LFF SATA hard drive	—	—
	a) 80-GB, 7200-rpm, hot-plug	397551-001	Mandatory ¹
	b) 160-GB, 7200-rpm, hot-plug*	397552-001	Mandatory ¹
	c) 160-GB, 7200-rpm, hot-plug, NCQ*	483095-001	Mandatory ¹
	d) 250-GB, 7200-rpm, hot-plug*	397553-001	Mandatory ¹
	e) 250-GB, 7200-rpm, hot-plug, NCQ*	459318-001	Mandatory ¹
	f) 500-GB, 7200-rpm, hot-plug*	395501-001	Mandatory ¹
	g) 500-GB, 7200-rpm, hot-plug*	495319-001	Mandatory ¹
	h) 750-GB, 7200-rpm, hot-plug, NCQ*	432401-001	Mandatory ¹
	i) 750-GB, 7200-rpm, hot-plug, 3G, NCQ*	459320-001	Mandatory ¹
	j) 1-TB, 7200-rpm, hot-plug, 3G, NCQ*	454273-001	Mandatory ¹
	k) 2-TB, 7200-rpm, hot-plug, 3G, NCQ*	508040-001	Mandatory ¹
30	LFF SAS hard drive*	—	—
	a) 72-GB, 15,000-rpm, hot-plug	376594-001	Mandatory ¹
	b) 72-GB, 15,000-rpm, hot-plug, dual-port	389343-001	Mandatory ¹
	c) 146-GB, 15,000-rpm, hot-plug	376595-001	Mandatory ¹
	d) 146-GB, 15,000-rpm, hot-plug, dual-port	389344-001	Mandatory ¹

Item	Description	Spare part number	Customer self repair (on page 5)
	e) 300-GB, 15,000-rpm, hot-plug, dual-port	416248-001	Mandatory ¹
	f) 300-GB, 15,000-rpm, hot-plug, dual-port	432146-001	Mandatory ¹
	g) 400-GB, 10,000-rpm, hot-plug	456896-001	Mandatory ¹
	h) 450-GB, 15,000-rpm, hot-plug, dual-port	454274-001	Mandatory ¹
	i) 750-GB, 15,000-rpm, hot-plug	461288-001	Mandatory ¹
	j) 1-TB, 15,000-rpm, hot-plug	461289-001	Mandatory ¹
	k) 1-TB, 7200-rpm, hot-plug	508011-001	Mandatory ¹
	l) 2-TB, 7200-rpm, hot-plug	508010-001	Mandatory ¹
	m) 300-GB, 6G/s	586875-001	Mandatory ¹
	n) 450-GB, 6G/s	586876-001	Mandatory ¹
	o) 600-GB, 6G/s	586877-001	Mandatory ¹
	p) 1-TB, 6G/s	601884-001	Mandatory ¹
	q) 2-TB, 6G/s	601883-001	Mandatory ¹
31	SFF SATA hard drives*	—	—
	a) 120-GB, 5400-rpm	459616-001	Mandatory ¹
	b) 160-GB, 5400-rpm	390158-018	Mandatory ¹
	c) 500-GB, 5400-rpm	390158-016	Mandatory ¹
	d) 60-GB, 5400-rpm, 1.5G, hot-plug	405419-001	Mandatory ¹
	e) 120-GB, 5400-rpm, 1.5G, hot-plug	431908-001	Mandatory ¹
	f) 120-GB, 5400-rpm, hot-plug	459322-001	Mandatory ¹
	g) 250-GB, 5400-rpm, hot-plug	460427-001	Mandatory ¹
	h) 36-GB, SSD	461332-001	Mandatory ¹
	i) 64-GB, SSD	461333-001	Mandatory ¹
32	SFF SAS hard drives*	—	—
	a) 36-GB, 10,000-rpm, hot-plug, 3G	376596-001	Mandatory ¹
	b) 36-GB, 15,000-rpm, hot-plug, dual-port, 3G	418397-001	Mandatory ¹
	c) 36-GB, 15,000-rpm, hot-plug, 3G	432322-001	Mandatory ¹
	d) 72-GB, 10,000-rpm, hot-plug, 3G	434916-001	Mandatory ¹
	e) 72-GB, 10,000-rpm, hot-plug, dual-port	389346-001	Mandatory ¹
	f) 72-GB, 15,000-rpm, hot-plug, dual-port	418398-001	Mandatory ¹
	g) 72-GB, 10,000-rpm, hot-plug, dual-port, 3G	389346-001	Mandatory ¹
	h) 72-GB, 15,000-rpm, hot-plug, 3G	432321-001	Mandatory ¹
	i) 146-GB, 10,000-rpm, hot-plug, dual-port	418399-001	Mandatory ¹
	j) 146-GB, 10,000-rpm, hot-plug, 3G	432320-001	Mandatory ¹

Item	Description	Spare part number	Customer self repair (on page 5)
	k) 146-GB, 10,000-rpm, hot-plug, dual-port, 6G	507283-001	Mandatory ¹
	l) 300-GB, 10,000-rpm, hot-plug, dual-port	493083-001	Mandatory ¹
	m) 300-GB, 10,000-rpm, hot-plug, dual-port, 6G	507284-001	Mandatory ¹
	n) 72-GB 6GB/s, 15,000-rpm	586871-001	Mandatory ¹
	o) 146-GB 6GB/s, 10,000-rpm	507129-002	Mandatory ¹
	p) 146-GB 6GB/s, 15,000-rpm	507129-010	Mandatory ¹
	q) 300-GB 6GB/s, 10,000-rpm	507129-004	Mandatory ¹
	r) 450-GB 6GB/s, 10,000-rpm	507129-012	Mandatory ¹
	s) 500-GB 6GB/s, 7,200-rpm	507129-006	Mandatory ¹
	t) 600-GB 6GB/s, 10,000-rpm	507129-014	Mandatory ¹
33	SATA Midline (MDL) Solid State Drive	—	—
	a) 60-GB, hot-plug*	539557-008	Mandatory ¹
	b) 120-GB, hot-plug*	539557-010	Mandatory ¹
34	Keyboard*	355630-001	Mandatory ¹
35	Mouse*	344704-001	Mandatory ¹
36	PCI-X expansion cage, two-slot assembly*	439400-001	Optional ²
37	Smart Array P410i Controller cache module, 256-MB	462974-001	Optional ²
38	Smart Array P410i Controller cache module, 512-MB*	562975-001	Optional ²
39	Smart Array P410i Controller battery pack*	488138-001	Optional ²
40	Smart Array P410i Controller battery cable assembly, 0.3 m (11.5 in)*	409124-001	Optional ²
41	Smart Array P410i Controller battery cable assembly, 0.6 m (24 in)*	462976-001	Optional ²
42	Trusted Platform Module*	505836-001	No ³
43	Battery cable, 0.6 m (24 in)*	488138-001	Mandatory ¹
44	Miscellaneous cable kit *	511789-001	Mandatory ¹
	a) SATA data, 0.76 (30 in)	—	—
	b) SATA power	—	—
	c) Mini-SAS to Mini-SAS, 0.46 m (18 in)	—	—
	d) BBWC battery power, 0.6 m (24 in)*	—	—
45	FBWC capacitor pack*	587324-001	Mandatory ¹
46	FBWC cache module, 512-MB*	578882-001	Mandatory ¹
47	FBWC cache module, 1-GB*	505908-001	Mandatory ¹

*Not shown

** Do not mix single-, dual-, or quad-core processors or processors with different speeds or cache sizes.

*** If LVDIMMs are mixed with standard DDR3 DIMMs on the same server, the LVDIMMs operate at 1.5V. LVDIMMs are only supported for use with the Intel® Xeon® 5600 series of processors.

¹Mandatory—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

²Optional—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

³No—Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

¹Mandatory: Obligatoire—Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

²Optional: Facultatif—Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

³No: Non—Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

¹Mandatory: Obbligatorie—Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

²Optional: Opzionali—Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese aggiuntive a seconda del tipo di garanzia previsto per il prodotto.

³No: Non CSR—Alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

¹Mandatory: Zwingend—Teile, die im Rahmen des Customer Self Repair Programms ersetzt werden müssen. Wenn Sie diese Teile von HP ersetzen lassen, werden Ihnen die Versand- und Arbeitskosten für diesen Service berechnet.

²Optional: Optional—Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

³No: Kein—Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

¹Mandatory: Obligatorio—componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

²Optional: Opcional— componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

³No: No—Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

¹Mandatory: Verplicht—Onderdelen waarvoor Customer Self Repair verplicht is. Als u HP verzoekt deze onderdelen te vervangen, komen de reiskosten en het arbeidsloon voor uw rekening.

²Optional: Optioneel—Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garantieservice voor het product.

³No: Nee—Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievooraarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

¹Mandatory: Obrigatória—Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

²Optional: Opcional—Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

³No: Nenhuma—Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca “No” (Não), no catálogo de peças ilustrado.

¹Mandatory: 必須・顧客自己修理が必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。

²Optional: 任意・顧客自己修理が任意である部品。この部品も顧客自己修理用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、費用を負担していただくことなく保証サービスを受けることができます。

³No: 除外・HP製品の一部の部品は、顧客自己修理用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品が顧客自己修理除外品である旨が記載されています。

¹Mandatory: 强制性的 — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

²Optional: 可选的 — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据为您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

³No: 否 — 某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

¹Mandatory: 強制的 — 客戶自行維修所使用的零件是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

²Optional: 選購的 — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

³No: 否 — 某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

¹ Mandatory: 필수 — 고객 셀프 수리가 의무 사항인 필수 부품. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

² Optional: 옵션 — 고객 셀프 수리가 선택 사항인 부품. 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

³ No: No — 고객 셀프 수리가 불가능하도록 설계된 HP 부품. 이 부품들은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 고객 보증을 만족시키기 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다.

Removal and replacement procedures

Required tools

You need the following items for some procedures:

- T-10/T-15 Torx screwdriver
- HP Insight Diagnostics software ("[HP Insight Diagnostics](#)" on page 76)

Preparation procedures

To access some components and perform certain service procedures, you must perform one or more of the following procedures:

- Extend the server from the rack (on page 28).
If you are performing service procedures in an HP, Compaq branded, telco, or third-party rack cabinet, you can use the locking feature of the rack rails to support the server and gain access to internal components.
For more information about telco rack solutions, refer to the RackSolutions.com website (<http://www.racksolutions.com/hp>).
- Power down the server (on page 27).
If you must remove a server from a rack or a non-hot-plug component from a server, power down the server.
- Remove the server from the rack (on page 29).
If the rack environment, cabling configuration, or the server location in the rack creates awkward conditions, remove the server from the rack.
- Access the product rear panel ("[Access the server rear panel \(rack model\)](#)" on page 29).
If you are performing certain service procedures, access the product rear panel.

Power down the server



WARNING: To reduce the risk of personal injury, electric shock, or damage to the equipment, remove the power cord to remove power from the server. The front panel Power On/Standby button does not completely shut off system power. Portions of the power supply and some internal circuitry remain active until AC power is removed.



IMPORTANT: If installing a hot-plug device, it is not necessary to power down the server.

1. Back up the server data.
2. Shut down the operating system as directed by the operating system documentation.

NOTE: If the operating system automatically places the server in Standby mode, omit the next step.

3. Press the Power On/Standby button to place the server in Standby mode. When the server activates Standby power mode, the system power LED changes to amber.



IMPORTANT: Pressing the UID button illuminates the blue UID LEDs on the front and rear panels. In a rack environment, this feature facilitates locating a server when moving between the front and rear of the rack.

4. Disconnect the power cords.

The system is now without power.

Extend the server from the rack

1. Power down the server (on page 27).
2. Pull down the quick-release levers on each side of the server to release the server from the rack.



IMPORTANT: If the server is installed in a telco rack, remove the server from the rack to access internal components.

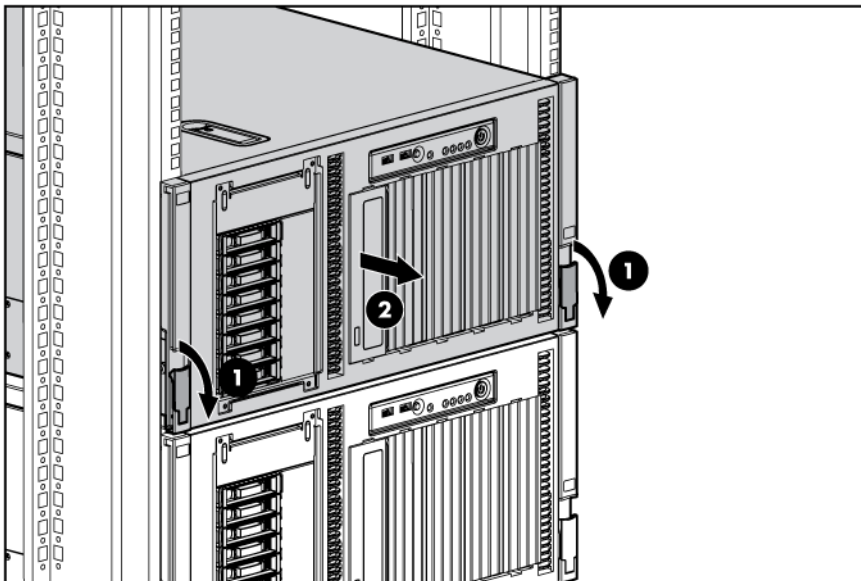
3. Extend the server on the rack rails until the server rail-release latches engage.



WARNING: To reduce the risk of personal injury or equipment damage, be sure that the rack is adequately stabilized before extending a component from the rack.



WARNING: To reduce the risk of personal injury, be careful when pressing the server rail-release latches and sliding the server into the rack. The sliding rails could pinch your fingers.



4. After performing the installation or maintenance procedure, press the rail-release latches and slide the server back into the rack.

Remove the server from the rack

To remove the server from an HP, Compaq branded, telco, or third-party rack:

1. Power down the server (on page 27).
2. Extend the server from the rack (on page 28).
3. Disconnect the cabling and remove the server from the rack. For more information, refer to the documentation that ships with the rack mounting option.
4. Place the server on a sturdy, level surface.

Access the server rear panel (rack model)

If the procedure requires accessing the server rear panel, unlock the cable management arm and swing the arm away from the server. For information on unlocking the cable management arm, refer to the installation instructions that ship with the 3-7U Quick Deploy Rail System.

Safety considerations

Before performing service procedures, review all the safety information.

Preventing electrostatic discharge

To prevent damaging the system, be aware of the precautions you need to follow when setting up the system or handling parts. A discharge of static electricity from a finger or other conductor may damage system boards or other static-sensitive devices. This type of damage may reduce the life expectancy of the device.

To prevent electrostatic damage:

- Avoid hand contact by transporting and storing products in static-safe containers.
- Keep electrostatic-sensitive parts in their containers until they arrive at static-free workstations.
- Place parts on a grounded surface before removing them from their containers.
- Avoid touching pins, leads, or circuitry.
- Always be properly grounded when touching a static-sensitive component or assembly.

Server warnings and cautions

Before installing a server, be sure that you understand the following warnings and cautions.



WARNING: To reduce the risk of electric shock or damage to the equipment:

- Do not disable the power cord grounding plug. The grounding plug is an important safety feature.
 - Plug the power cord into a grounded (earthed) electrical outlet that is easily accessible at all times.
 - Unplug the power cord from the power supply to disconnect power to the equipment.
 - Do not route the power cord where it can be walked on or pinched by items placed against it. Pay particular attention to the plug, electrical outlet, and the point where the cord extends from the server.
-

⚠ WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

⚠ CAUTION: Do not operate the server for long periods with the access panel open or removed. Operating the server in this manner results in improper airflow and improper cooling that can lead to thermal damage.

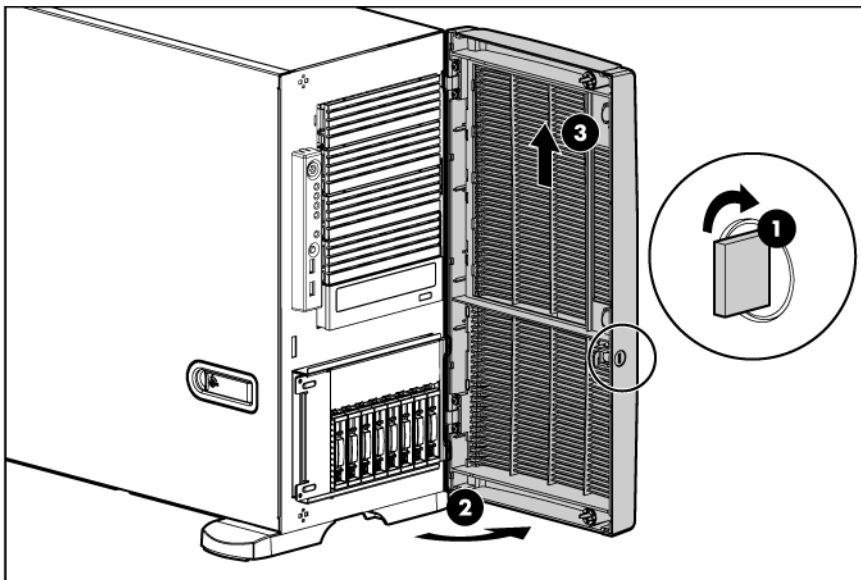
Front bezel

This server has a removable bezel that must be unlocked and opened before accessing the front panel components. The bezel should be kept closed during normal server operations.

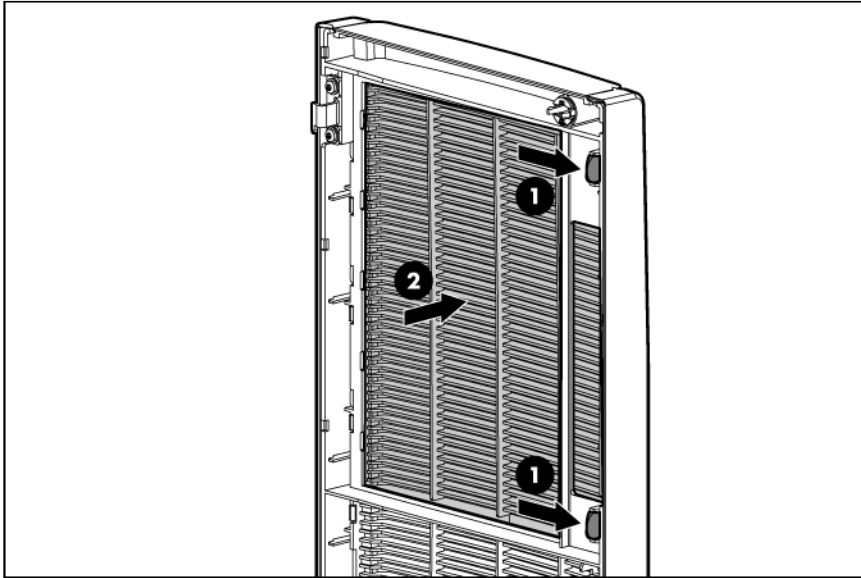
Use the key provided with the server to unlock the bezel with a clockwise turn.

If necessary, remove the bezel.

⚠ CAUTION: To avoid breaking the bezel, remove the bezel before placing the server on its side.



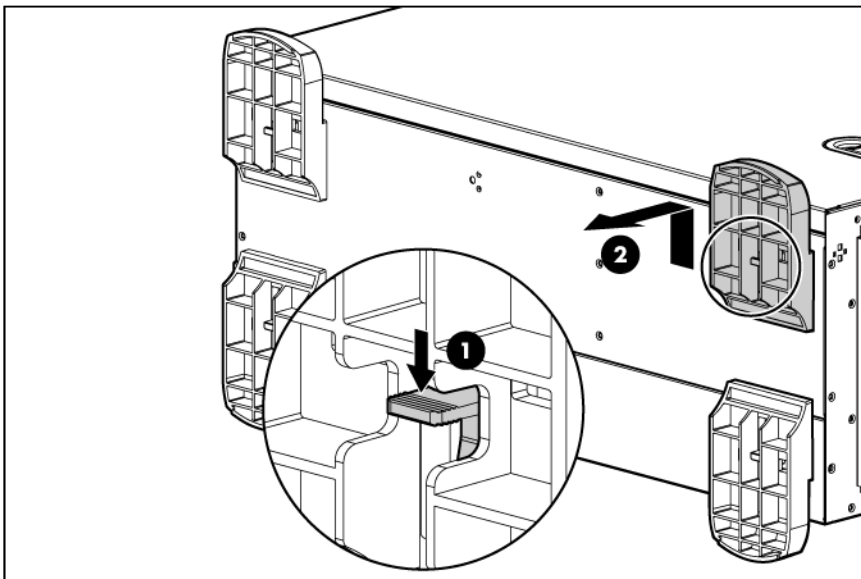
For operations involving removable media bay access, the media bay panel can be removed from the bezel.



Tower foot

To remove the component:

1. Power down the server (on page 27).
2. Remove the tower bezel ("Front bezel" on page 30).
3. Place the server on its side.
4. Remove the foot.



To replace the component, reverse the removal procedure.

Access panel



CAUTION: Do not operate the server with the access panel removed. Operating the server in this manner results in improper airflow and improper cooling that can lead to thermal damage.

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the tower front bezel. ("Front bezel" on page 30)
3. If the locking latch is locked, use a T-15 Torx screwdriver to unlock the latch.
4. Slide the access panel back about 1.5 cm (0.5 in).
5. Lift and remove the access panel.

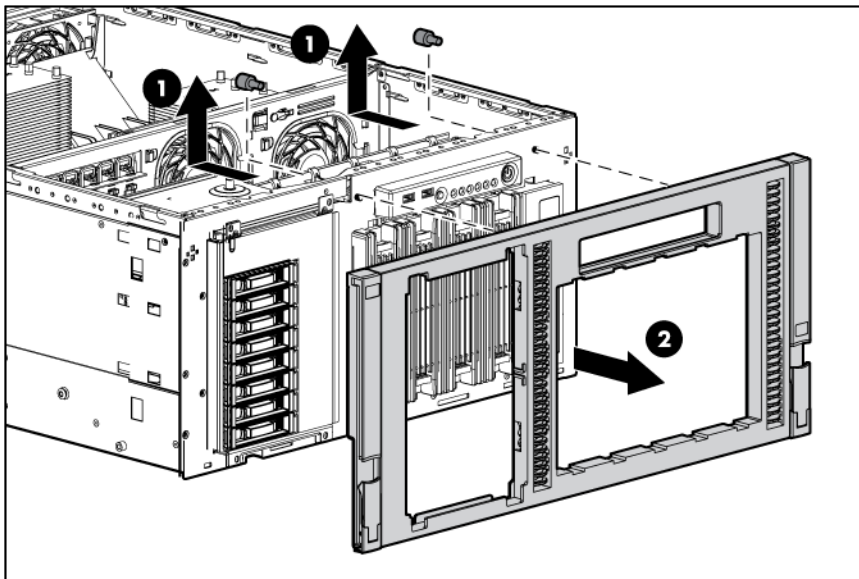
Turn the access panel over to locate labeling with information about options installation, LEDs, and switch settings.

To replace the component, reverse the removal procedure.

Rack bezel

To remove the component:

1. Power down the server (on page 27).
2. Extend the server from the rack (on page 28).
3. Remove the access panel ("Access panel" on page 31).
4. Remove the bezel.

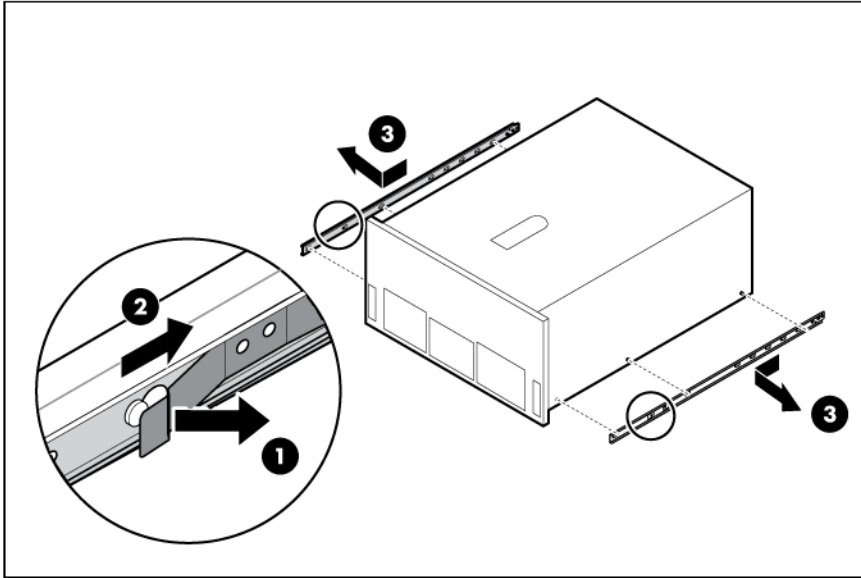


To replace the component, reverse the removal procedure.

Rack rails

To remove the component:

1. Power down the server (on page [27](#)).
2. Remove the server from the rack (on page [29](#)).
3. Use a flat-head screwdriver to lift the spring tab.
4. Slide the rail forward and remove it from the server.



5. Repeat the steps above to remove the other rail.

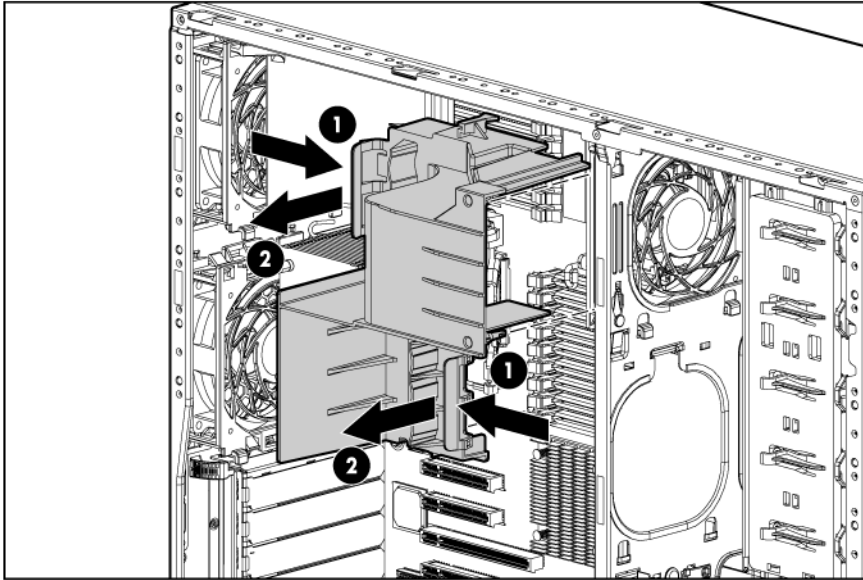
To replace the component, reverse the removal procedure.

Large redundant fan air baffle

To remove the component:

1. Power down the server (on page [27](#)).
2. Do one of the following:
 - Open or remove the tower bezel, as needed ("[Front bezel](#)" on page [30](#)).
 - Extend the server from the rack (on page [28](#)).
3. Remove the access panel ("[Access panel](#)" on page [31](#)).

4. Remove the large redundant fan air baffle.

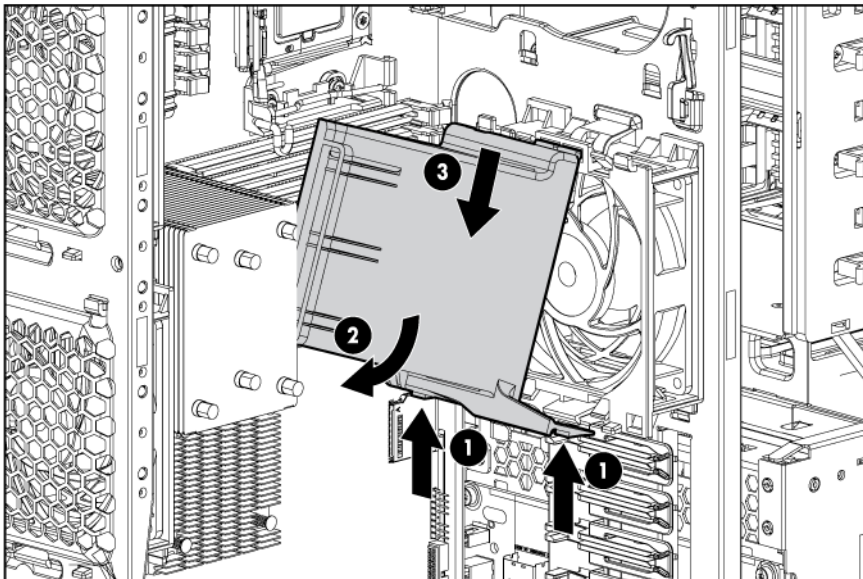


To replace the component, reverse the removal procedure.

DIMM baffle

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - o Open or remove the tower bezel, as needed ("[Front bezel](#)" on page 30).
 - o Extend the server from the rack (on page 28).
3. Remove the access panel ("[Access panel](#)" on page 31).
4. Remove the large redundant fan air baffle, if installed ("[Large redundant fan air baffle](#)" on page 33).
5. Remove the DIMM baffle.

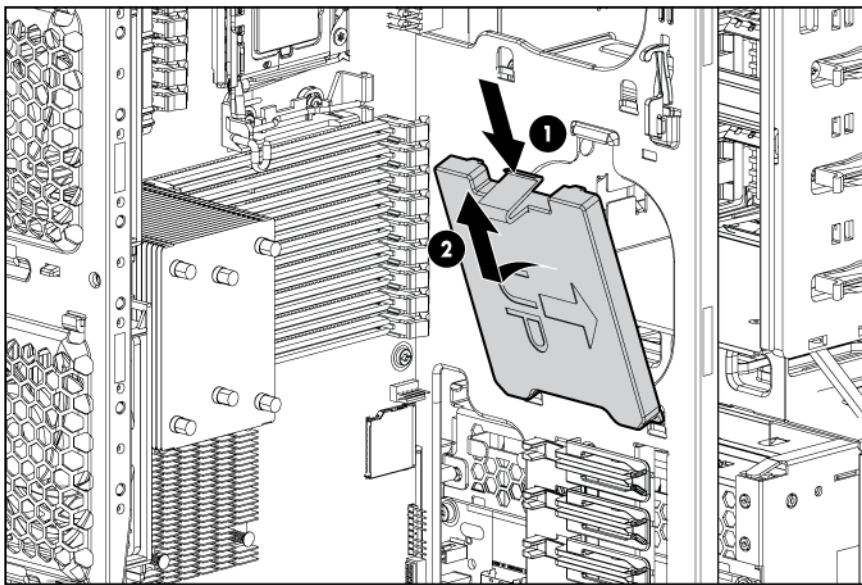


To replace the component, reverse the removal procedure.

Fan blank

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - o Open or remove the tower bezel, as needed ("Front bezel" on page 30).
 - o Extend the server from the rack (on page 28).
3. Remove the access panel ("Access panel" on page 31).
4. Remove the large redundant fan air baffle, if installed ("Large redundant fan air baffle" on page 33).
5. Remove the fan blank.



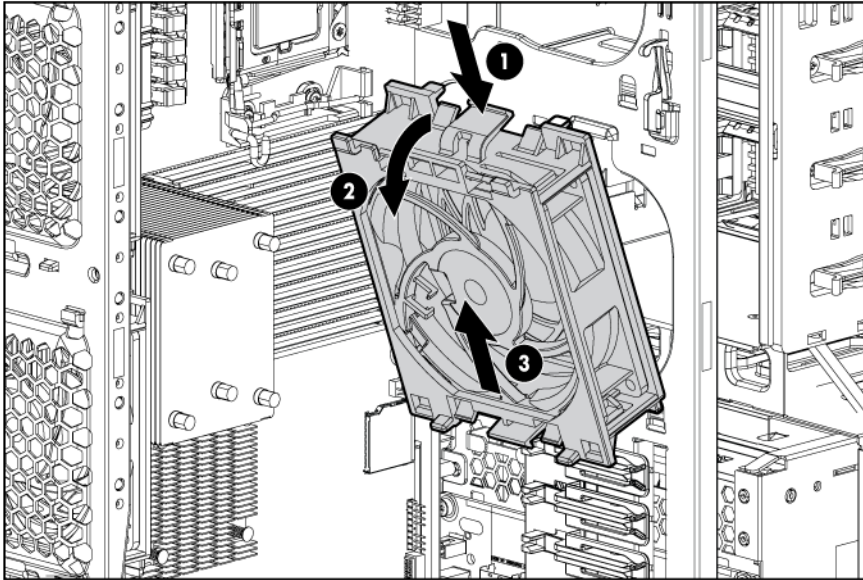
To replace the component, reverse the removal procedure.

Fan

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - o Open or remove the tower bezel, as needed ("Front bezel" on page 30).
 - o Extend the server from the rack (on page 28).
3. Remove the access panel ("Access panel" on page 31).
4. Remove the large redundant fan air baffle, if installed ("Large redundant fan air baffle" on page 33).
5. Disconnect the fan cable.

6. Remove the fan.



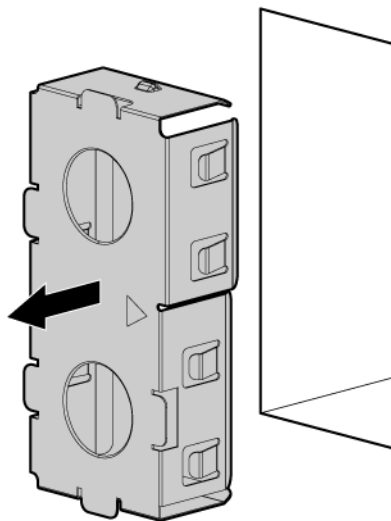
To replace the component, reverse the removal procedure.

Power supply blank

To remove the component:

1. Access the product rear panel ("[Access the server rear panel \(rack model\)](#)" on page 29).
2. Remove the power supply blank.

⚠ WARNING: To reduce the risk of personal injury from hot surfaces, allow the power supply or power supply blank to cool before touching it.



To replace the component, reverse the removal procedure.

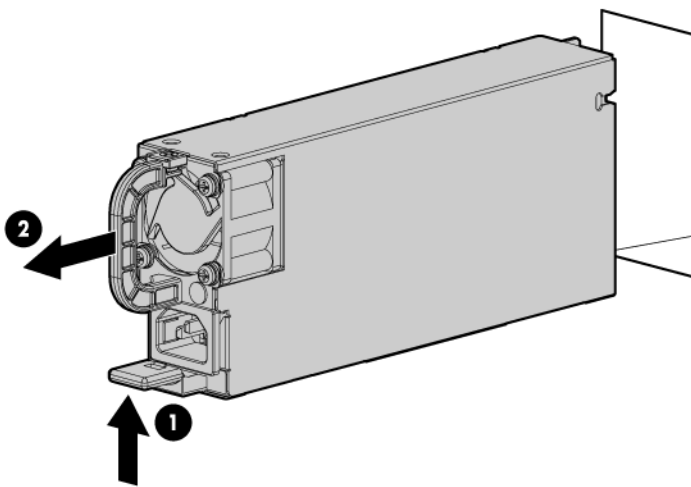
Hot-plug power supply

⚠ WARNING: To reduce the risk of electric shock, do not disassemble the power supply or attempt to repair it. Replace it only with the specified spare part.

⚠ CAUTION: Do not attempt to remove and replace a power supply as a hot-plug procedure unless both bays are populated with power supplies.

To remove the component:

1. Access the product rear panel ("[Access the server rear panel \(rack model\)](#)" on page 29).
2. Disconnect the power cord from the AC source.
3. Disconnect the power cord from the power supply.
4. Remove the power supply.



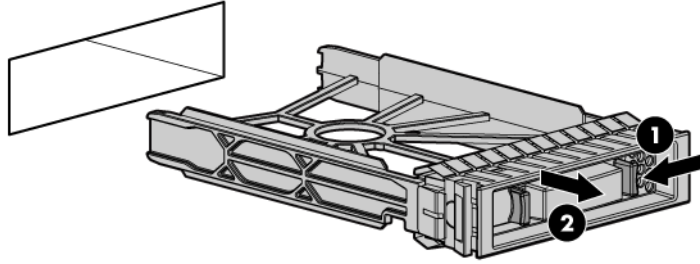
⚠ CAUTION: To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

To replace the component, reverse the removal procedure.

SAS hard drive blank

⚠ CAUTION: For proper cooling do not operate the server without the access panel, baffles, expansion slot covers, or blanks installed. If the server supports hot-plug components, minimize the amount of time the access panel is open.

Remove the component as indicated.



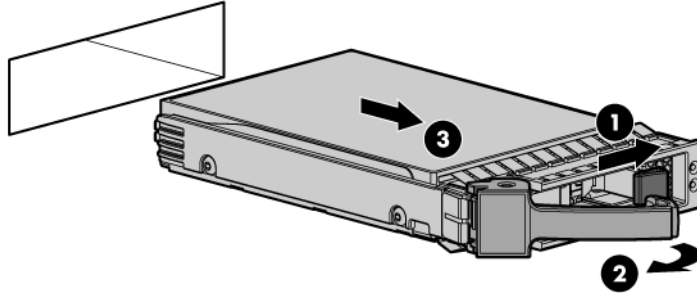
To replace the blank, slide the blank into the bay until it locks into place.

SAS/SATA hard drive

CAUTION: To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

To remove the component:

1. Determine the status of the hard drive from the hot-plug SAS hard drive LED combinations ("[SAS and SATA hard drive LED combinations](#)" on page 90).
2. Back up all server data on the hard drive.
3. Remove the hard drive.



To replace the component, reverse the removal procedure.

Hard drive cages

The server supports the following hard drive cages:

- Standard six-bay LFF or eight-bay SFF hard drive cage ("[Standard hard drive cage](#)" on page 39)
- Optional eight-bay SFF hard drive cage (on page 39)
- Optional two-bay LFF hard drive cage (on page 41)

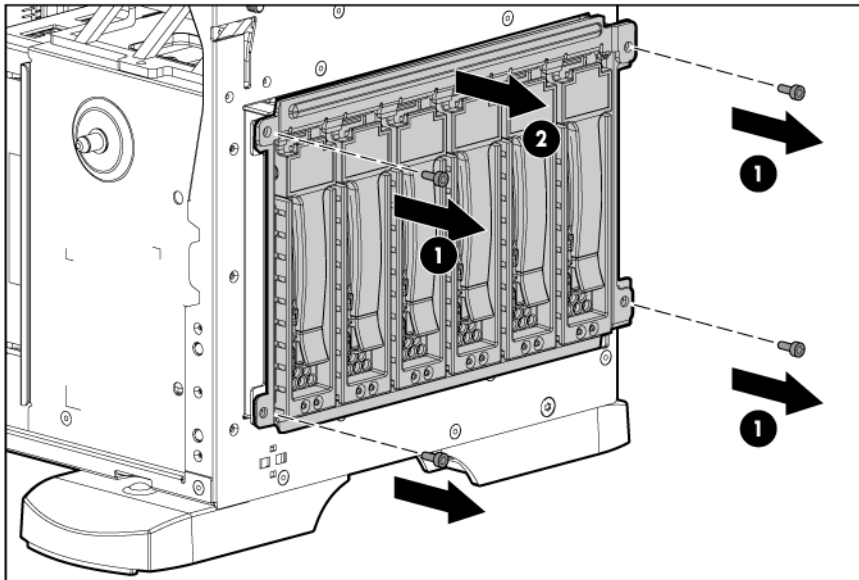
For jumper settings, see "[Optional hard drive cage jumper location and configuration settings](#) (on page 97)."

Standard hard drive cage

The procedure is the same for both the standard six-bay LFF hard drive cage and the standard eight-bay SFF hard drive cage.

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - o Open or remove the tower bezel, as needed ("Front bezel" on page 30).
 - o Extend the server from the rack (on page 28).
3. Place the tower server on its side.
4. Remove the access panel ("Access panel" on page 31).
5. Disconnect all cables from the rear of the hard drive cage.
6. Remove the hard drive cage.



7. Remove all hard drives ("SAS/SATA hard drive" on page 38).

To replace the component, reverse the removal procedure.

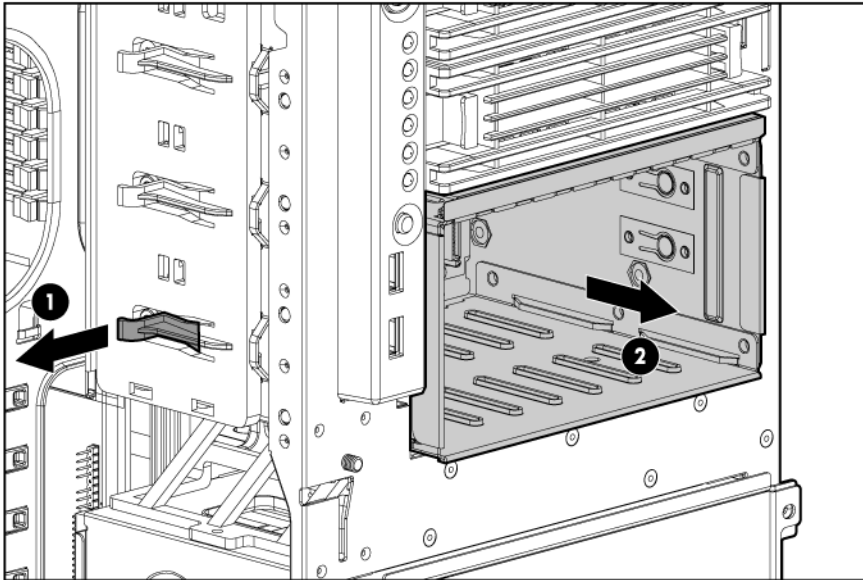
Optional eight-bay SFF hard drive cage

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - o Open or remove the tower bezel, as needed ("Front bezel" on page 30).
 - o Extend the server from the rack (on page 28).
3. Place the tower server on its side.
4. Remove the access panel ("Access panel" on page 31).
5. Remove all hard drives ("SAS/SATA hard drive" on page 38).
6. Disconnect all cables from the rear of the hard drive cage.

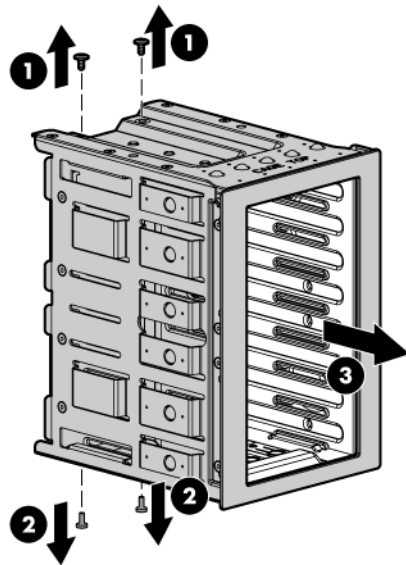
NOTE: Remove the shipping screw, if installed, before removing the hard drive cage.

7. Remove the hard drive cage.

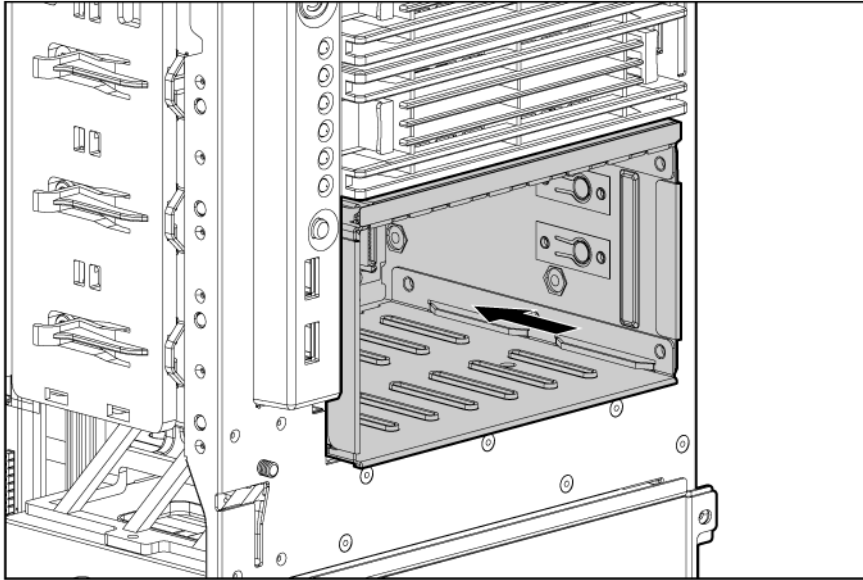


To replace the component:

1. Using a T-15 Torx screwdriver, remove the sleeve from the spare hard drive cage.



2. Install the SFF hard drive cage into the server.



3. Connect all cables to the spare hard drive cage.



CAUTION: Always populate each media bay with either a device or a blank. Proper airflow can only be maintained when the bays are populated. Unpopulated drive bays can lead to improper cooling and thermal damage.

4. Install any hard drives or blanks.
5. Install the access panel.
6. Do one of the following:
 - o Close or install the tower bezel, as needed.
 - o Slide the server back into the rack.
7. Power up the server.

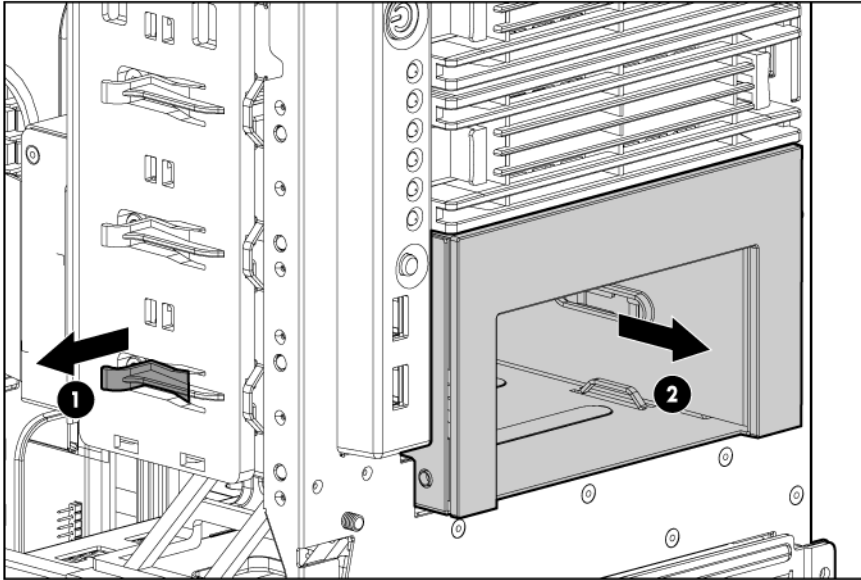
Optional two-bay LFF hard drive cage

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - o Open or remove the tower bezel, as needed ("[Front bezel](#)" on page 30).
 - o Extend the server from the rack (on page 28).
3. Place the tower server on its side.
4. Remove the access panel ("[Access panel](#)" on page 31).
5. Remove all hard drives ("[SAS/SATA hard drive](#)" on page 38).
6. Disconnect all cables from the rear of the hard drive cage.

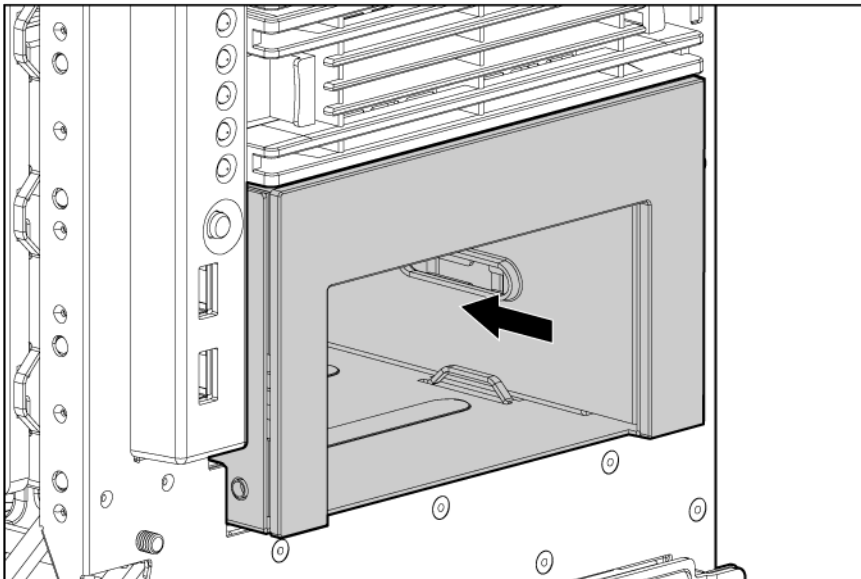
NOTE: Remove the shipping screw, if installed, before removing the hard drive cage.

7. Remove the hard drive cage.



To replace the component:

1. Slide the spare hard drive cage about three-fourths of the way into the bay, leaving room to connect cables at the back of the drive cage.



2. Connect all cables to the spare hard drive cage.
3. Slide the optional hard drive cage fully into the bay until it clicks.

CAUTION: Always populate each media bay with either a device or a blank. Proper airflow can only be maintained when the bays are populated. Unpopulated drive bays can lead to improper cooling and thermal damage.

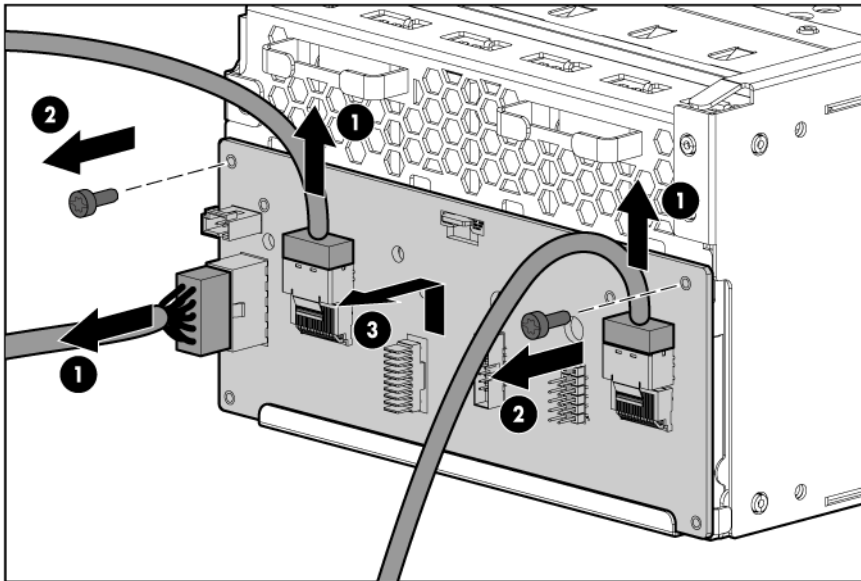
4. Install any hard drives or blanks.
5. Install the access panel.
6. Do one of the following:
 - o Close or install the tower bezel, as needed.

- Slide the server back into the rack.
7. Power up the server.

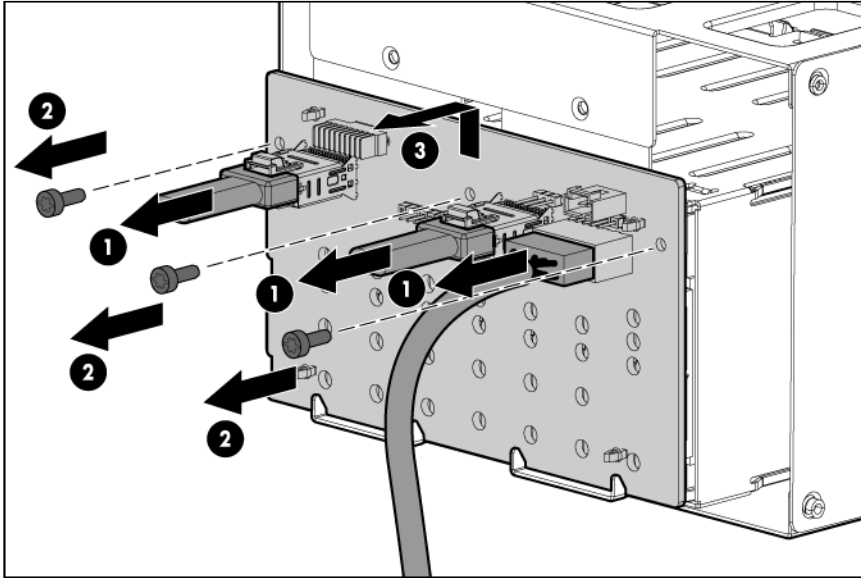
Standard hard drive cage backplane

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - Open or remove the tower bezel, as needed ("Front bezel" on page 30).
 - Extend the server from the rack (on page 28).
3. Place the tower server on its side.
4. Remove the access panel ("Access panel" on page 31).
5. Disconnect all cables from the rear of the hard drive cage.
6. Remove the hard drive cage ("Standard hard drive cage" on page 39).
7. Remove all hard drives ("SAS/SATA hard drive" on page 38).
8. Remove the hard drive cage backplane:
 - Six-bay LFF hard drive cage backplane



- Eight-bay SFF hard drive cage backplane

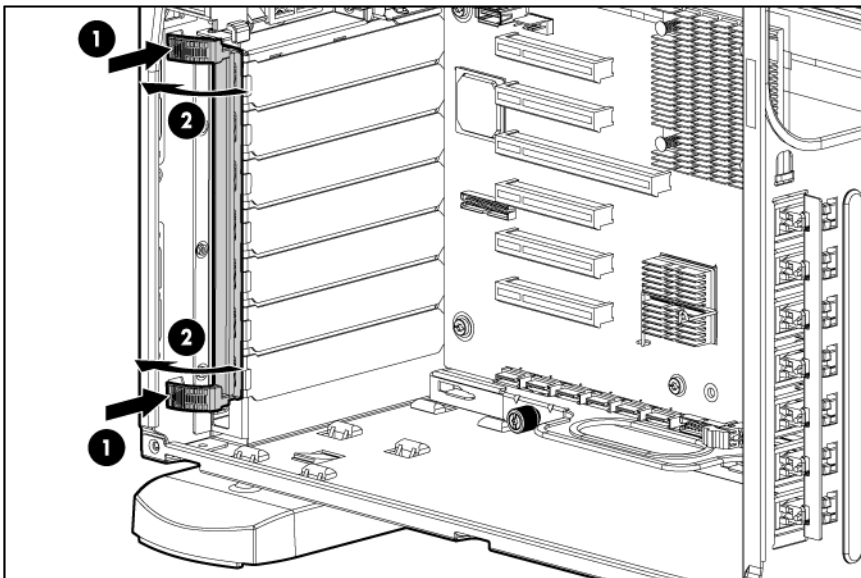


To replace the component, reverse the removal procedure.

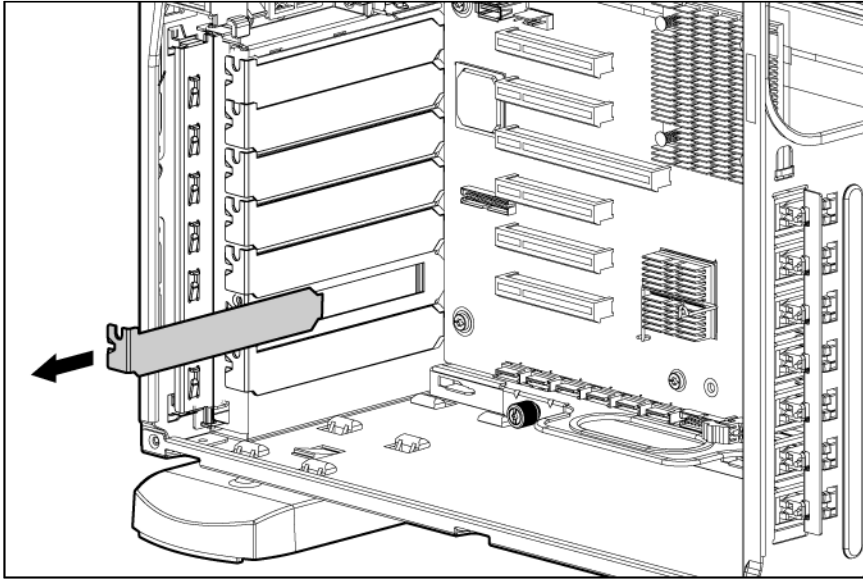
Expansion slot cover

To remove the component:

1. Do one of the following:
 - Unlock and remove the bezel ("[Front bezel](#)" on page 30).
 - Extend the server from the rack (on page 28).
2. Remove the access panel ("[Access panel](#)" on page 31).
3. Push the release latches on the expansion board retainer, and then open the retainer.



4. Remove the expansion slot cover.



⚠ **CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all PCI slots have either an expansion slot cover or an expansion board installed.

To replace the component, reverse the removal procedure.

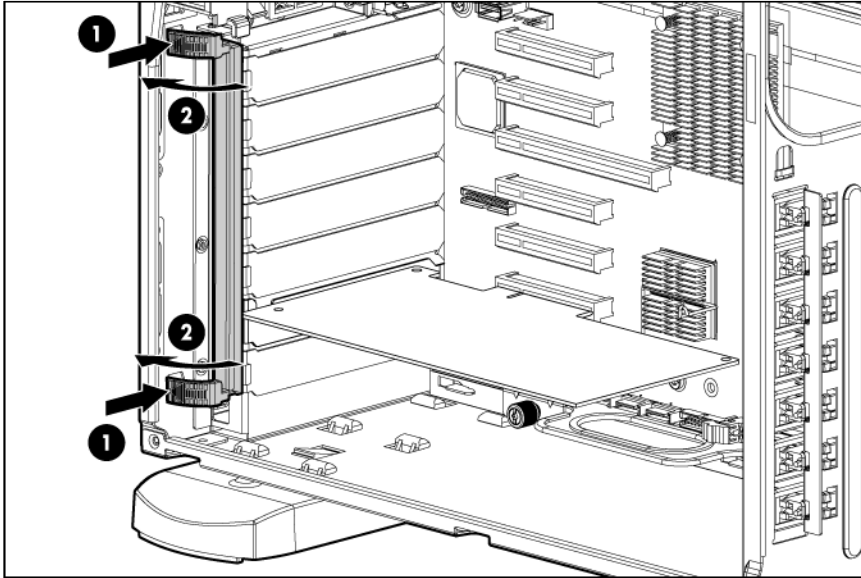
Expansion board

⚠ **CAUTION:** To prevent damage to the server or expansion boards, power down the server and remove all AC power cords before removing or installing the expansion boards.

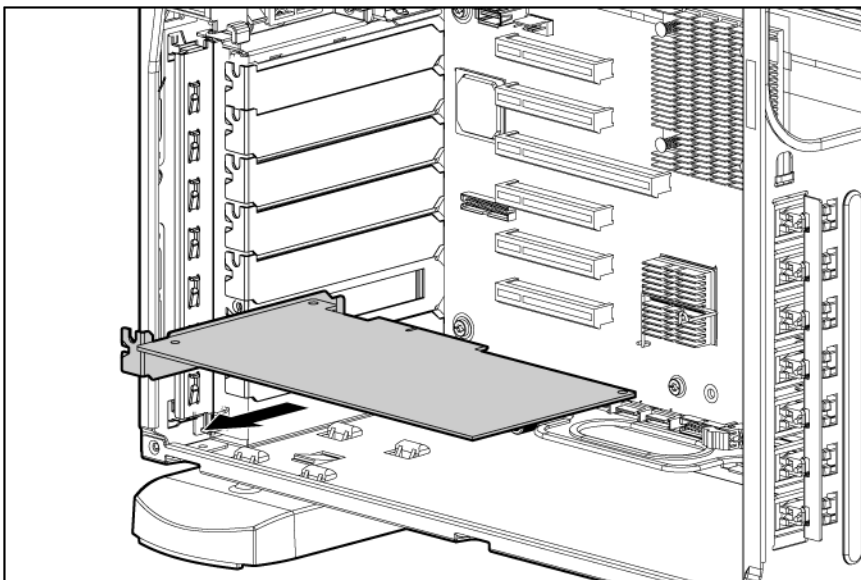
To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - Unlock and remove the bezel ("Front bezel" on page 30).
 - Extend the server from the rack (on page 28).
3. Remove the access panel ("Access panel" on page 31).
4. Disconnect any internal or external cables from the expansion board.

5. Push the release latches on the expansion board retainer, and then open the retainer.



6. Remove the T-15 Torx screw securing the expansion board, if necessary.
7. Remove the expansion board.



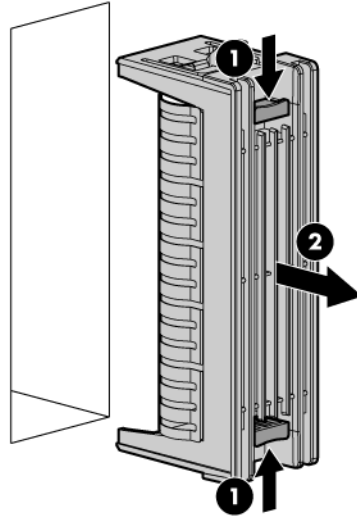
To replace the component, reverse the removal procedure.

Media bay blank

To remove the component:

1. Open or remove the tower bezel ("Front bezel" on page 30).

2. Remove the media bay blank.



To replace the component, reverse the removal procedure.

Battery-backed write cache procedures

Two types of procedures are provided for the BBWC option:

- Removal and replacement of failed components:
 - Removing the cache module ("[Battery-backed write cache module](#)" on page 47)
 - Removing the battery pack ("[BBWC battery pack](#)" on page 48)
- Recovery of cached data from a failed server ("[Recovering data from the battery-backed write cache](#)" on page 49)

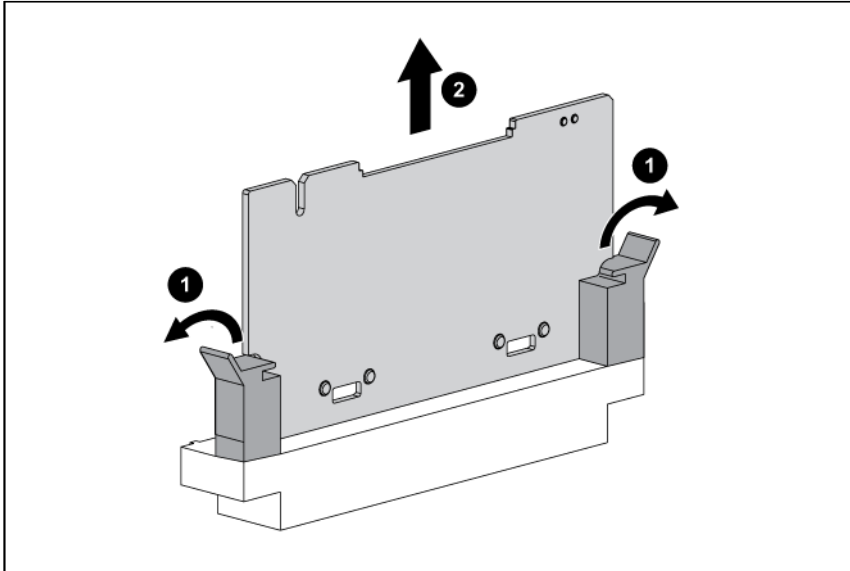
CAUTION: Do not detach the cable that connects the battery pack to the cache module. Detaching the cable causes any unsaved data in the cache module to be lost.

Battery-backed write cache module

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - Open or remove the tower bezel, as needed ("[Front bezel](#)" on page 30).
 - Extend the server from the rack (on page 28).
3. Remove the access panel ("[Access panel](#)" on page 31).

4. Remove the cache module.

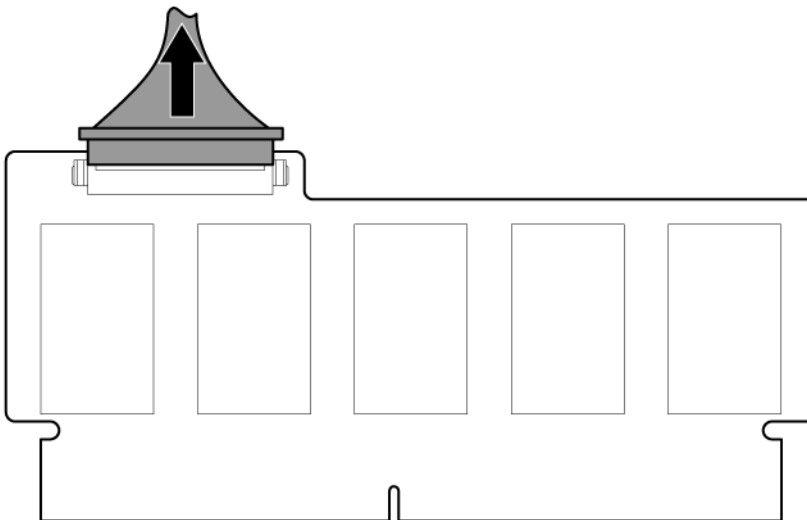


To replace the component, reverse the removal procedure.

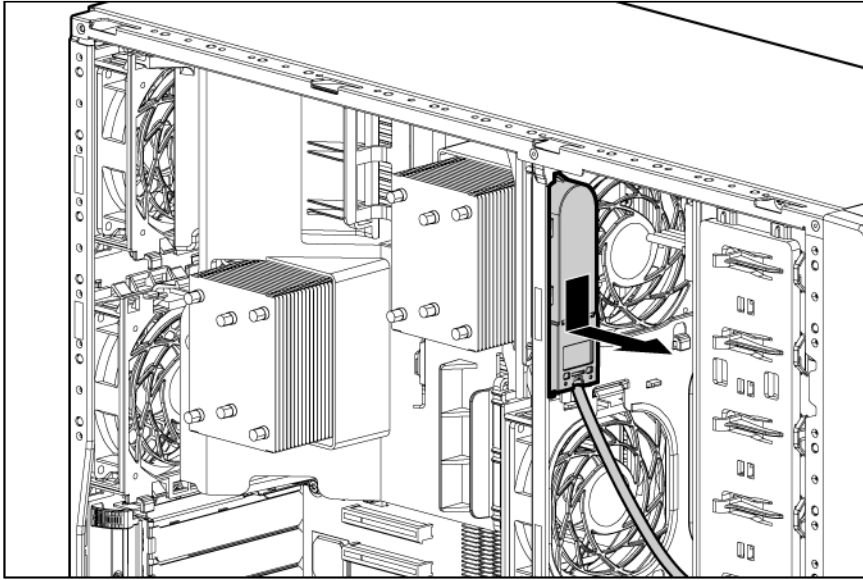
BBWC battery pack

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - o Open or remove the tower bezel, as needed ("Front bezel" on page 30).
 - o Extend the server from the rack (on page 28).
3. Remove the access panel ("Access panel" on page 31).
4. Disconnect the BBWC cable from the cache module.



5. Remove the battery pack.



To replace the component, reverse the removal procedure.

Recovering data from the battery-backed write cache

If the server fails, use the following procedure to recover data temporarily stored in the BBWC.

CAUTION: Before starting this procedure, read the information about protecting against electrostatic discharge ("[Preventing electrostatic discharge](#)" on page 29).

1. Perform one of the following:
 - Set up a recovery server station using an identical server model. Do not install any internal drives or BBWC in this server. (HP recommends this option.)
 - Find a server that has enough empty drive bays to accommodate all the drives from the failed server and that meets all the other requirements for drive and array migration.
2. Power down the failed server ("[Power down the server](#)" on page 27). If any data is stored in the cache module, a green LED on the module flashes every 2 seconds.


CAUTION: Do not detach the cable that connects the battery pack to the cache module. Detaching the cable causes any unsaved data in the cache module to be lost.

3. Transfer the hard drives from the failed server to the recovery server station.
4. Perform one of the following:
 - If the array controller has failed, remove the cache module ("[Battery-backed write cache module](#)" on page 47) and battery pack ("[BBWC battery pack](#)" on page 48) from the failed array controller, and install the cache module and battery pack on an array controller in the recovery server.
 - If the server has failed, remove the controller, cache module ("[Battery-backed write cache module](#)" on page 47), and battery pack ("[BBWC battery pack](#)" on page 48) from the failed server, and install the controller, cache module, and battery pack in the recovery server.
5. Power up the recovery server. A 1759 POST message is displayed, stating that valid data was flushed from the cache. This data is now stored on the drives in the recovery server. You can now transfer the drives (and controller, if one was used) to another server.

Flash-backed write cache procedures


Two types of procedures are provided for the FBWC option:

- Removal and replacement of failed components:
 - Removing the cache module ("[Flash-backed write cache module](#)" on page 50)
 - Removing the capacitor pack ("[Flash-backed write cache capacitor pack](#)" on page 51)
- Recovery of cached data from a failed server ("[Recovering data from the battery-backed write cache](#)" on page 49)


 **CAUTION:** Do not detach the cable that connects the battery pack or capacitor pack to the cache module. Detaching the cable causes any unsaved data in the cache module to be lost.

Flash-backed write cache module

To remove the component:

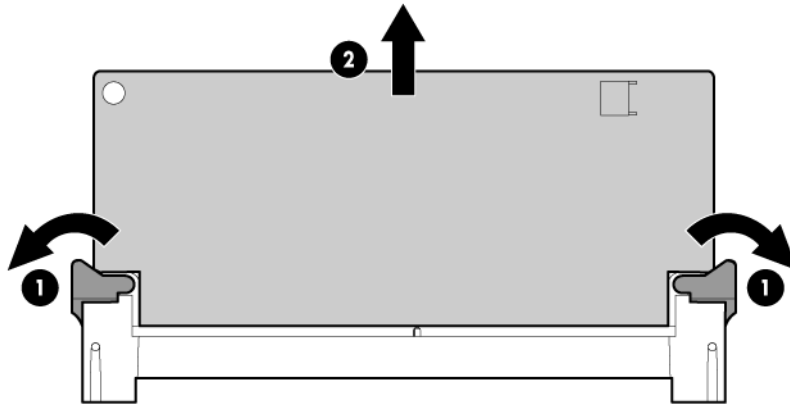
 **CAUTION:** Do not use this controller with cache modules designed for other controller models, because the controller can malfunction and you can lose data. Also, do not transfer this cache module to a different controller module, because you can lose data.

1. Back up all data.
2. Close all applications.
3. Power down the server (on page 27).

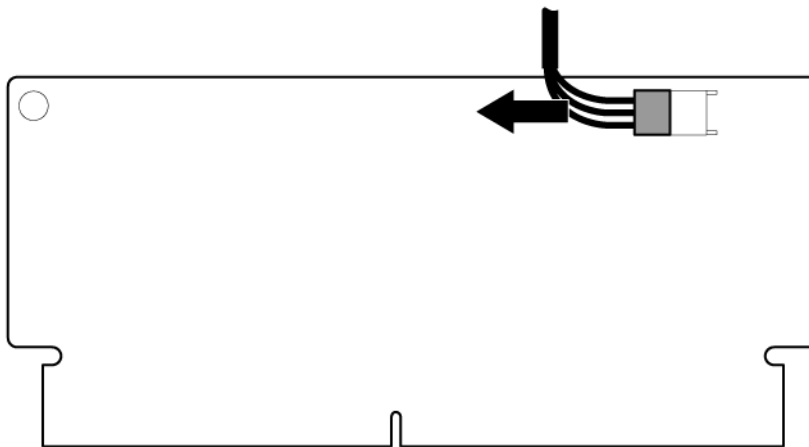
 **CAUTION:** In systems that use external data storage, be sure that the server is the first unit to be powered down and the last to be powered back up. Taking this precaution ensures that the system does not erroneously mark the drives as failed when the server is powered up.

4. Do one of the following:
 - Open or remove the tower bezel, as needed ("[Front bezel](#)" on page 30).
 - Extend the server from the rack (on page 28).
5. Remove the access panel ("[Access panel](#)" on page 31).
6. If the existing cache module is connected to a capacitor pack, observe the FBWC module LEDs (on page 92):
 - If the amber LED is flashing, data is trapped in the cache. Restore system power, and restart this procedure from step 1.
 - If the amber LED is not illuminated, remove the controller from the server, and then continue with the next step.

7. Open the ejector latches on each side of the cache module connector. Normally, the cache module is ejected from the cache module connector. If the module is not ejected automatically, remove the cache module.



8. If the cache module is connected to a capacitor pack, disconnect the capacitor pack cable from the connector on the top of the cache module.



To replace the component, reverse the removal procedure.

- CAUTION:** To prevent damage to the cache module during installation, be sure the cache module is fully inserted before pressing down.

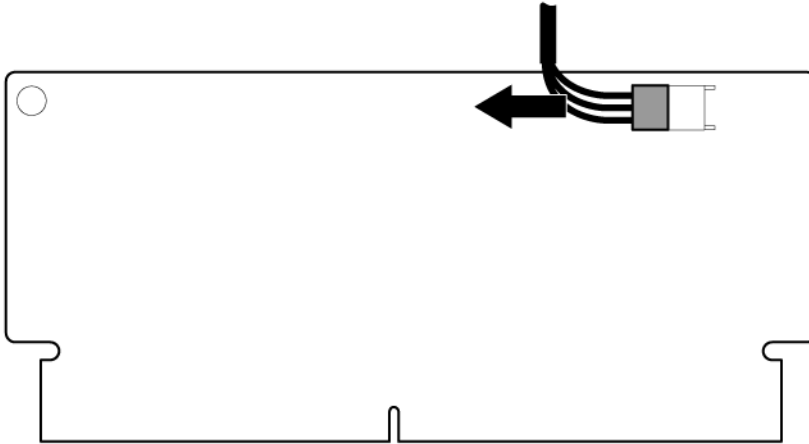
Flash-backed write cache capacitor pack

To remove the component:

1. Back up all data.
2. Close all applications.
3. Power down the server (on page 27).

CAUTION: In systems that use external data storage, be sure that the server is the first unit to be powered down and the last to be powered back up. Taking this precaution ensures that the system does not erroneously mark the drives as failed when the server is powered up.

4. Do one of the following:
 - Open or remove the tower bezel, as needed ("Front bezel" on page 30).
 - Extend the server from the rack (on page 28).
5. Remove the access panel ("Access panel" on page 31).
6. If the capacitor pack is connected to the cache module, disconnect the capacitor pack cable from the connector on the top of the cache module.



7. Remove the capacitor pack.
To replace the component, reverse the removal procedure.

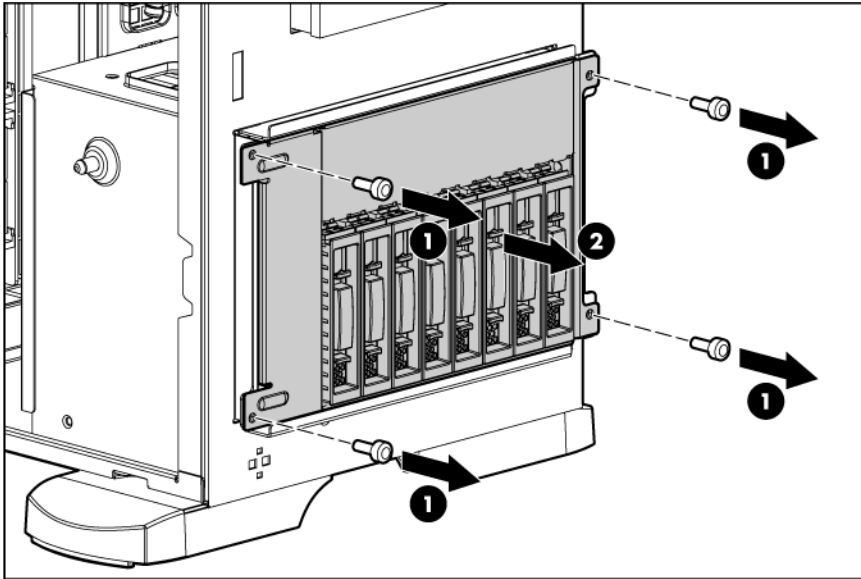
PCI-X expansion cage

CAUTION: To prevent damage to the server or expansion boards, power down the server and remove all AC power cords before removing or installing the PCI expansion cage.

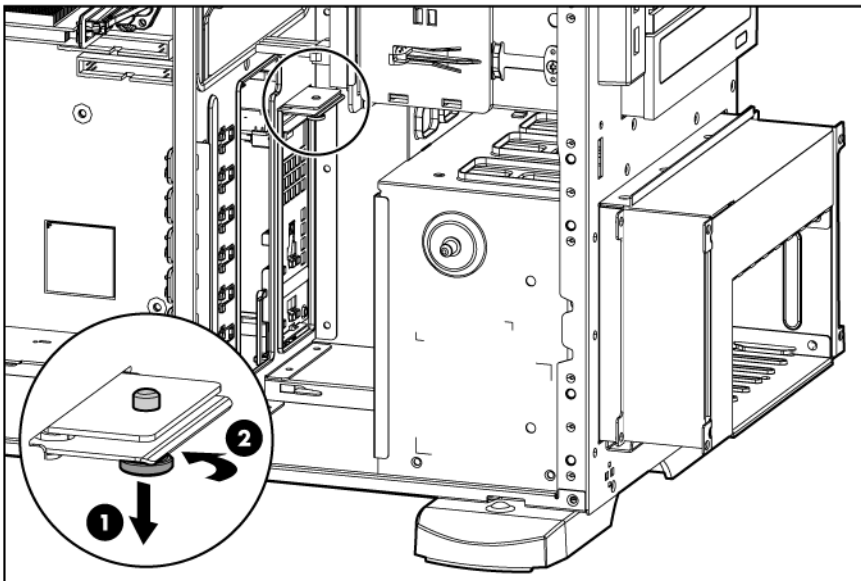
To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - Unlock and remove the bezel ("Front bezel" on page 30).
 - Extend the server from the rack (on page 28).
3. Remove the access panel ("Access panel" on page 31).
4. Remove the rack bezel (rack servers only) ("Rack bezel" on page 32).

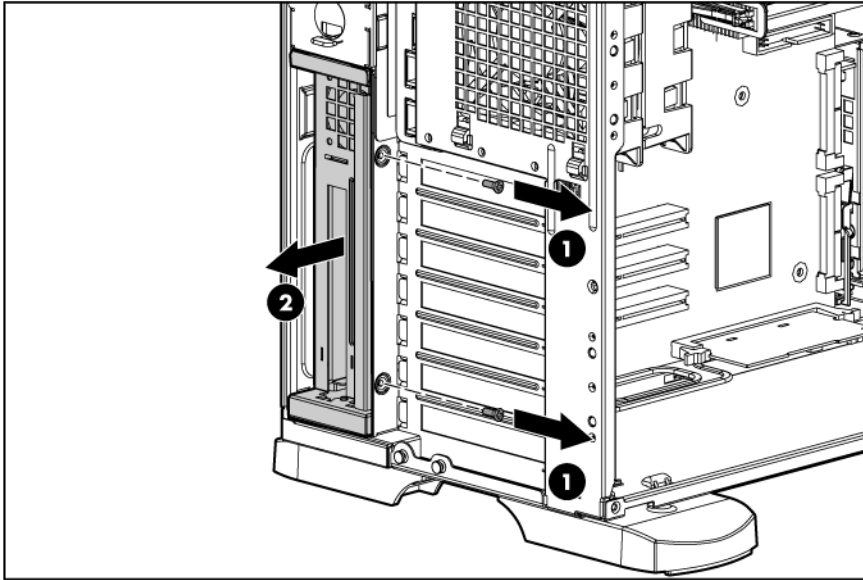
5. Remove the four T-15 screws from the hard drive cage, and then slide the hard drive cage partially out of the chassis.



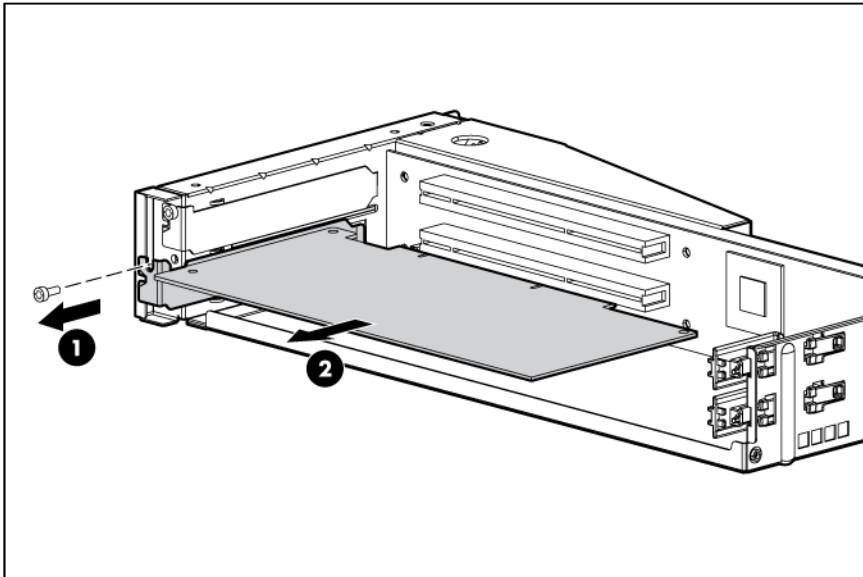
6. Disconnect any external cables from the PCI-X expansion boards.
7. Disconnect the power cable extension and the signal cable from the PCI-X expansion cage.
8. Pull the spring-loaded locking pin out of its socket.



9. Remove the PCI-X expansion cage.



10. Remove any expansion boards.



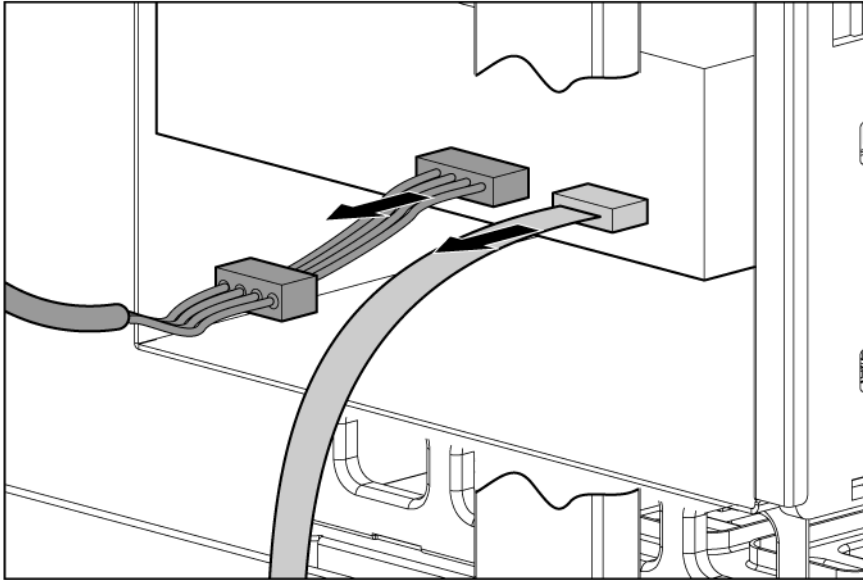
To replace the components, reverse the removal procedure.

Half-height or full-height media device

To remove the component:

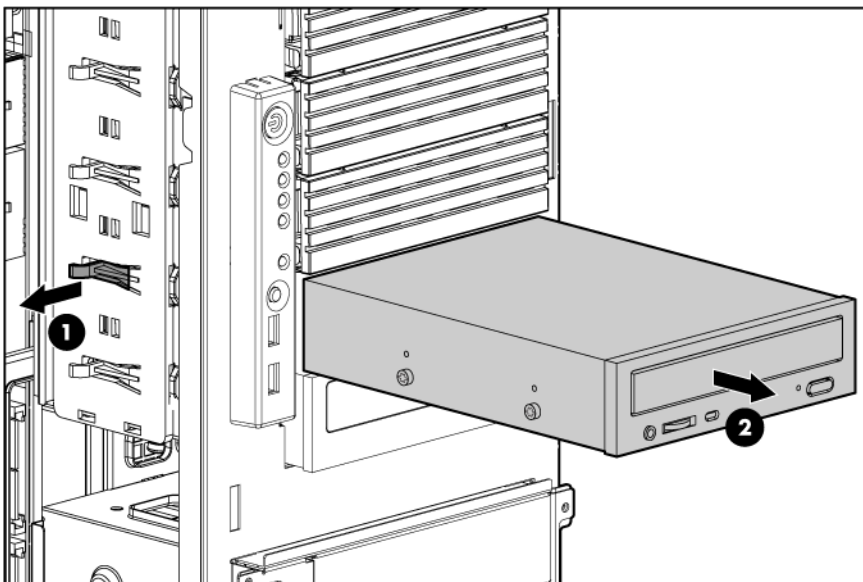
1. Power down the server (on page 27).
2. Do one of the following:
 - o Unlock and remove the bezel ("Front bezel" on page 30).
 - o Extend the server from the rack (on page 28).
3. Remove the access panel ("Access panel" on page 31).

4. Disconnect data and power cables:

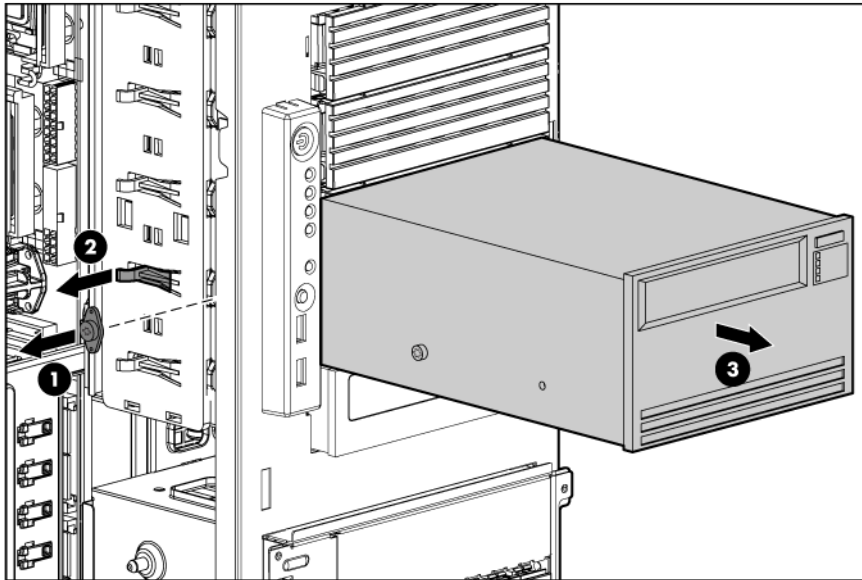


5. Remove the device:

- o Half-height



- Full-height



To replace the component, reverse the removal procedure.



IMPORTANT: Be sure to connect the right-angle end of the SATA data cable to the system board. Connecting it to the SATA drive may interfere with other installed media bay devices.



IMPORTANT: If both SATA and PATA optical devices are installed simultaneously, only one can boot at a time. Boot priority will go to SATA if media is inserted into the SATA optical drive. Boot priority for PATA is not configurable. To boot PATA, remove the media from the SATA optical device, or remove the SATA optical device.

DIMM

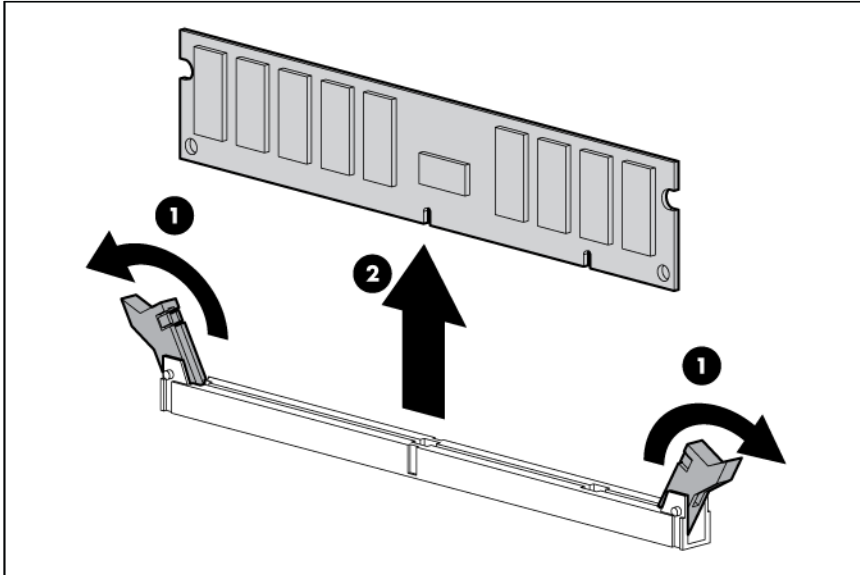


IMPORTANT: This server does not support mixing RDIMMs and UDIMMs. Attempting to mix these two types causes the server to halt during BIOS initialization.

To identify the DIMMs installed in the server, see "DIMM identification (on page 87)."

1. Power down the server (on page 27).
2. Do one of the following:
 - Unlock and remove the bezel ("Front bezel" on page 30).
 - Extend the server from the rack (on page 28).
3. Remove the access panel ("Access panel" on page 31).
4. Remove the large redundant fan air baffle, if installed ("Large redundant fan air baffle" on page 33).
5. Remove the DIMM baffles ("DIMM baffle" on page 34).
6. Remove a fan, if necessary ("Fan" on page 35).
7. Open the DIMM slot latches.

8. Remove the DIMM.



To replace the component, reverse the removal procedure.

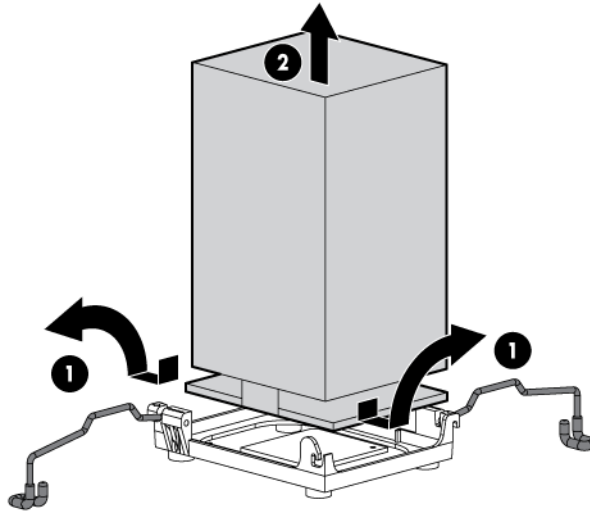
For DIMM configuration information, see the server user guide.

Heatsink

To remove the component:

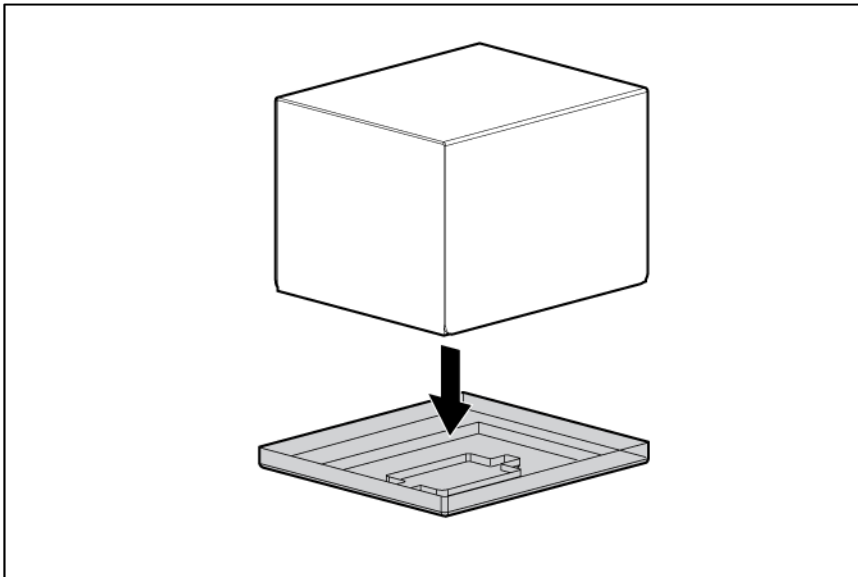
1. Power down the server (on page [27](#)).
2. Do one of the following:
 - o Open or remove the tower bezel, as needed ("[Front bezel](#)" on page [30](#)).
 - o Extend the server from the rack (on page [28](#)).
3. Place the tower server on its side.
4. Remove the access panel ("[Access panel](#)" on page [31](#)).
5. Remove the large redundant fan air baffle, if installed ("[Large redundant fan air baffle](#)" on page [33](#)).
6. Open the heatsink locking levers.

7. Remove the heatsink.



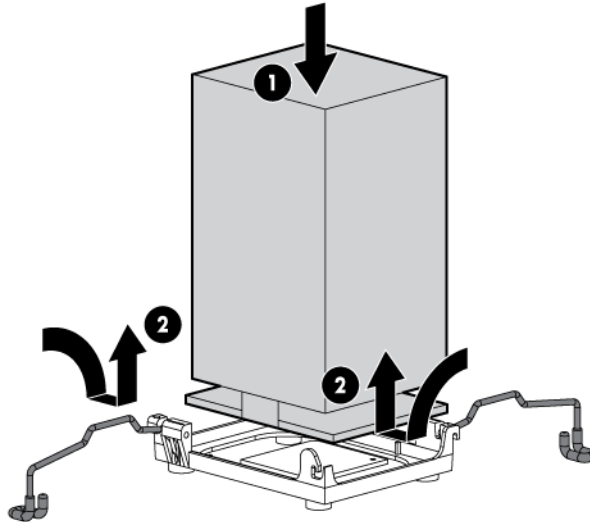
To replace the component:

1. Use the alcohol swab to remove all the existing thermal grease from the processor. Allow the alcohol to evaporate before continuing.
2. Remove the heatsink protective cover.



3. Install the heatsink.

4. Close the heatsink locking levers.



5. Install the large redundant fan air baffle, if removed.
6. Install the access panel.
7. Do one of the following:
 - o Close or install the tower bezel, as needed.
 - o Slide the server back into the rack.

Processor

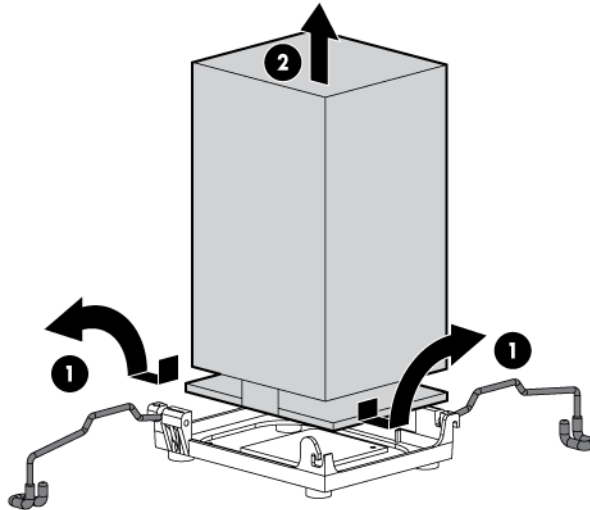
The server supports single- and dual-processor operation. With two processors installed, the server supports boot functions through the processor installed in processor socket 1. However, if processor 1 fails, then the system boots automatically from processor 2 and displays a processor failure message.

-
- △ **CAUTION:** To avoid damage to the processor and system board, only authorized personnel must replace or install the processor in this server.
-
- △ **CAUTION:** To help avoid damage to the processor and system board, do not install the processor without using the processor installation tool.
-
- △ **CAUTION:** To prevent possible server malfunction and damage to the equipment, multiprocessor configurations must contain processors with the same part number.
-

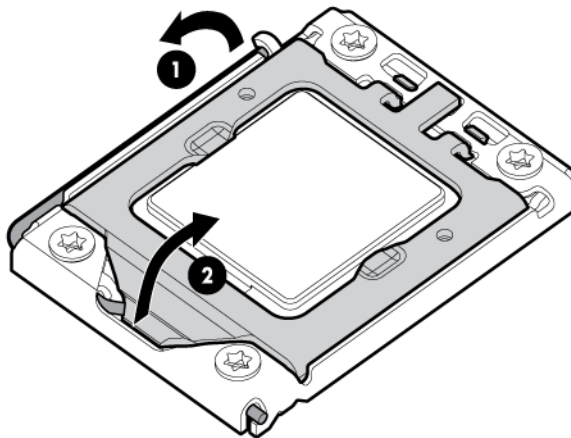
To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - o Open or remove the tower bezel, as needed ("Front bezel" on page 30).
 - o Extend the server from the rack (on page 28).
3. Place the tower server on its side.
4. Remove the access panel ("Access panel" on page 31).
5. Remove the large redundant fan air baffle, if installed ("Large redundant fan air baffle" on page 33).

6. Remove the heatsink.

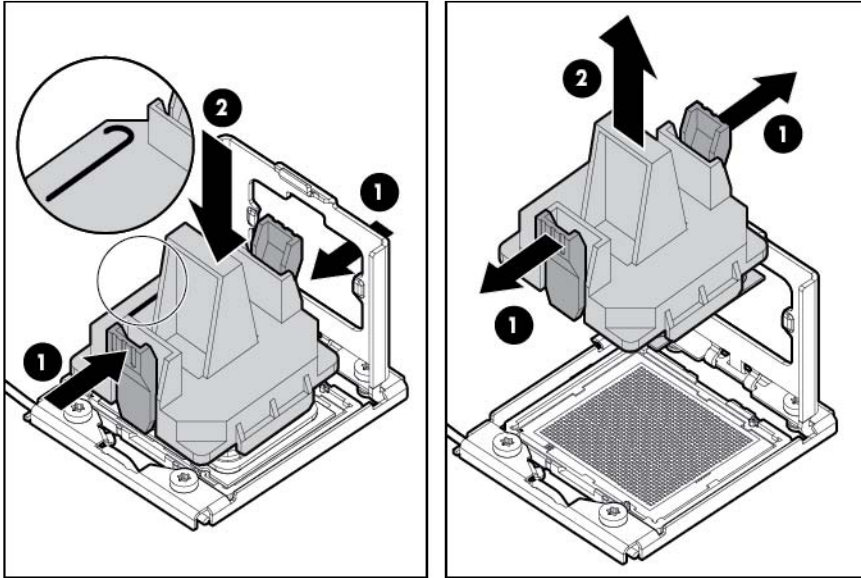


7. Open the processor locking lever and the processor socket retaining bracket.

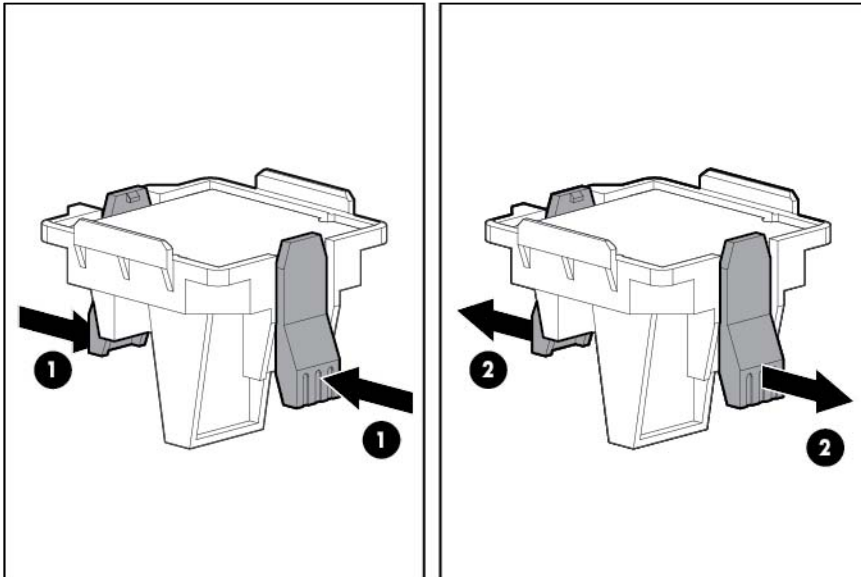


8. Using the processor tool, remove the processor from the system board:
 - a. Line up the processor tool, ensuring the locking lever graphic on the tool is oriented correctly.
 - b. Press in on the plastic tabs, and then place the tool on the processor.

- c. Release the tabs, and then carefully lift the processor and tool straight up.



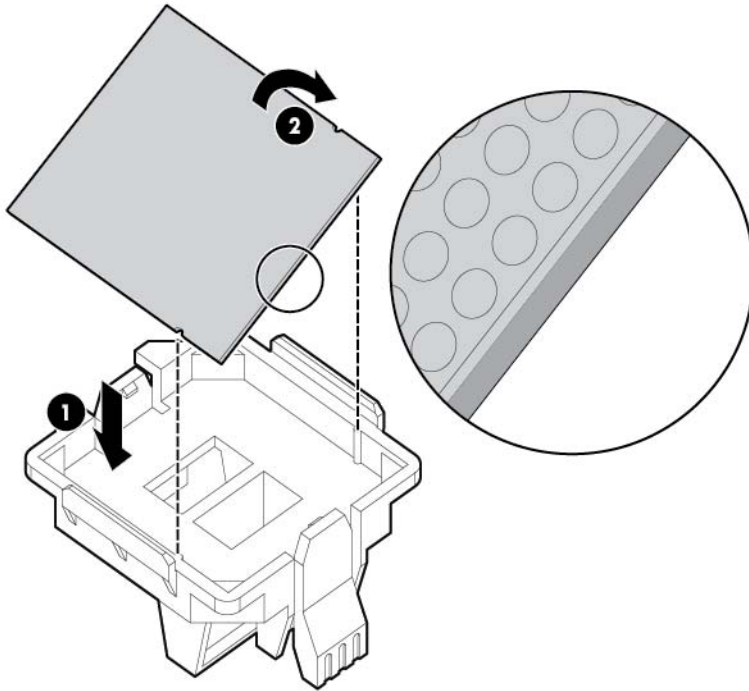
9. Carefully rotate the tool, and then push in and release the tabs to secure the processor in the tool.



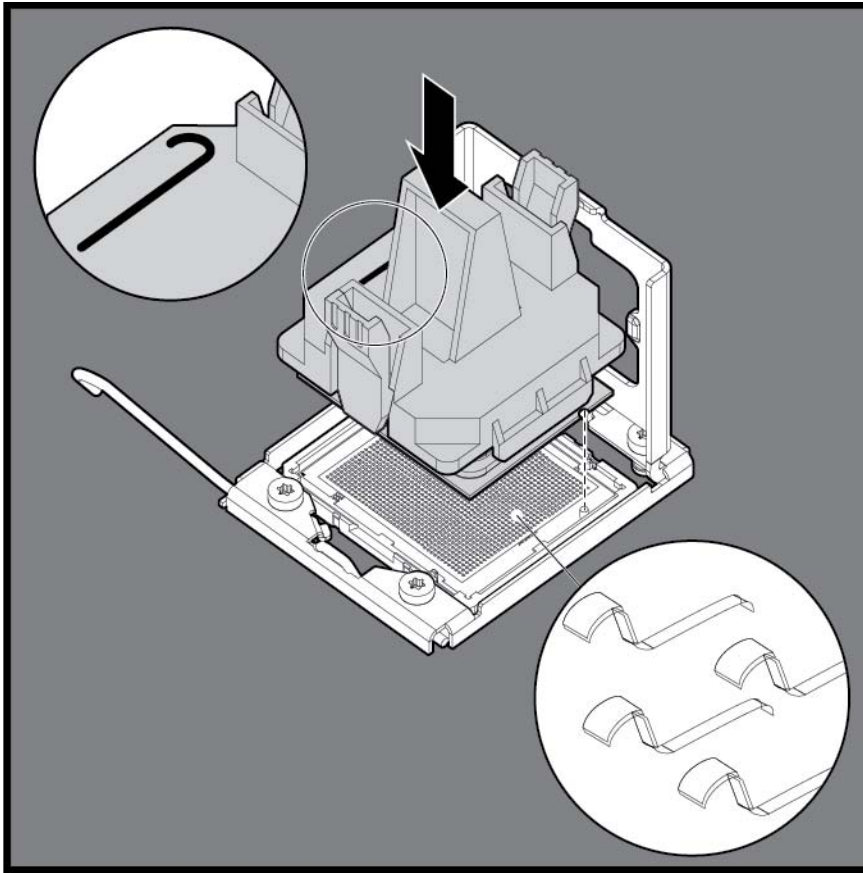
CAUTION: To avoid damage to the processor, do not touch the bottom of the processor, especially the contact area.

To replace a processor:

1. Carefully insert the processor into the processor installation tool. Handle the processor by the edges only, and do not touch the bottom of the processor, especially the contact area.



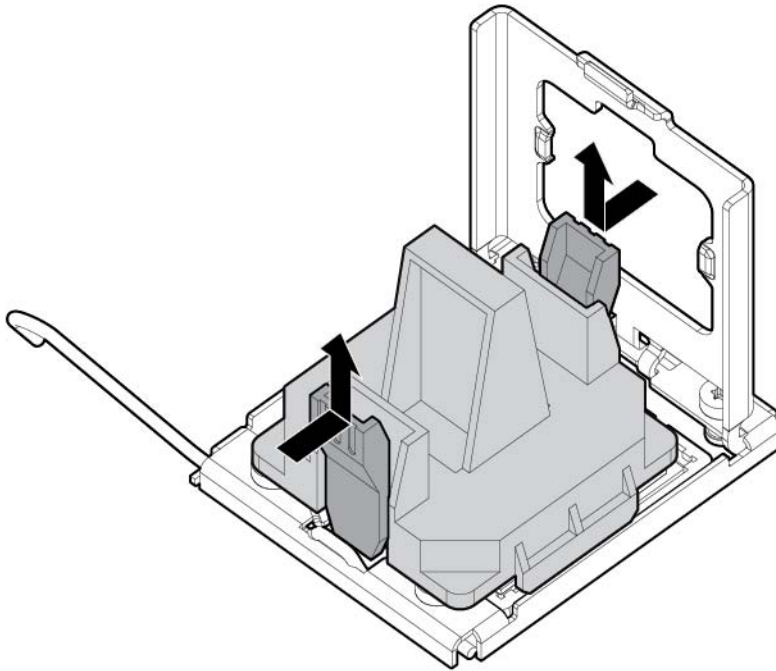
2. Be sure the tool is oriented correctly. Align the processor installation tool with the socket, and then install the processor. **THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED.**



CAUTION: THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED. To avoid damage to the system board:

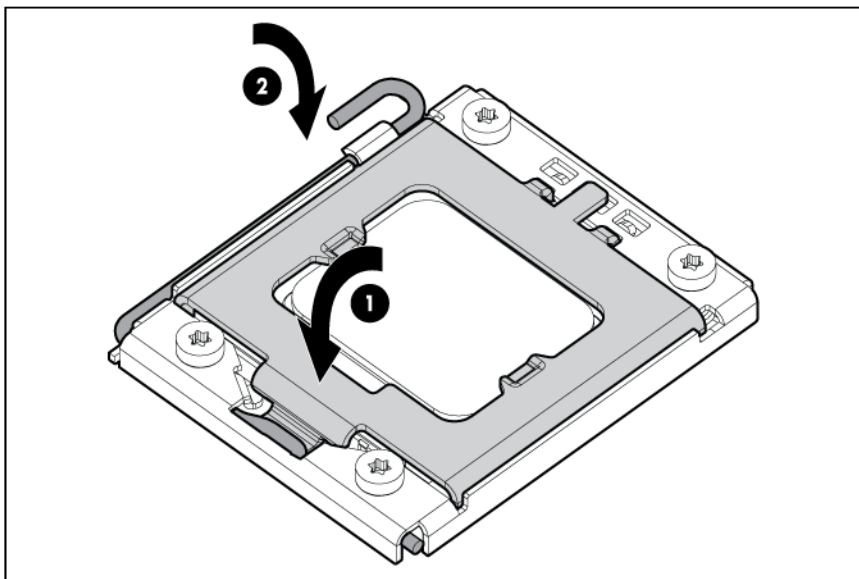
- Never install or remove a processor without using the processor installation tool.
- Do not touch the processor socket contacts.
- Do not tilt or slide the processor when lowering the processor into the socket.

3. Press and hold the tabs on the processor installation tool to separate it from the processor, and then remove the tool.



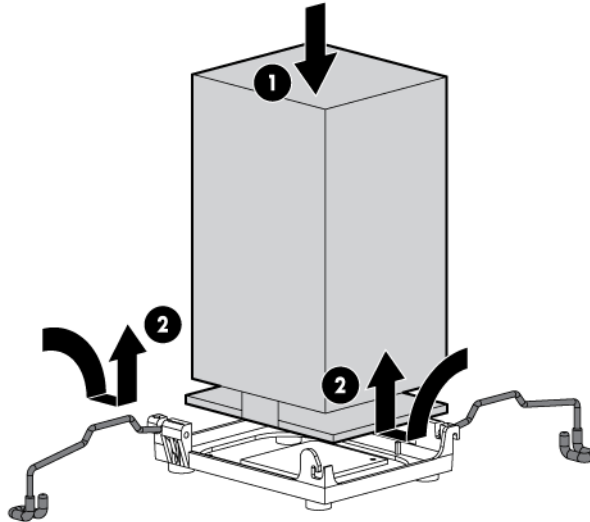
4. Close the processor socket retaining bracket and the processor locking lever.

⚠ CAUTION: Be sure to close the processor socket retaining bracket before closing the processor locking lever. The lever should close without resistance. Forcing the lever closed can damage the processor and socket, requiring system board replacement.



5. Install the heatsink.

6. Close the heatsink locking levers.



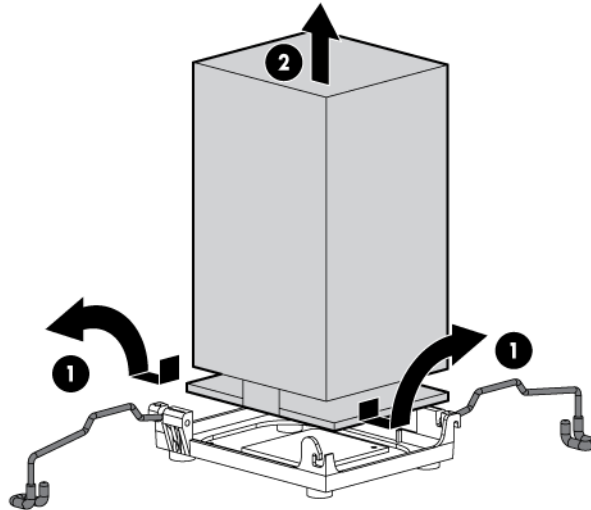
7. Install the large redundant fan air baffle, if removed.
8. Install the access panel.
9. Do one of the following:
 - o Close or install the tower bezel, as needed.
 - o Slide the server back into the rack.
10. Power up the server.

System board

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - o Open or remove the tower bezel, as needed ("[Front bezel](#)" on page 30).
 - o Extend the server from the rack (on page 28).
3. Remove the access panel ("[Access panel](#)" on page 31).
4. Disconnect all cables connected to the system board ("[System board components](#)" on page 83).
5. Remove all expansion boards ("[Expansion board](#)" on page 45).
6. Remove the large redundant fan air baffle, if installed ("[Large redundant fan air baffle](#)" on page 33).
7. Remove the DIMM baffles ("[DIMM baffle](#)" on page 34).
8. Remove all fans ("[Fan](#)" on page 35).
9. Remove all DIMMs ("[DIMM](#)" on page 56).
10. Remove the battery-backed write cache module, if installed ("[Battery-backed write cache module](#)" on page 47).

11. Remove the heatsink ("Heatsink" on page 57).



CAUTION: To avoid damage to the processor:

- Handle the processor only by the edges.
- Do not touch the bottom of the processor, especially the contact area.



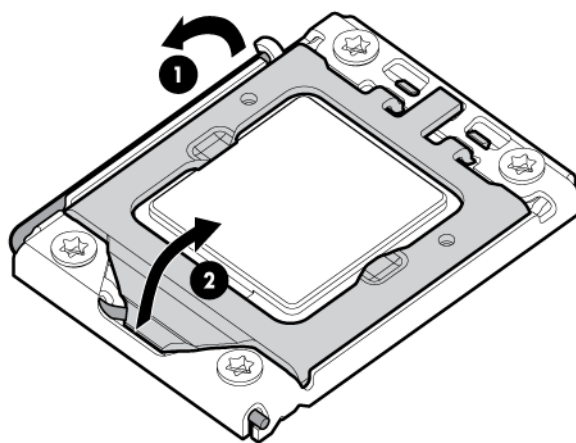
CAUTION: To avoid damage to the system board:

- Do not touch the processor socket contacts.
- Always install the processor socket cover after removing the processor from the socket.
- Do not tilt or slide the processor when lowering the processor into the socket.



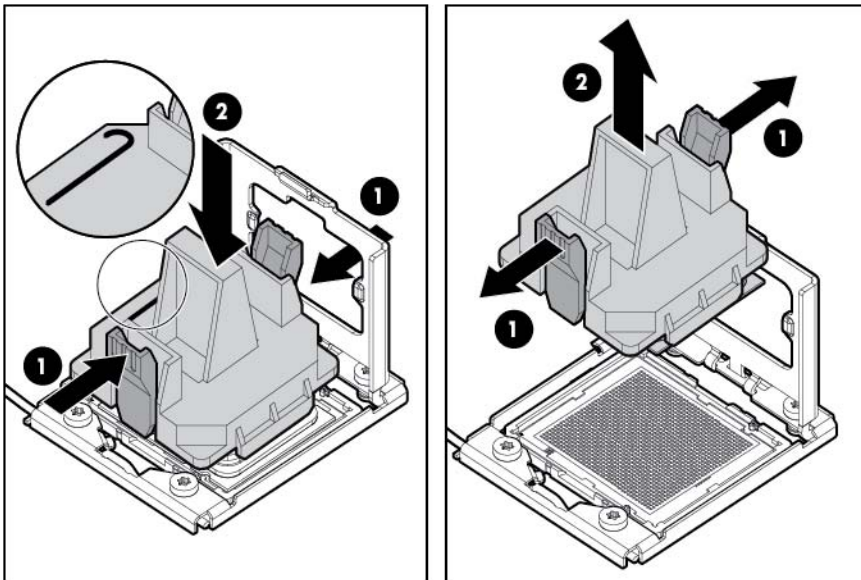
CAUTION: Removal of the processor or heatsink renders the thermal layer between the processor and heatsink useless. Clean the component with the provided alcohol swab, then add thermal grease.

12. Open the processor locking lever and the processor socket retaining bracket.

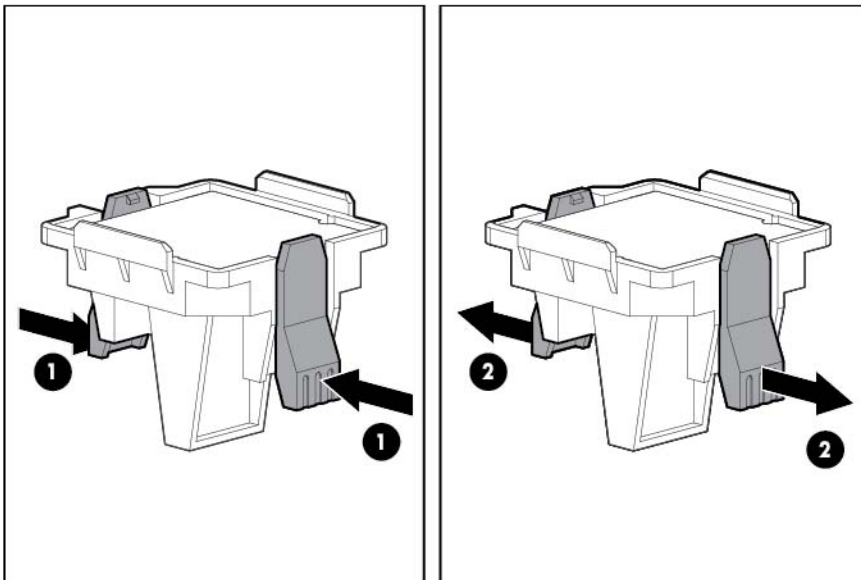


13. Using the processor tool, remove the processor from the system board:

- a. Line up the processor tool, ensuring the locking lever graphic on the tool is oriented correctly.
- b. Press in on the plastic tabs, and then place the tool on the processor.
- c. Release the tabs, and then carefully lift the processor and tool straight up.



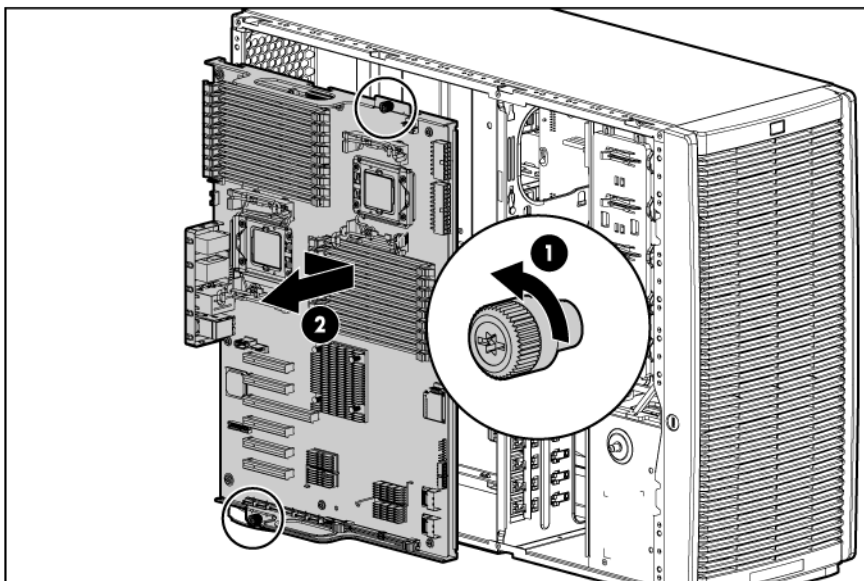
14. Carefully rotate the tool, and then push in and release the tabs to secure the processor in the tool.



CAUTION: To avoid damage to the processor, do not touch the bottom of the processor, especially the contact area.

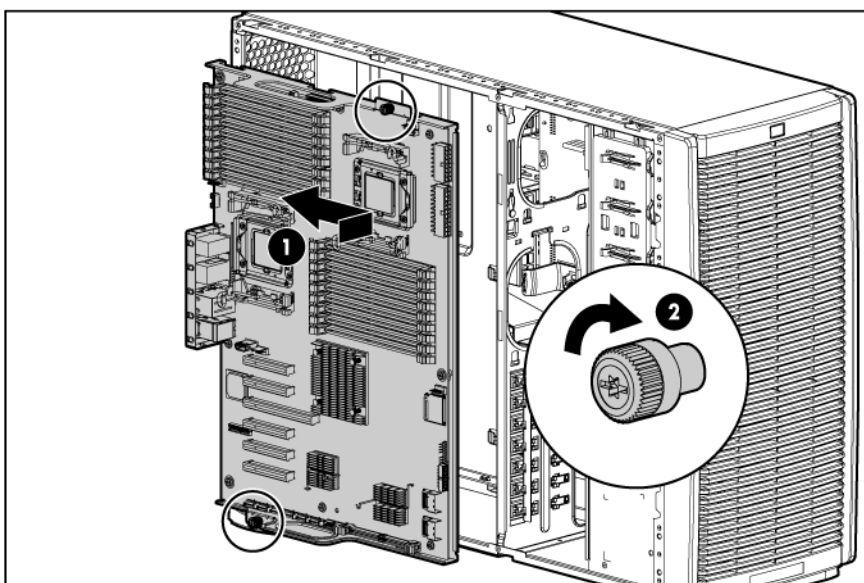
15. Loosen the two system board thumbscrews.

16. Using the system board tray handles, slide the tray forward and remove the failed system board.



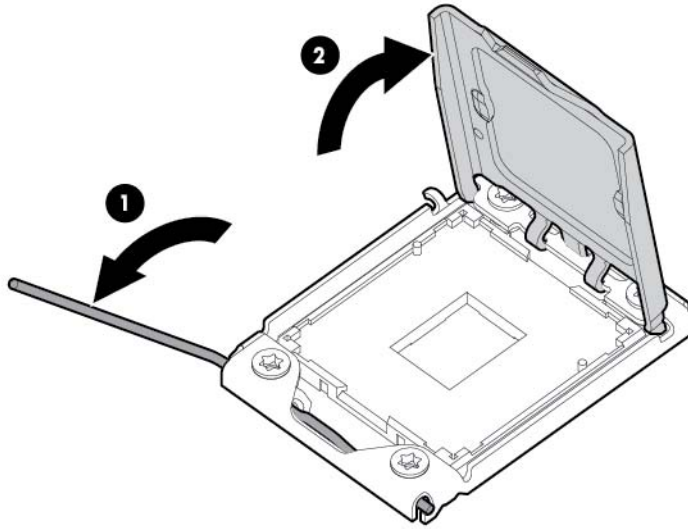
To replace the component:

1. Install the spare system board in the server before installing the processor.



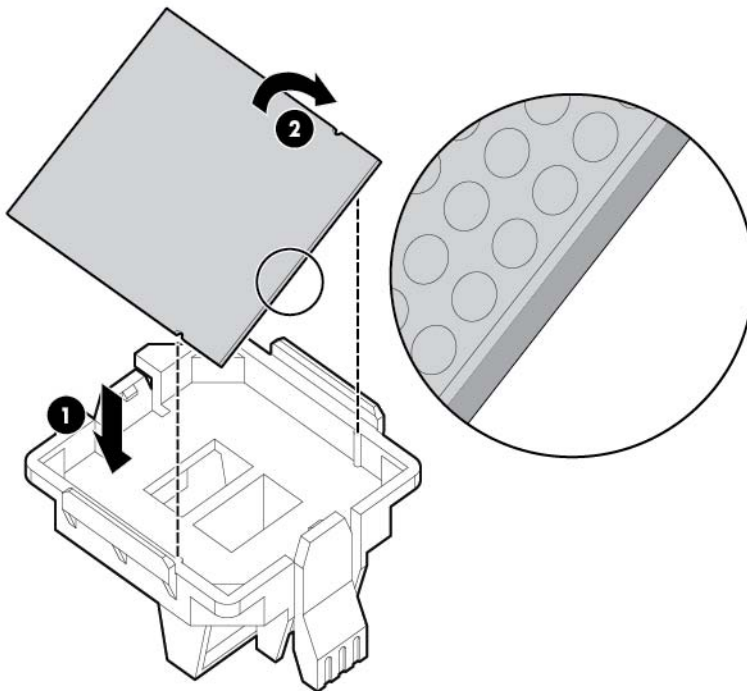
CAUTION: Failure to completely open the processor locking lever prevents the processor from seating during installation, leading to hardware damage.

2. Open the processor locking lever and the processor socket retaining bracket. **Do not remove the processor socket cover.**

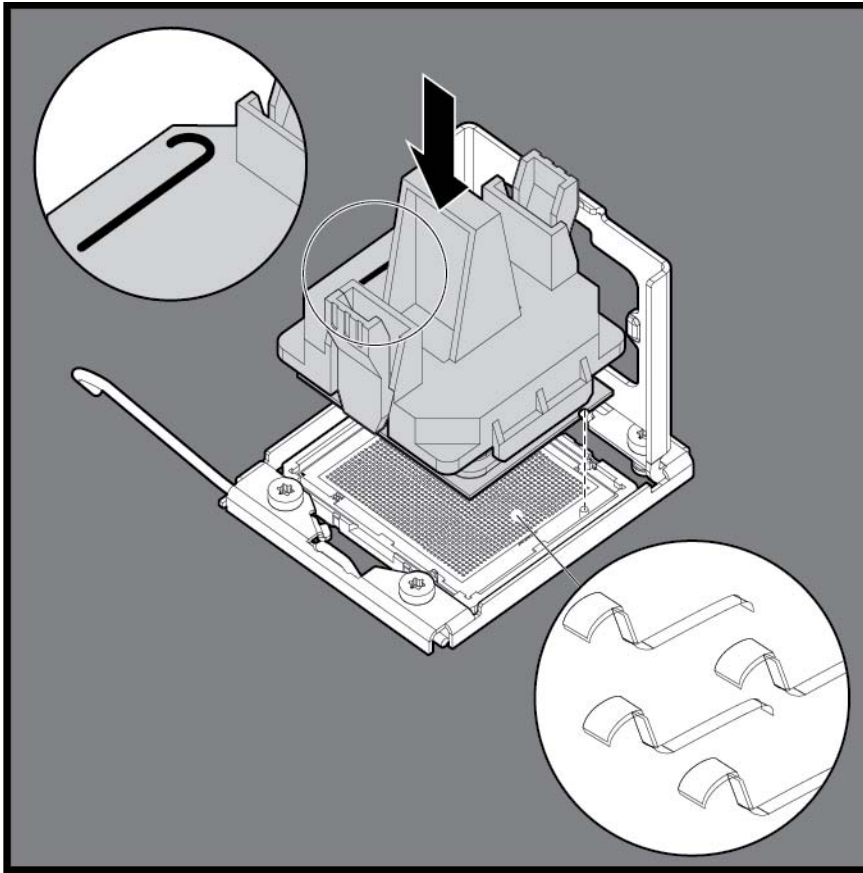


IMPORTANT: Be sure the processor remains inside the processor installation tool.

3. If the processor has separated from the installation tool, carefully re-insert the processor in the tool. Handle the processor by the edges only, and do not touch the bottom of the processor, especially the contact area.



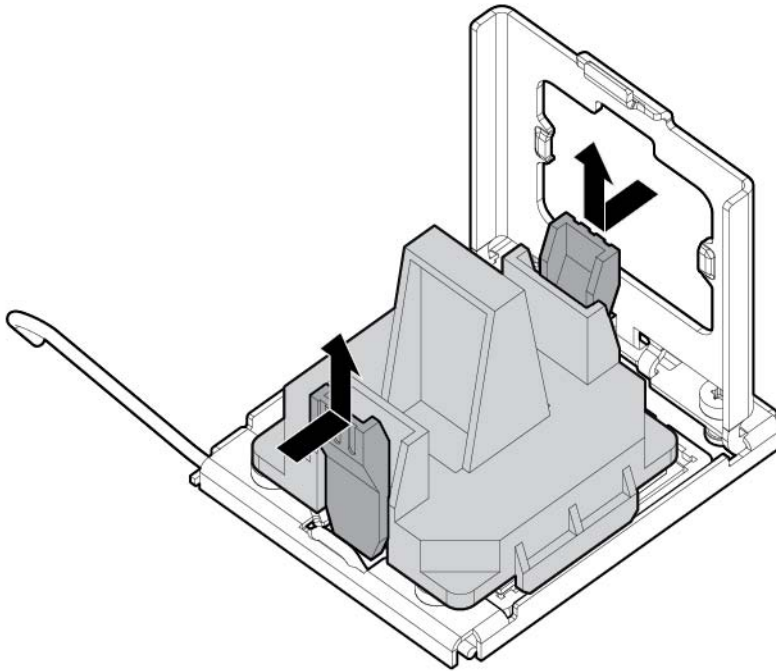
4. Align the processor installation tool with the socket, and then install the processor. **THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED.**



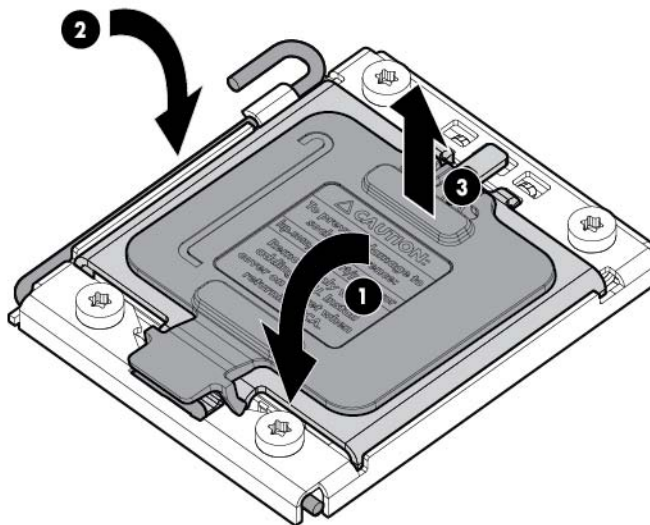
CAUTION: THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED. To avoid damage to the system board:

- Never install or remove a processor without using the processor installation tool.
- Do not touch the processor socket contacts.
- Do not tilt or slide the processor when lowering the processor into the socket.

5. Press the tabs on the processor installation tool to separate it from the processor, and then remove the tool.



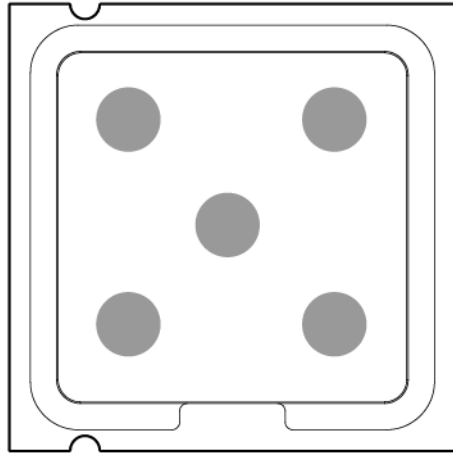
6. Close the processor socket retaining bracket and the processor locking lever. **The processor socket cover is automatically ejected.** Remove the cover.



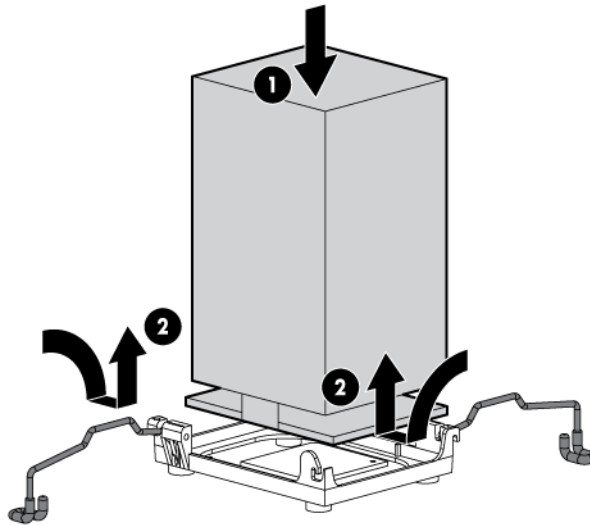
CAUTION: Be sure to close the processor socket retaining bracket before closing the processor locking lever. The lever should close without resistance. Forcing the lever closed can damage the processor and socket, requiring system board replacement.

7. Install the processor socket cover onto the processor socket of the failed system board.
8. Clean the old thermal grease from the heatsink and the top of the processor with the alcohol swab. Allow the alcohol to evaporate before continuing.

9. Apply all the grease to the top of the processor in the following pattern to ensure even distribution.



10. Install the heatsink.
11. Close the heatsink locking levers.



IMPORTANT: Install all components with the same configuration that was used on the failed system board.

12. Install all components removed from the failed system board.
13. Connect the cables to the system board.
14. Install the access panel.
15. Do one of the following:
 - Install and lock the bezel.
 - Slide the server back into the rack.
16. Power up the server.

After you replace the system board, you must re-enter the server serial number and the product ID.

1. During the server startup sequence, press the **F9** key to access RBSU.

2. Select the **Advanced Options** menu.
3. Select **Service Options**.
4. Select **Serial Number**. The following warnings appear:
WARNING! WARNING! WARNING! The serial number is loaded into the system during the manufacturing process and should NOT be modified. This option should only be used by qualified service personnel. This value should always match the serial number sticker located on the chassis.
Warning: The serial number should ONLY be modified by qualified personnel. This value should always match the serial number located on the chassis.
5. Press the **Enter** key to clear the warning.
6. Enter the serial number and press the **Enter** key.
7. Select **Product ID**. The following warning appears:
Warning: The Product ID should ONLY be modified by qualified personnel. This value should always match the Product ID on the chassis.
8. Enter the product ID and press the **Enter** key.
9. Press the **Esc** key to close the menu.
10. Press the **Esc** key to exit RBSU.
11. Press the **F10** key to confirm exiting RBSU. The server automatically reboots.

Power supply backplane

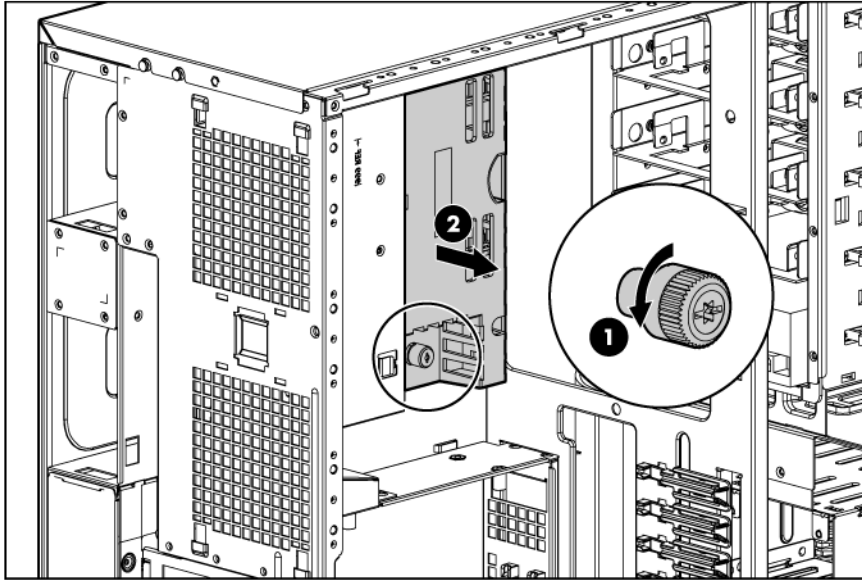
To remove the component:

1. Power down the server (on page 27).
2. Remove the power supplies ("[Hot-plug power supply](#)" on page 37).
3. Do one of the following:
 - o Unlock and remove the bezel ("[Front bezel](#)" on page 30).
 - o Extend the server from the rack (on page 28).
4. Remove the access panel ("[Access panel](#)" on page 31).
5. Remove the large redundant fan air baffle ("[Large redundant fan air baffle](#)" on page 33).
6. Remove the DIMM baffles ("[DIMM baffle](#)" on page 34).
7. Remove all fans ("[Fan](#)" on page 35).
8. Remove all expansion boards ("[Expansion board](#)" on page 45).
9. Remove the system board ("[System board](#)" on page 65).

For this procedure, removing the processors, heatsinks, DIMMs, and cache module from the system board is not required.

10. Disconnect the cables from the power supply backplane.

11. Remove the power supply backplane.



To replace the component, reverse the removal procedure.

Battery

If the server no longer automatically displays the correct date and time, you may need to replace the battery that provides power to the real-time clock. Under normal use, battery life is 5 to 10 years.



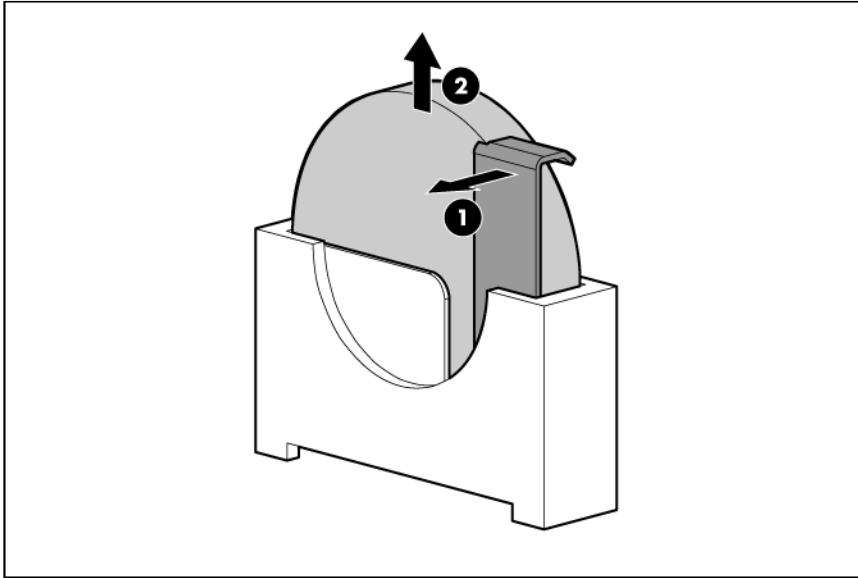
WARNING: The computer contains an internal lithium manganese dioxide, a vanadium pentoxide, or an alkaline battery pack. A risk of fire and burns exists if the battery pack is not properly handled. To reduce the risk of personal injury:

- Do not attempt to recharge the battery.
- Do not expose the battery to temperatures higher than 60°C (140°F).
- Do not disassemble, crush, puncture, short external contacts, or dispose of in fire or water.
- Replace only with the spare designated for this product.

To remove the component:

1. Power down the server (on page 27).
2. Do one of the following:
 - Open or remove the tower bezel, as needed ("Front bezel" on page 30).
 - Extend the server from the rack (on page 28).
3. Remove the access panel ("Access panel" on page 31).

4. Remove the battery.



IMPORTANT: Replacing the system board battery resets the system ROM to its default configuration. After replacing the battery, reconfigure the system through RBSU.

To replace the component, reverse the removal procedure.

For more information about battery replacement or proper disposal, contact an authorized reseller or an authorized service provider.

HP Trusted Platform Module

The TPM is not a customer-removable part.



CAUTION: Any attempt to remove an installed TPM from the system board breaks or disfigures the TPM security rivet. Upon locating a broken or disfigured rivet on an installed TPM, administrators should consider the system compromised and take appropriate measures to ensure the integrity of the system data.

If you suspect a TPM board failure, leave the TPM installed and remove the system board ("[System board](#)" on page [65](#)). Contact an HP authorized service provider for a replacement system board and TPM board.

Diagnostic tools

Troubleshooting resources

The *HP ProLiant Servers Troubleshooting Guide* provides procedures for resolving common problems and comprehensive courses of action for fault isolation and identification, error message interpretation, issue resolution, and software maintenance on ProLiant servers and server blades. This guide includes problem-specific flowcharts to help you navigate complex troubleshooting processes. To view the guide, select a language:

- English (http://www.hp.com/support/ProLiant_TSG_en)
- French (http://www.hp.com/support/ProLiant_TSG_fr)
- Italian (http://www.hp.com/support/ProLiant_TSG_it)
- Spanish (http://www.hp.com/support/ProLiant_TSG_sp)
- German (http://www.hp.com/support/ProLiant_TSG_gr)
- Dutch (http://www.hp.com/support/ProLiant_TSG_nl)
- Japanese (http://www.hp.com/support/ProLiant_TSG_jp)

HP ROM-Based Setup Utility

RBSU is a configuration utility embedded in ProLiant servers that performs a wide range of configuration activities that can include the following:

- Configuring system devices and installed options
- Enabling and disabling system features
- Displaying system information
- Selecting the primary boot controller
- Configuring memory options
- Language selection

For more information on RBSU, see the *HP ROM-Based Setup Utility User Guide* on the Documentation CD or the HP website (<http://www.hp.com/support/smartstart/documentation>).

HP Insight Diagnostics

HP Insight Diagnostics is a proactive server management tool, available in both offline and online versions, that provides diagnostics and troubleshooting capabilities to assist IT administrators who verify server installations, troubleshoot problems, and perform repair validation.

HP Insight Diagnostics Offline Edition performs various in-depth system and component testing while the OS is not running. To run this utility, launch the SmartStart CD.

HP Insight Diagnostics Online Edition is a web-based application that captures system configuration and other related data needed for effective server management. Available in Microsoft® Windows® and Linux versions, the utility helps to ensure proper system operation.

For more information or to download the utility, refer to the HP website (<http://www.hp.com/servers/diags>).

HP Insight Diagnostics survey functionality

HP Insight Diagnostics (on page 76) provides survey functionality that gathers critical hardware and software information on ProLiant servers.

This functionality supports operating systems that may not be supported by the server. For operating systems supported by the server, see the HP website (<http://www.hp.com/go/supportos>).

If a significant change occurs between data-gathering intervals, the survey function marks the previous information and overwrites the survey data files to reflect the latest changes in the configuration.

Survey functionality is installed with every SmartStart-assisted HP Insight Diagnostics installation, or it can be installed through the HP PSP.

NOTE: The current version of SmartStart provides the memory spare part numbers for the server. To download the latest version, see the HP website (<http://www.hp.com/support>).

Integrated Management Log

The IML records hundreds of events and stores them in an easy-to-view form. The IML timestamps each event with 1-minute granularity.

You can view recorded events in the IML in several ways, including the following:

- From within HP SIM
- From within Survey Utility
- From within operating system-specific IML viewers
 - For NetWare: IML Viewer
 - For Windows®: IML Viewer
 - For Linux: IML Viewer Application
- From within the iLO 2 user interface
- From within HP Insight Diagnostics (on page 76)

For more information, see the Management CD in the HP Insight Foundation suite for ProLiant.

Array Diagnostic Utility

The HP Array Diagnostics Utility is a web-based application that creates a report of all HP storage controllers and disk drives. This report provides vital information to assist in identifying faults or conditions that may require attention. ADU can be accessed from the SmartStart CD or downloaded from the HP website (<http://www.hp.com>).

HP Insight Remote Support software

HP strongly recommends that you install HP Insight Remote Support software to complete the installation or upgrade of your product and to enable enhanced delivery of your HP Warranty, HP Care Pack Service, or HP contractual support agreement. HP Insight Remote Support supplements your monitoring 24 x 7 to ensure maximum system availability by providing intelligent event diagnosis, and automatic, secure submission of hardware event notifications to HP, which will initiate a fast and accurate resolution, based on your product's service level. Notifications may be sent to your authorized HP Channel Partner for on-site service, if configured and available in your country. The software is available in two variants:

- **HP Insight Remote Support Standard:** This software supports server and storage devices and is optimized for environments with 1–50 servers. Ideal for customers who can benefit from proactive notification but do not need proactive service delivery and integration with a management platform.
- **HP Insight Remote Support Advanced:** This software provides comprehensive remote monitoring and proactive service support for nearly all HP servers, storage, network, and SAN environments, plus selected non-HP servers that have a support obligation with HP. It is integrated with HP Systems Insight Manager. A dedicated server is recommended to host both HP Systems Insight Manager and HP Insight Remote Support Advanced.

Details for both versions are available on the HP website (<http://www.hp.com/go/insightremotesupport>).

To download the software, go to Software Depot (<http://www.software.hp.com>).

Select **Insight Remote Support** from the menu on the right.

HP Insight Server Migration software for ProLiant

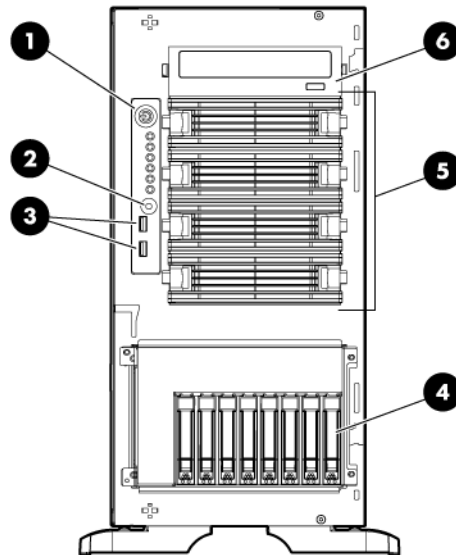
The HP Insight Server Migration software for ProLiant (SMP) enables administrators to upgrade or replace an existing server through server migration. SMP provides an automated, accurate, and affordable method of migrating existing servers and their content to the latest server technologies.

SMP automates the migration of the operating system, applications, and data from one server to another without errors, eliminating the need for manual redeployment of these elements on the new server. During the migration process, the software automatically loads new drivers, required for boot, on the destination server. The wizard-based user interface simplifies the migration process and requires little experience or training.

For more information about the SMP, see the HP website (<http://www.hp.com/go/migrate>).

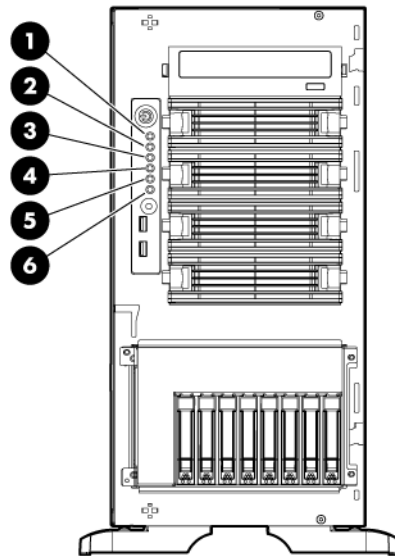
Component identification

Front panel components



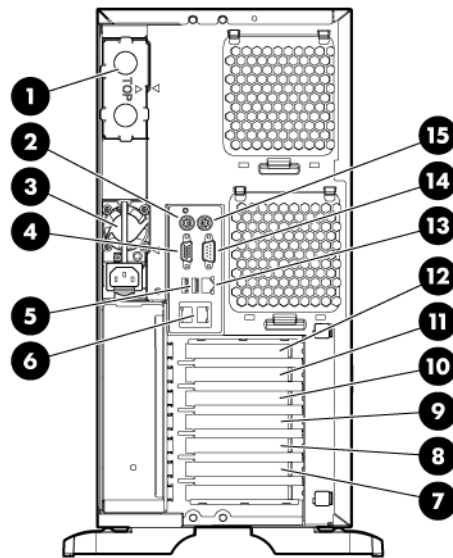
Item	Description
1	Power On/Standby button
2	UID button
3	USB connectors (2)
4	Hot-plug hard drive bays (8-bay SFF drive cage model)
5	Removable media bays
6	Optical drive

Front panel LEDs and buttons



Item	Description	Status
1	System power LED	Green = Power on Flashing green = Waiting for power due to group power capping Amber = System in standby, but power still applied Off = Power cord not attached or power supply failure
2	Health LED	Green = Normal Amber = System degraded. To identify the component in a degraded state, see the system board LEDs (on page 85). Red = System critical. To identify the component in a critical state, see the system board LEDs (on page 85). Off = Normal (when in standby mode)
3	Power cap LED	Green = Power cap configured Flashing amber = Power cap exceeded Off = Server in standby or power cap disabled
4	NIC 1 activity LED	Green = Network link Flashing = Network link and activity Off = No link to network. If power is off, view status on the rear panel RJ-45 LEDs (" Rear panel LEDs and buttons " on page 82).
5	NIC 2 activity LED	Green = Network link Flashing = Network link and activity Off = No link to network. If power is off, view status on the rear panel RJ-45 LEDs (" Rear panel LEDs and buttons " on page 82).
6	UID LED	Blue = Activated Flashing = System managed remotely Off = Deactivated

Rear panel components



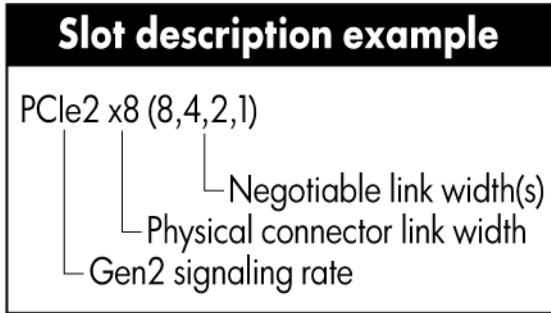
Item	Description
1	Power supply bay 2
2	Keyboard connector
3	Power supply bay 1 (populated)
4	Video connector
5	USB connectors (2)
6	RJ-45 Ethernet connectors (2)
7	Slot 1 PCIe2 x8 (4, 2, 1) ¹
8	Slot 2 PCIe2 x8 (4, 2, 1) ²
9	Slot 3 PCIe2 x8 (8, 4, 2, 1) ³
10	Slot 4 PCIe2 x16 (8, 4, 2, 1) 75W +EXT 75W ⁴
11	Slot 5 PCIe2 x8 (4, 2, 1)
12	Slot 6 PCIe2 x8 (4, 2, 1)
13	RJ-45 Ethernet connector (dedicated iLO 2 management)
14	Serial connector
15	Mouse connector

¹The SAS expander and the HP NC522SFP Dual Port 10GbE Server Adapter are not supported in slot 1.

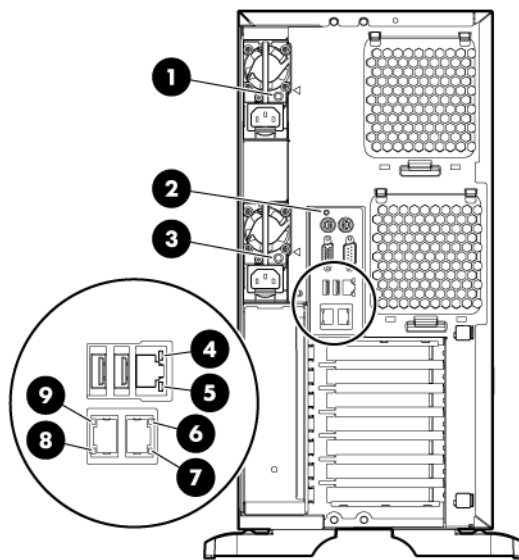
²HP recommends the SAS expander is installed in slot 2.

³The HP NC522SFP Dual Port 10GbE Server Adapter is only supported in slot 3.

⁴To support options beyond 75W, install the 150W PCIe video/graphics controller power cable option.



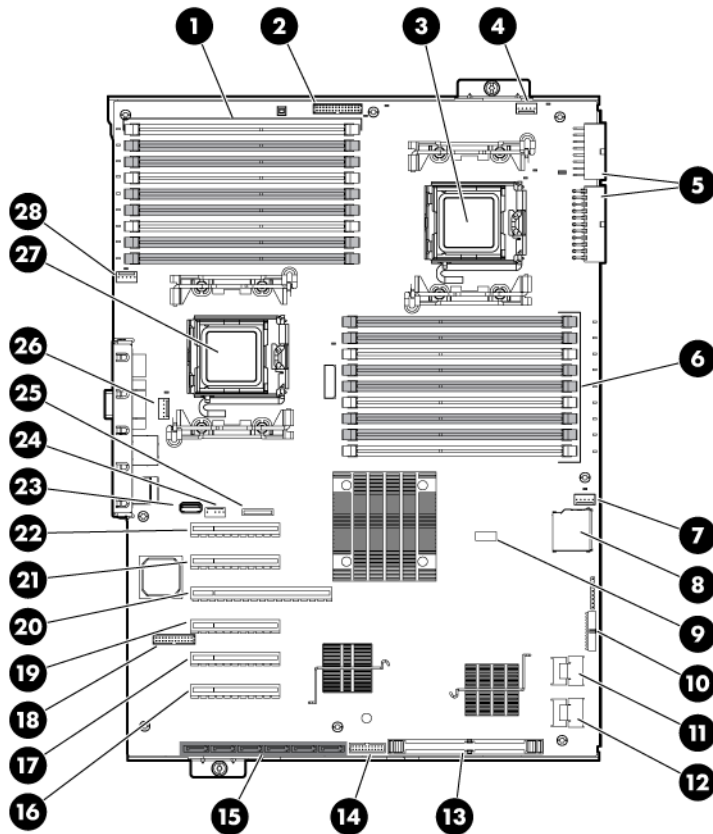
Rear panel LEDs and buttons



Item	Description	Status
1	Power supply 2 LED	Green = Power supply is on and functioning. Off = AC power is not available or AC power supply has failed.
2	UID LED	Blue = Activated Flashing blue = System managed remotely Off = Deactivated
3	Power supply 1 LED	Green = Power supply is on and functioning. Off = AC power is not available or AC power supply has failed.
4	iLO 2 link LED	Green = Linked to network Off = Not linked to network
5	iLO 2 activity LED	Green or flashing = Network activity Off = No network activity
6	NIC 2 link LED	Green = Linked to network Off = Not linked to network
7	NIC 2 activity LED	Green or flashing = Network activity Off = No network activity

Item	Description	Status
8	NIC 1 link LED	Green = Linked to network Off = Not linked to network
9	NIC 1 activity LED	Green or flashing = Network activity Off = No network activity

System board components



Item	Description
1	Processor 1 DIMM slots
2	Power supply backplane connector
3	Processor socket 2
4	System fan 4 connector
5	System power connectors
6	Processor 2 DIMM slots
7	System fan 3 connector
8	SD card slot (non-hot-plug)
9	System maintenance switch
10	Front panel LED board connector
11	SAS connector B
12	SAS connector A
13	HP Smart Array P410i memory connector

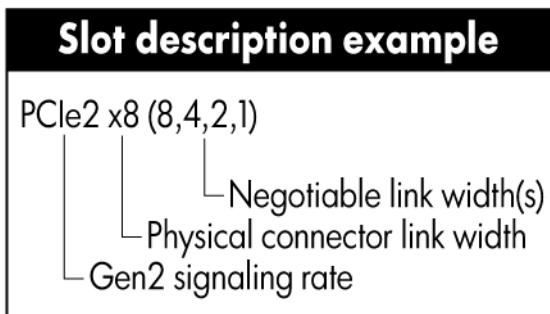
Item	Description
14	TPM connector
15	SATA connectors (6)
16	Slot 1 PCIe2 x8 (4, 2, 1) ¹
17	Slot 2 PCIe2 x8 (4, 2, 1) ²
18	10Gb sideband connector (MII 24-pin)
19	Slot 3 PCIe2 x8 (8, 4, 2, 1) ³
20	Slot 4 PCIe2 x16 (8, 4, 2, 1) 75W +EXT 75W ⁴
21	Slot 5 PCIe2 x8 (4, 2, 1)
22	Slot 6 PCIe2 x8 (4, 2, 1)
23	Internal USB connector
24	Internal USB tape connector
25	System battery
26	System fan 2 connector
27	Processor socket 1
28	System fan 1 connector

¹The SAS expander and the HP NC522SFP Dual Port 10GbE Server Adapter are not supported in slot 1.

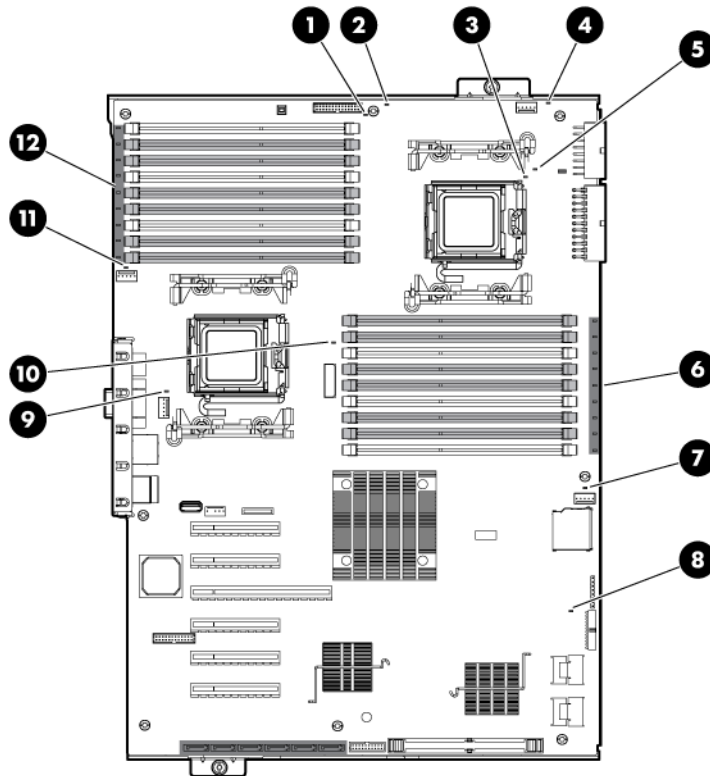
²HP recommends the SAS expander is installed in slot 2.

³The HP NC522SFP Dual Port 10GbE Server Adapter is only supported in slot 3.

⁴To support options beyond 75W, install the 150W PCIe video/graphics controller power cable option.



System board LEDs



Item	Description	Status
1	Power supply 1	Amber = No AC power or failed power supply Off = Power supply is on and functioning.
2	Power supply 2	Amber = No AC power or failed power supply Off = Power supply is on and functioning.
3	Processor 2	Amber = Processor 2 failed. Off = Processor 2 is functioning.
4	System fan 4	Amber = Fan is missing or has failed. Off = Fan is functioning.
5	AMP status	Green = AMP mode is enabled. Amber = Failover has occurred, or the configuration is not valid. Off = AMP mode is disabled.
6	Processor 2 DIMMs	Amber = An error has occurred. Off = Normal operation
7	System fan 3	Amber = Fan is missing or has failed. Off = Fan is functioning.
8	Overtemperature	Amber = System temperature threshold exceeded Off = Normal operation
9	System fan 2	Amber = Fan is missing or has failed. Off = Fan is functioning.

Item	Description	Status
10	Processor 1	Amber = Processor 1 failed. Off = Processor 1 is functioning.
11	System fan 1	Amber = Fan is missing or has failed. Off = Fan is functioning.
12	Processor 1 DIMMs	Amber = An error has occurred. Off = Normal operation

System maintenance switch

Position	Default	Function
S1	Off	Off = iLO 2 security is enabled. On = iLO 2 security is disabled.
S2	Off	Off = System configuration can be changed. On = System configuration is locked.
S3	Off	Reserved
S4	Off	Reserved
S5	Off	Off = Power-on password is enabled. On = Power-on password is disabled.
S6	Off	Off = No function On = Clear NVRAM
S7	—	Reserved
S8	—	Reserved
S9	—	Reserved
S10	—	Reserved

When the system maintenance switch position 6 is set to the On position, the system is prepared to erase all system configuration settings from both CMOS and NVRAM.



CAUTION: Clearing CMOS and/or NVRAM deletes configuration information. Be sure to properly configure the server or data loss could occur.

NMI functionality

An NMI crash dump enables administrators to create crash dump files when a system is hung and not responding to traditional debug mechanisms.

Crash dump log analysis is an essential part of diagnosing reliability problems, such as hangs in operating systems, device drivers, and applications. Many crashes freeze a system, and the only available action for administrators is to cycle the system power. Resetting the system erases any information that could support problem analysis, but the NMI feature preserves that information by performing a memory dump before a hard reset.

To force the OS to invoke the NMI handler and generate a crash dump log, the administrator can do any of the following:

- Short the NMI jumper pins
- Press the NMI switch

- Use the iLO Virtual NMI feature

For additional information, see the whitepaper on the HP website

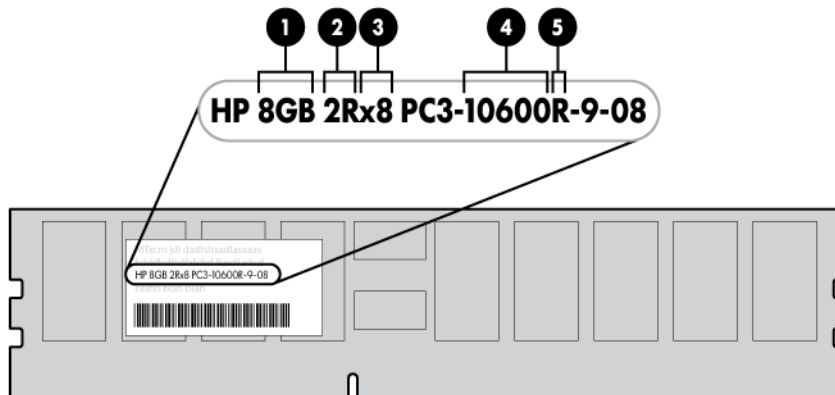
(<http://h20000.www2.hp.com/bc/docs/support/SupportManual/c00797875/c00797875.pdf>).

DIMM identification



IMPORTANT: This server does not support mixing RDIMMs and UDIMMs. Attempting to mix these two types causes the server to halt during BIOS initialization.

The memory subsystem may be populated with either RDIMMs or UDIMMs, but mixing the two types is not supported. To determine DIMM characteristics, use the label attached to the DIMM and the following illustration and table.

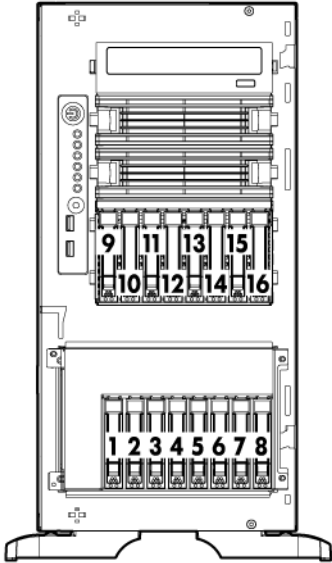


Item	Description	Definition
1	Size	—
2	Rank	1R = Single-rank 2R = Dual-rank 4R = Quad-rank
3	Data width	x4 = 4-bit x8 = 8-bit
4	Memory speed	10600 = 1333-MHz 8500 = 1066-MHz
5	DIMM type	R = RDIMM (registered) E = UDIMM (unbuffered with ECC)

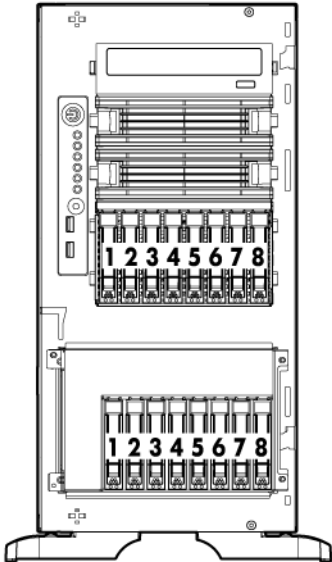
For the latest supported memory information, see the QuickSpecs on the HP website (<http://www.hp.com>).

SAS/SATA device numbers

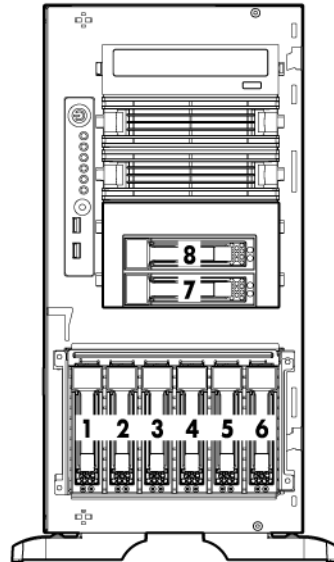
- SFF configuration with an optional SAS expander



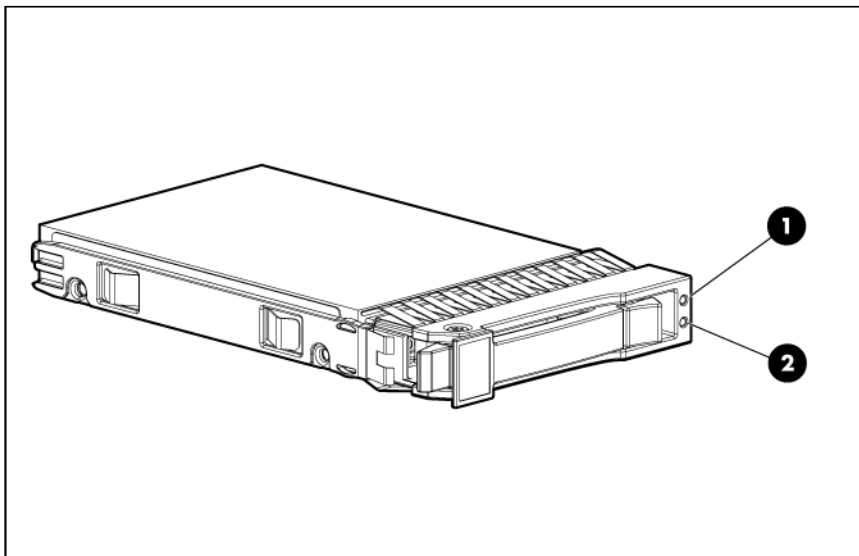
- SFF configuration with a second SAS controller



- LFF configuration



SAS and SATA hard drive LEDs

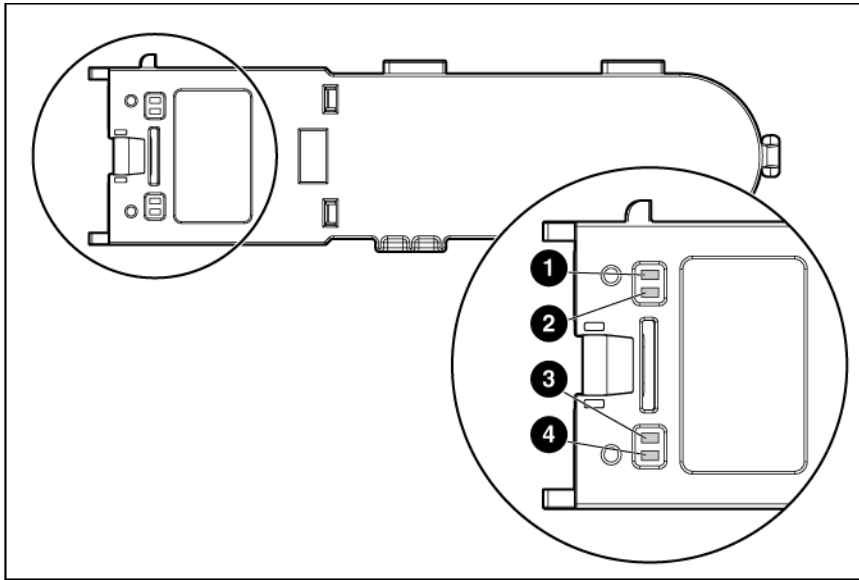


Item	Description
1	Fault/UID LED (amber/blue)
2	Online LED (green)

SAS and SATA hard drive LED combinations

Online/activity LED (green)	Fault/UID LED (amber/blue)	Interpretation
On, off, or flashing	Alternating amber and blue	The drive has failed, or a predictive failure alert has been received for this drive; it also has been selected by a management application.
On, off, or flashing	Steadily blue	The drive is operating normally, and it has been selected by a management application.
On	Amber, flashing regularly (1 Hz)	A predictive failure alert has been received for this drive. Replace the drive as soon as possible.
On	Off	The drive is online, but it is not active currently.
Flashing regularly (1 Hz)	Amber, flashing regularly (1 Hz)	Do not remove the drive. Removing a drive may terminate the current operation and cause data loss. The drive is part of an array that is undergoing capacity expansion or stripe migration, but a predictive failure alert has been received for this drive. To minimize the risk of data loss, do not replace the drive until the expansion or migration is complete.
Flashing regularly (1 Hz)	Off	Do not remove the drive. Removing a drive may terminate the current operation and cause data loss. The drive is rebuilding, erasing, or it is part of an array that is undergoing capacity expansion or stripe migration.
Flashing irregularly	Amber, flashing regularly (1 Hz)	The drive is active, but a predictive failure alert has been received for this drive. Replace the drive as soon as possible.
Flashing irregularly	Off	The drive is active, and it is operating normally.
Off	Steadily amber	A critical fault condition has been identified for this drive, and the controller has placed it offline. Replace the drive as soon as possible.
Off	Amber, flashing regularly (1 Hz)	A predictive failure alert has been received for this drive. Replace the drive as soon as possible.
Off	Off	The drive is offline, a spare, or not configured as part of an array.

Battery pack LEDs



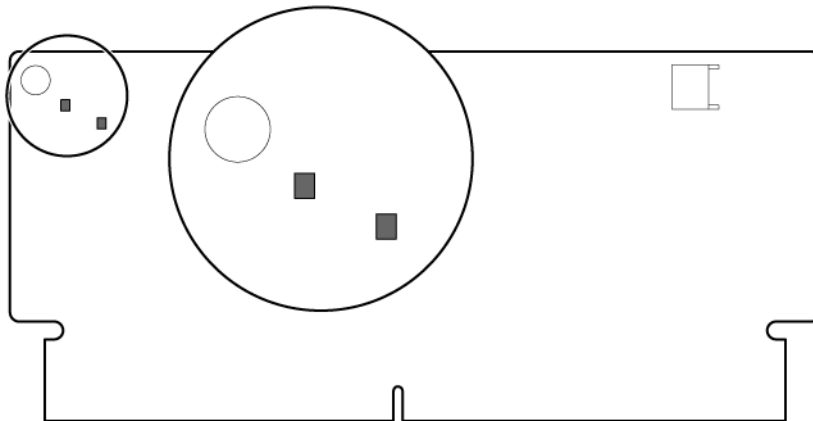
Item ID	Color	Description
1	Green	System Power LED. This LED glows steadily when the system is powered up and 12 V system power is available. This power supply is used to maintain the battery charge and provide supplementary power to the cache microcontroller.
2	Green	Auxiliary Power LED. This LED glows steadily when 3.3V auxiliary voltage is detected. The auxiliary voltage is used to preserve BBWC data and is available any time that the system power cords are connected to a power supply.
3	Amber	Battery Health LED. To interpret the illumination patterns of this LED, see the following table.
4	Green	BBWC Status LED. To interpret the illumination patterns of this LED, see the following table.

LED3 pattern	LED4 pattern	Interpretation
—	One blink every two seconds	The system is powered down, and the cache contains data that has not yet been written to the drives. Restore system power as soon as possible to prevent data loss. Data preservation time is extended any time that 3.3 V auxiliary power is available, as indicated by LED 2. In the absence of auxiliary power, battery power alone preserves the data. A fully-charged battery can normally preserve data for at least two days. The battery lifetime also depends on the cache module size. For further information, refer to the controller QuickSpecs on the HP website (http://www.hp.com).
—	Double blink, then pause	The cache microcontroller is waiting for the host controller to communicate.

LED3 pattern	LED4 pattern	Interpretation
—	One blink per second	The battery pack is below the minimum charge level and is being charged. Features that require a battery (such as write cache, capacity expansion, stripe size migration, and RAID migration) are temporarily unavailable until charging is complete. The recharge process takes between 15 minutes and two hours, depending on the initial capacity of the battery.
—	Steady glow	The battery pack is fully charged, and posted write data is stored in the cache.
—	Off	The battery pack is fully charged, and there is no posted write data in the cache.
One blink per second	One blink per second	An alternating green and amber blink pattern indicates that the cache microcontroller is executing from within its boot loader and receiving new flash code from the host controller.
Steady glow	—	There is a short circuit across the battery terminals or within the battery pack. BBWC features are disabled until the battery pack is replaced. The life expectancy of a battery pack is typically more than three years.
One blink per second	—	There is an open circuit across the battery terminals or within the battery pack. BBWC features are disabled until the battery pack is replaced. The life expectancy of a battery pack is typically more than three years.

FBWC module LEDs

The FBWC module has two single-color LEDs (green and amber). The LEDs are duplicated on the reverse side of the cache module to facilitate status viewing.



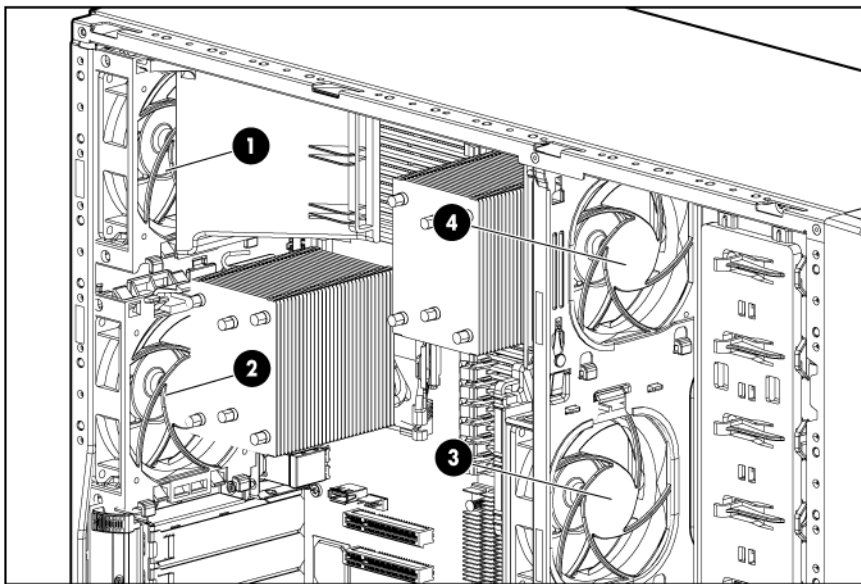
Green LED	Amber LED	Interpretation
Off	On	A backup is in progress.
Flashing (1 Hz)	On	A restore is in progress.
Flashing (1 Hz)	Off	The capacitor pack is charging.
On	Off	The capacitor pack has completed charging.

Green LED	Amber LED	Interpretation
Flashing (2 Hz) Alternating with amber LED	Flashing (2 Hz) Alternating with green LED	One of the following conditions exists: <ul style="list-style-type: none"> The charging process has timed out. The capacitor pack is not connected.
On	On	The flash code image failed to load.
Off	Off	The flash code is corrupt.

Fan locations and configurations

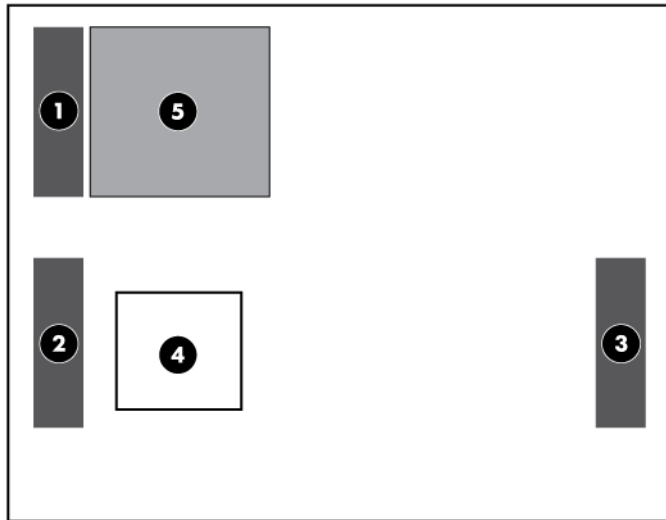
CAUTION: To maintain proper cooling, all fan bays must be populated with a fan or a fan blank.

- Fan locations



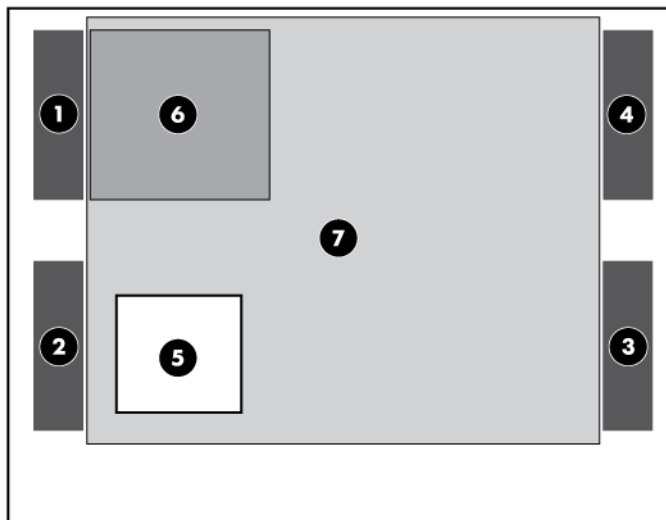
Item	Description
1	Rear fan 1
2	Rear fan 2
3	Front fan 3
4	Front fan 4

- Single-processor, standard fan configuration



Item	Description
1	Rear fan 1
2	Rear fan 2
3	Front fan 3
4	Processor 1
5	DIMM baffle

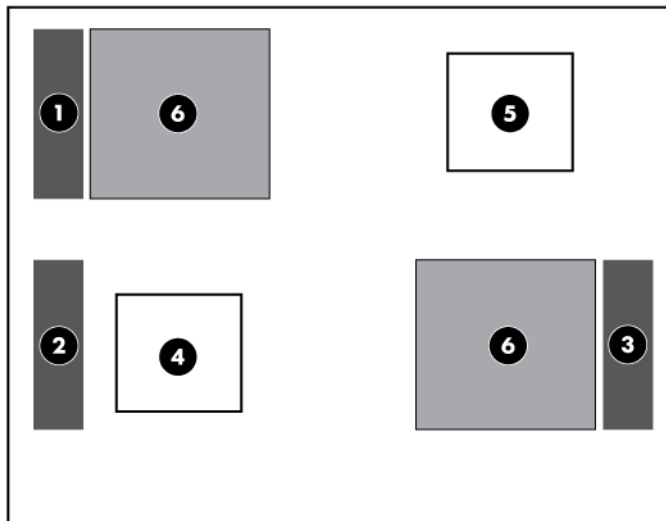
- Single-processor, redundant fan configuration



Item	Description
1	Rear fan 1
2	Rear fan 2

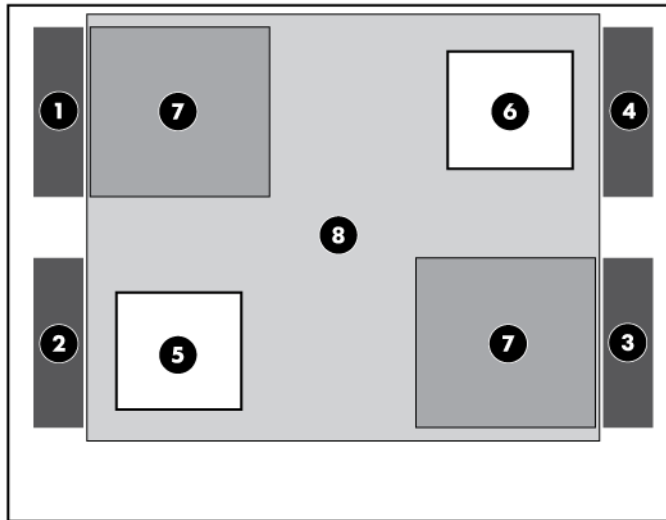
Item	Description
3	Front fan 3
4	Front fan 4
5	Processor 1
6	DIMM baffle
7	Large redundant fan air baffle

- Dual-processor, non-redundant fan configuration



Item	Description
1	Rear fan 1
2	Rear fan 2
3	Front fan 3
4	Processor 1
5	Processor 2
6	DIMM baffles

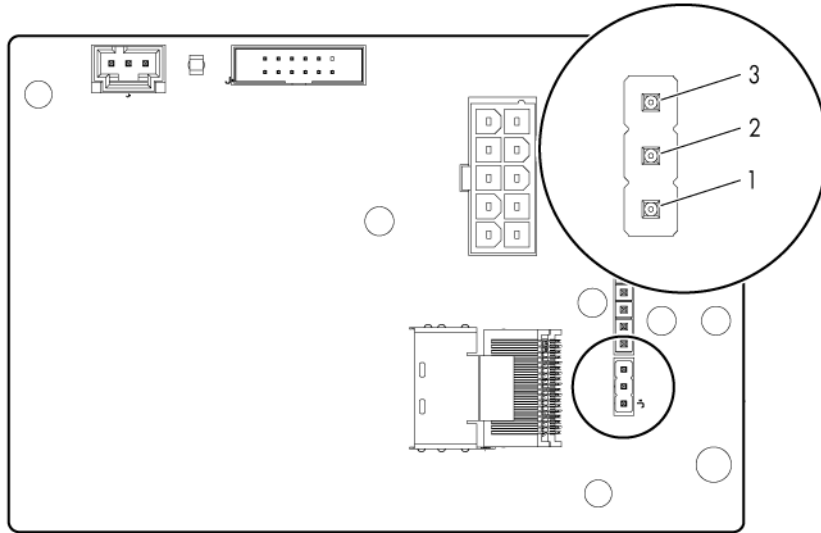
- Dual-processor, redundant fan configuration



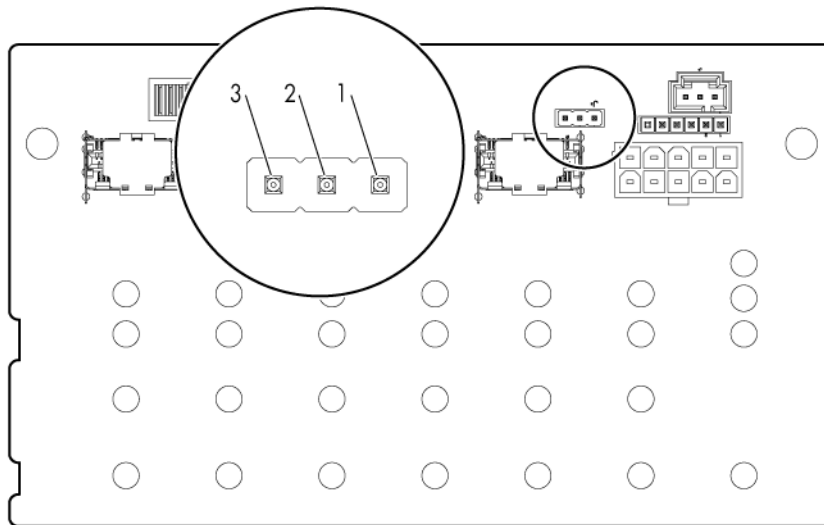
Item	Description
1	Rear fan 1
2	Rear fan 2
3	Front fan 3
4	Front fan 4
5	Processor 1
6	Processor 2
7	DIMM baffles
8	Large redundant fan air baffle

Optional hard drive cage jumper location and configuration settings

- Optional two-bay LFF backplane



- Optional eight-bay SFF backplane



Drive cage	Installation	Pin setting
1	Standard	No jumper
2	Optional	1-2*

*Optional drive cages ship with the jumper set across pins 1 and 2.

Specifications

Environmental specifications

Specification	Value
Temperature range*	
Operating	10°C to 35°C (50°F to 95°F)
Shipping	-40°C to 70°C (-40°F to 158°F)
Maximum wet bulb temperature	28°C (82.4°F)
Relative humidity (noncondensing)**	
Operating	10% to 90%
Non-operating	5% to 95%

* All temperature ratings shown are for sea level. An altitude derating of 1°C per 300 m (1.8°F per 1,000 ft) to 3048 m (10,000 ft) is applicable. No direct sunlight allowed.

** Storage maximum humidity of 95% is based on a maximum temperature of 45°C (113°F). Altitude maximum for storage corresponds to a pressure minimum of 70 kPa.

Mechanical specifications

Specification	Value
Dimension	
Height (without tower feet)	44.45 cm (17.50 in)
Height (with tower feet)	46.70 cm (18.38 in)
Depth (with tower bezel)	60.00 cm (23.60 in)
Width	22.00 cm (8.66 in)
Weight (no drives installed)	27.22 kg (60.00 lb)

Power supply specifications

Depending on installed options, the server is configured with one of the following power supplies:

- HP ProLiant 1200 W Power Supply

Specification	Value
Input requirements	
Rated input voltage	100 to 120 VAC, 200 to 240 VAC
Rated input frequency	50 Hz to 60 Hz
Rated input current	10 A at 100 VAC 4.9 A at 200 VAC

Rated input power	930 W at 100V AC input 1348 W at 200V AC input
BTUs per hour	3530 at 120V AC input 4600 at 200V to 240V AC input
Power supply output	
Rated steady-state power	800 W at 100V AC input 900 W at 120V AC input 1200 W at 200V to 240V AC input
Maximum peak power	800 W at 100V AC input 900 W at 120V AC input 1200 W at 200V to 240V AC input

- HP ProLiant 750 W Power Supply

Specification	Value
Input requirements	
Rated input voltage	100 to 120 VAC, 200 to 240 VAC
Rated input frequency	50 Hz to 60 Hz
Rated input current	8.9 A at 100 VAC 4.3 A at 200 VAC
Rated input power	857 W at 100V AC input 824 W at 200V AC input
BTUs per hour	2925 at 100V AC input 2812 at 200V AC input
Power supply output	
Rated steady-state power	750 W at 100V to 120V AC input 750 W at 200V to 240V AC input
Maximum peak power	750 W at 100V to 120V AC input 750 W at 200V to 240V AC input

- HP ProLiant 460 W Power Supply

Specification	Value
Input requirements	
Rated input voltage	100 to 120 VAC, 200 to 240 VAC
Rated input frequency	50 Hz to 60 Hz
Rated input current	5.5 A at 100 VAC 2.6 A at 200 VAC
Rated input power	526 W at 100V AC input 505 W at 200V AC input
BTUs per hour	1794 at 100V AC input 1725 at 200V AC input
Power supply output	
Rated steady-state power	460 W at 100V to 120V AC input 460 W at 200V to 240V AC input

Maximum peak power	460 W at 100V to 120V AC input 460 W at 200V to 240V AC input
--------------------	------------------------------------------------------------------

Acronyms and abbreviations

ADU

Array Diagnostics Utility

AMP

Advanced Memory Protection

FBWC

flash-backed write cache

iLO

Integrated Lights-Out

IML

Integrated Management Log

LFF

large form-factor

LV DIMM

Low voltage DIMM

NCQ

Native Command Queuing

NMI

non-maskable interrupt

PATA

parallel ATA

PCIe

peripheral component interconnect express

PCI-X

peripheral component interconnect extended

POST

Power-On Self Test

PSP

ProLiant Support Pack

RBSU

ROM-Based Setup Utility

RDIMM

Registered Dual In-line Memory Module

SAS

serial attached SCSI

SATA

serial ATA

SFF

small form-factor

SIM

Systems Insight Manager

SMP

Server Migration Pack

TPM

trusted platform module

UDIMM

Unregistered Dual In-Line Memory Module

UID

unit identification

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